



Future Directions in Computational Electromagnetics for Digital Applications

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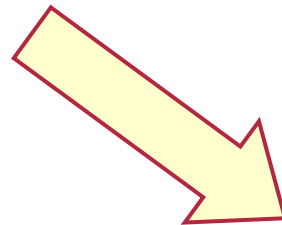
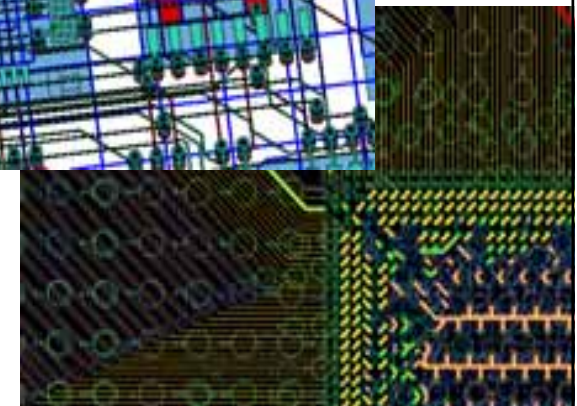
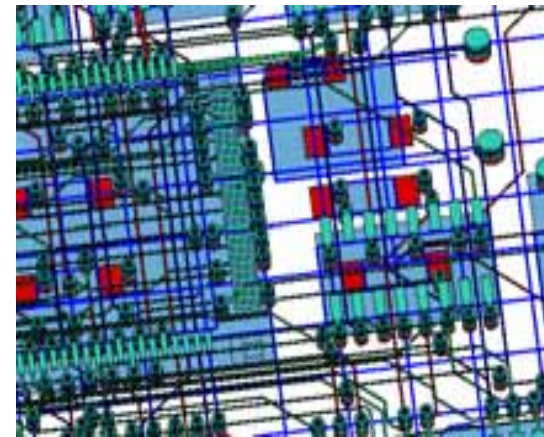
- Introduction
- State of the art
 - Three steps in solving an EM Problem
 - Finite Integration Technique as universal method
 - Wide choice of solution methods
- Future trends
 - Geometrically complex problems
 - EMC, Signal and Power integrity
 - Network Extraction, Passivity
 - Coupled problems
 - Integrated flows
- Conclusions



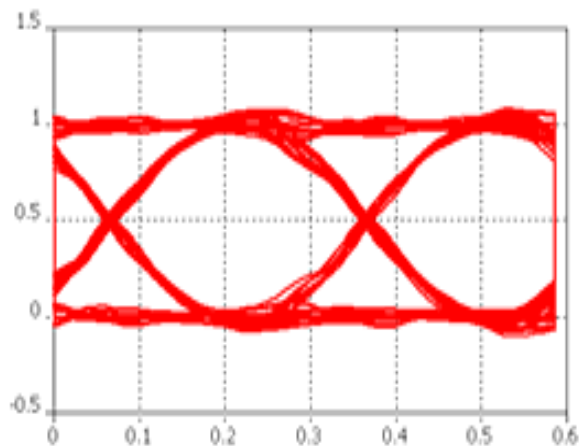
Motivation: Why 3D EM simulation?



- Growing frequencies / clock rates
- High density of components
- Increasing parasitics relevance
- Sophisticated packaging technologies
- 3D packaging



- No simple models available
- Increase in crosstalk problems
- EMI / EMC concerns
- Signal / power integrity issues
- 2 ½D solvers cannot cope with all 3D effects



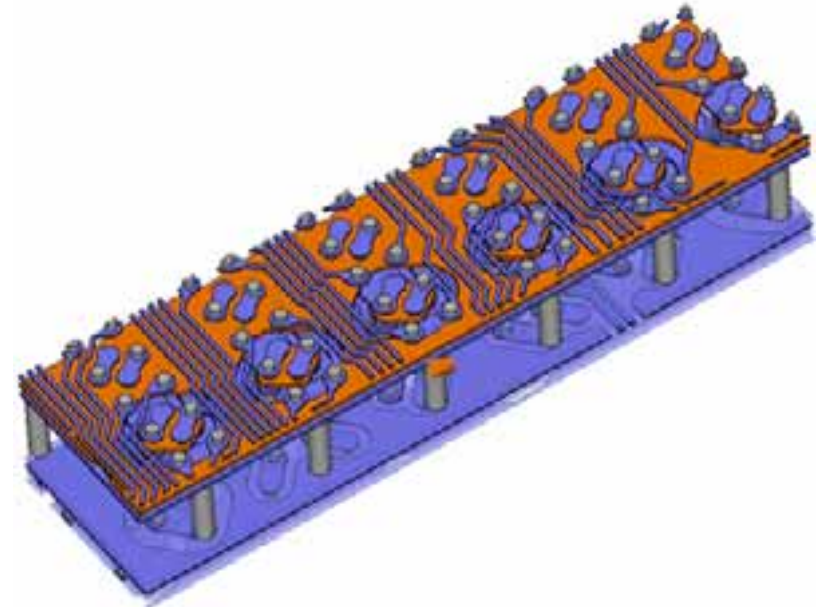


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1 Spatial Discretization of geometry

- Staircase grid
- Tetrahedral grid
- Surface mesh
- Boundary fitted meshes
-



2 Local approximation of Maxwell's Equations

- Finite Difference
- Finite Integration Technique
- Finite Element
- Finite Volume
-

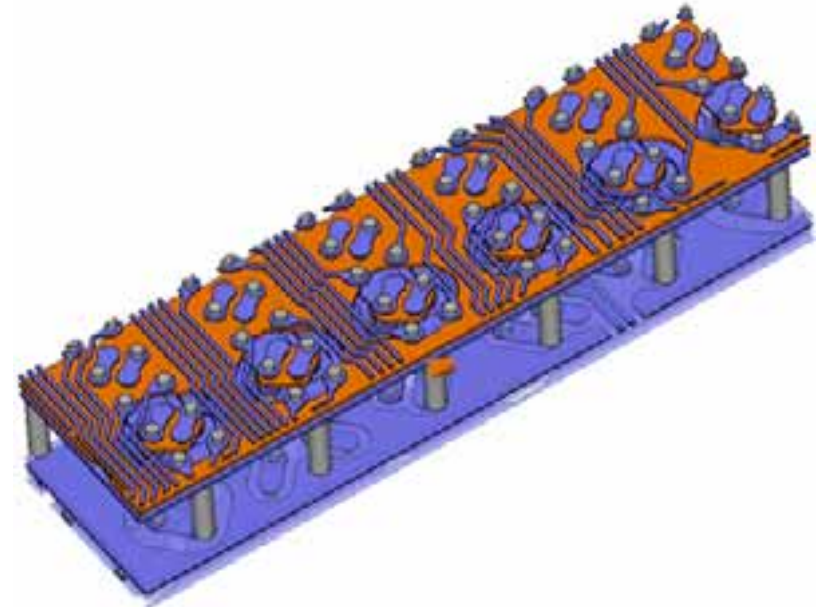
3 Solving the algebraic system

- Direct solver
- Iterative solver
- Eigenvalue solver
- Time stepping solver
-



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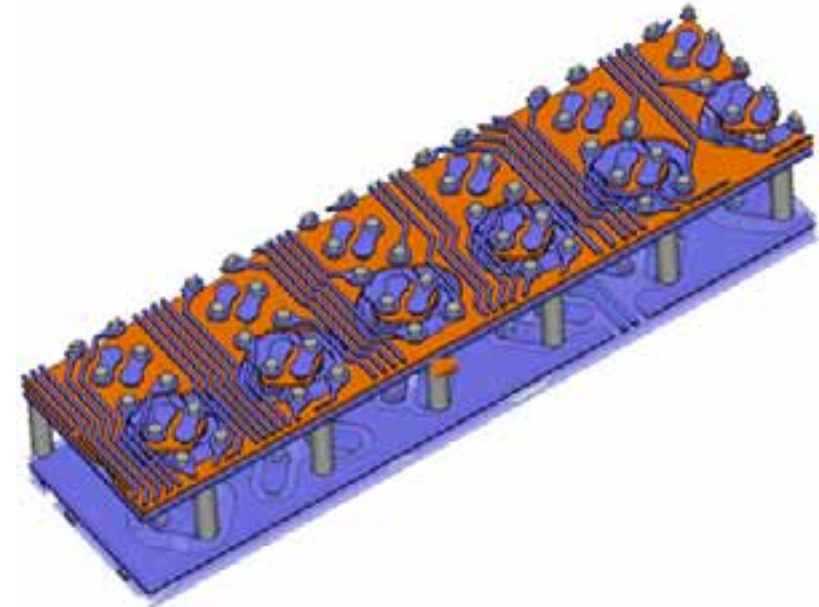


EM Solution = 3 Steps



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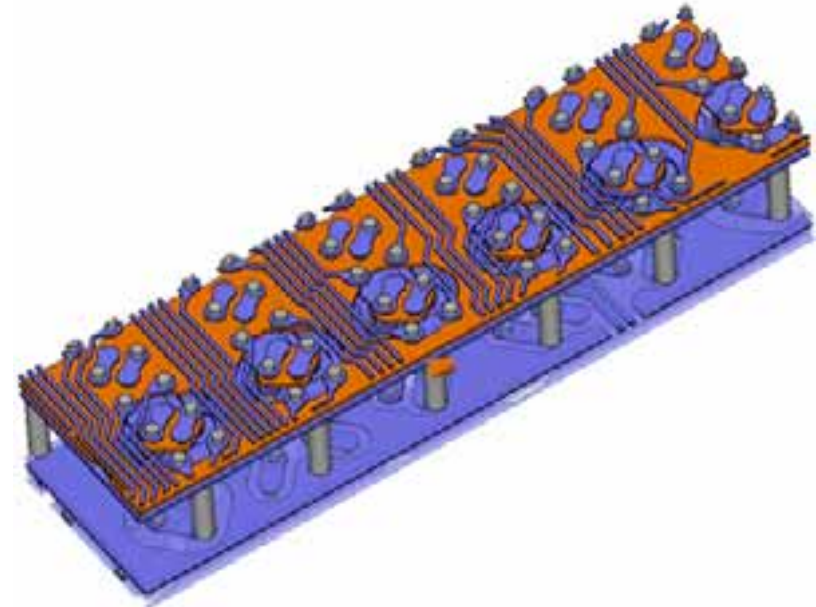
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3 Solving the algebraic system

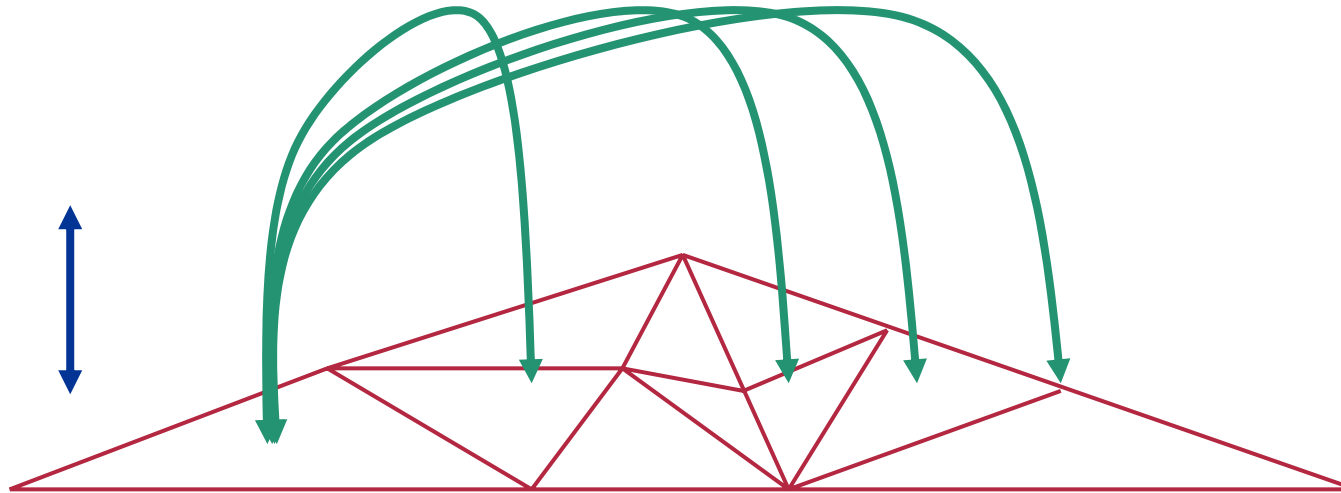
- Direct solver
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-



Surface Meshing



Each patch talks to each patch



With **D** as linear dimension

„Method of Moments“

$$N_{\text{cell}} \propto D^2 \quad ; \quad \text{Matrix rank} \propto D^2$$

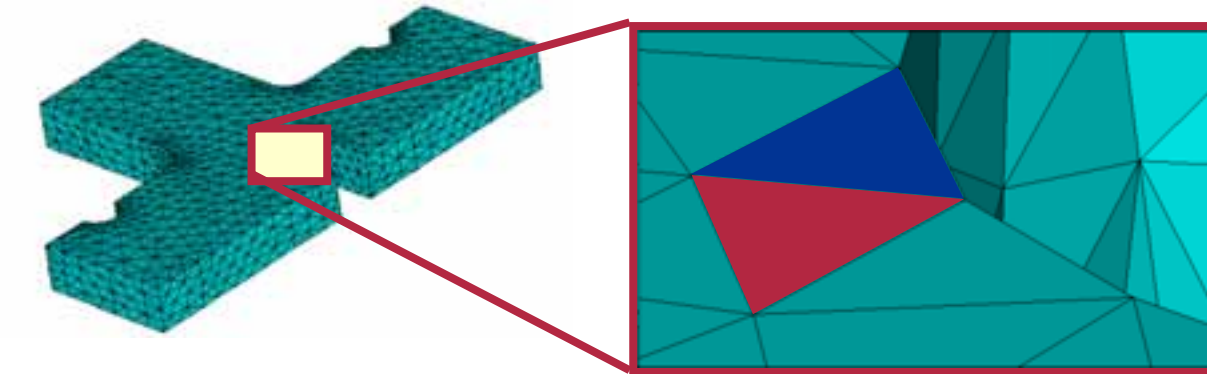
Matrix completely filled

$$\text{Number of matrix elements} \propto D^4$$

$$\text{Solvers mostly} \propto (D^2)^3 = D^6 \dots D^2 \log D^2$$

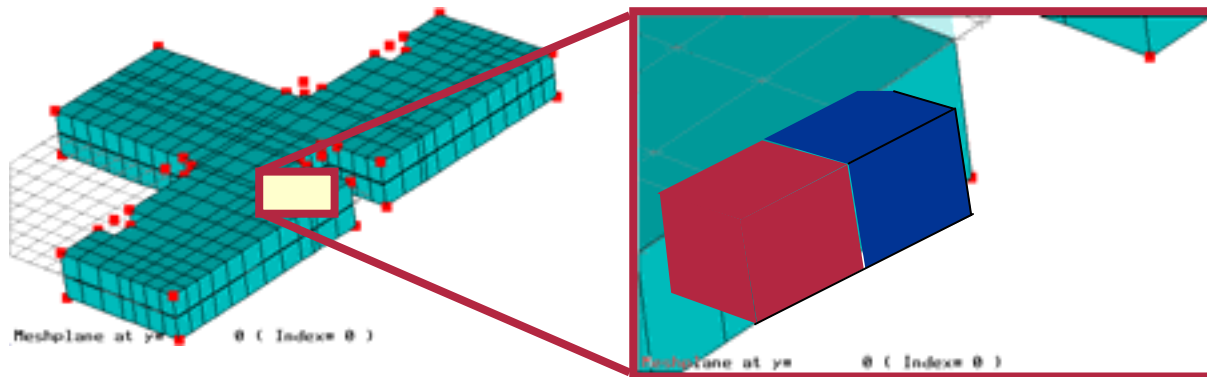
Good for linear materials

Good for Volume/Surface=Large



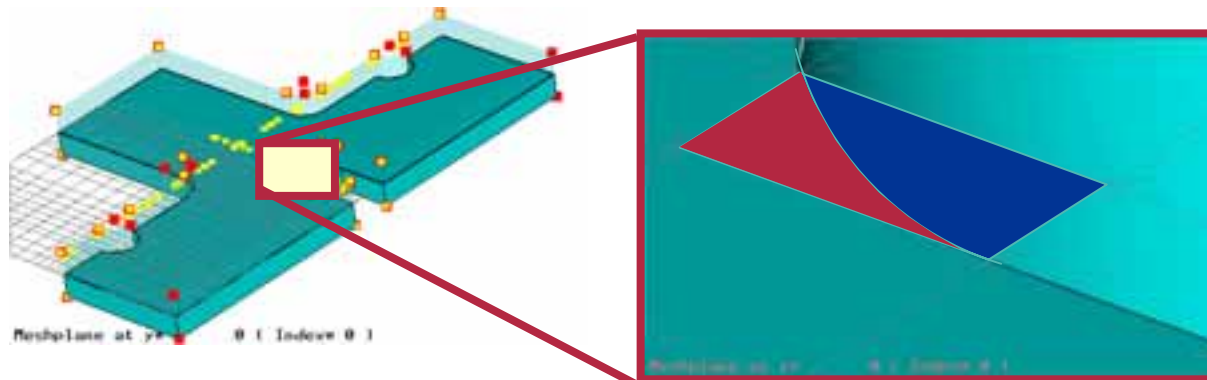
$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$



$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$

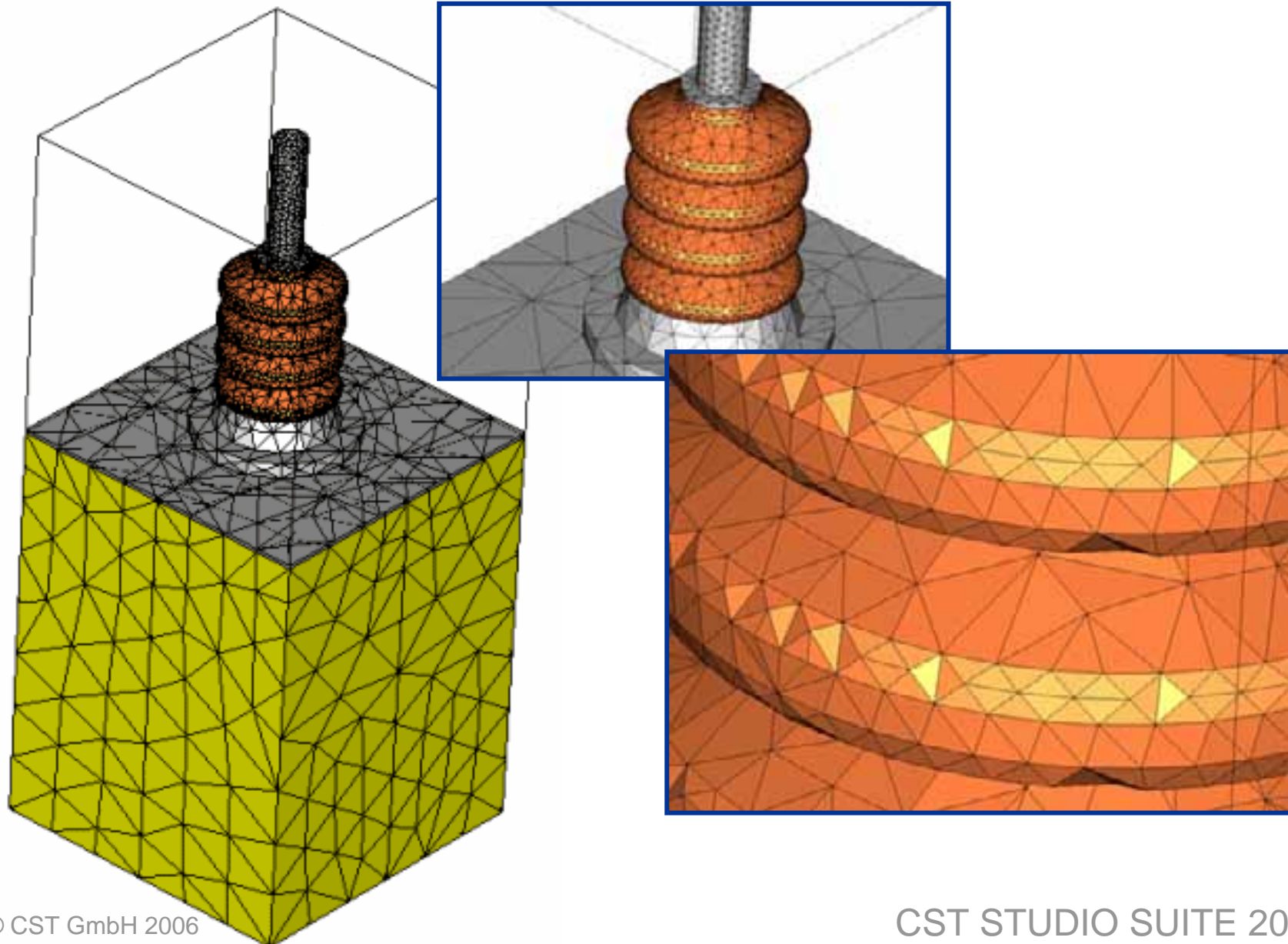


$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$

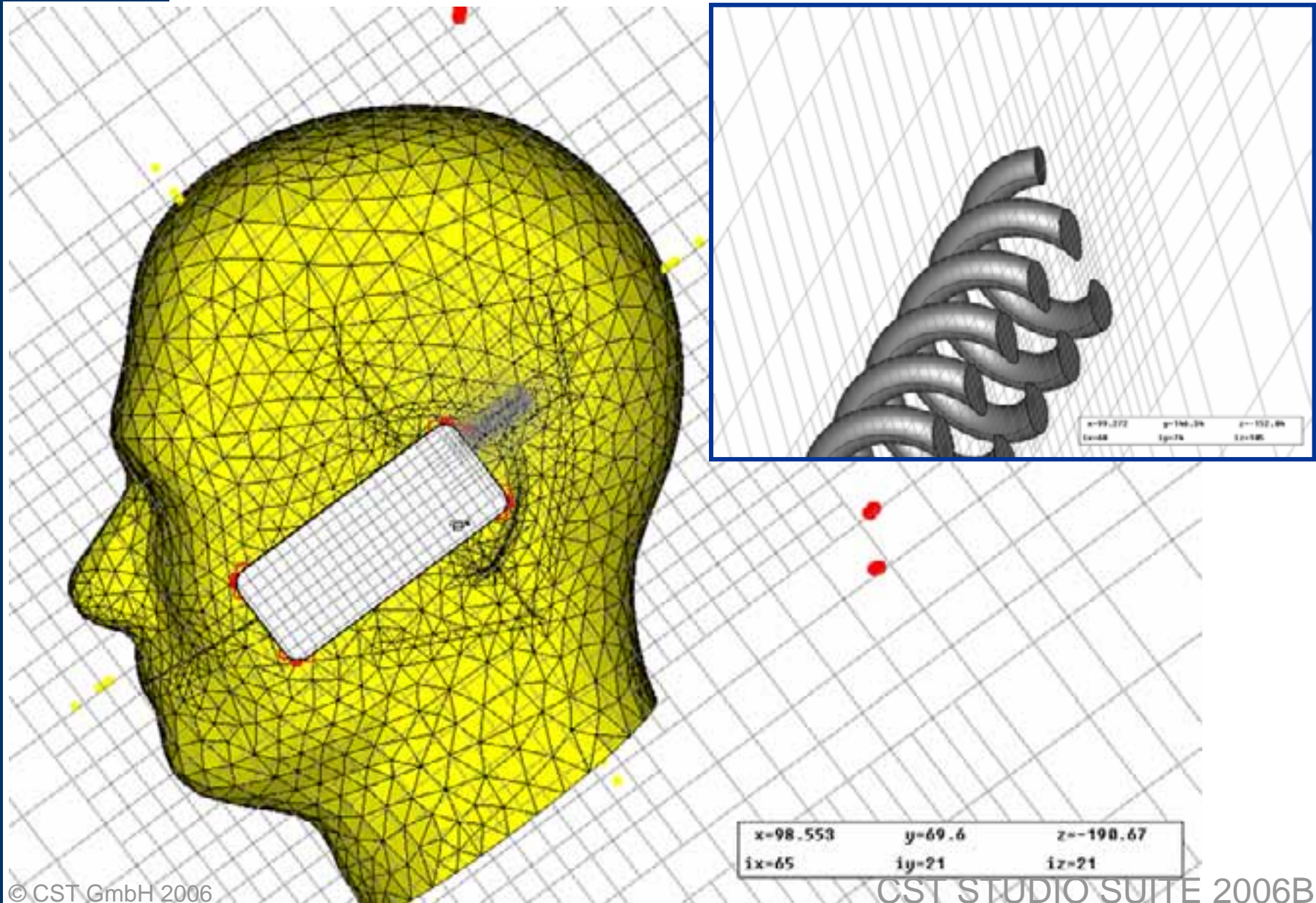


High Voltage - Bushing





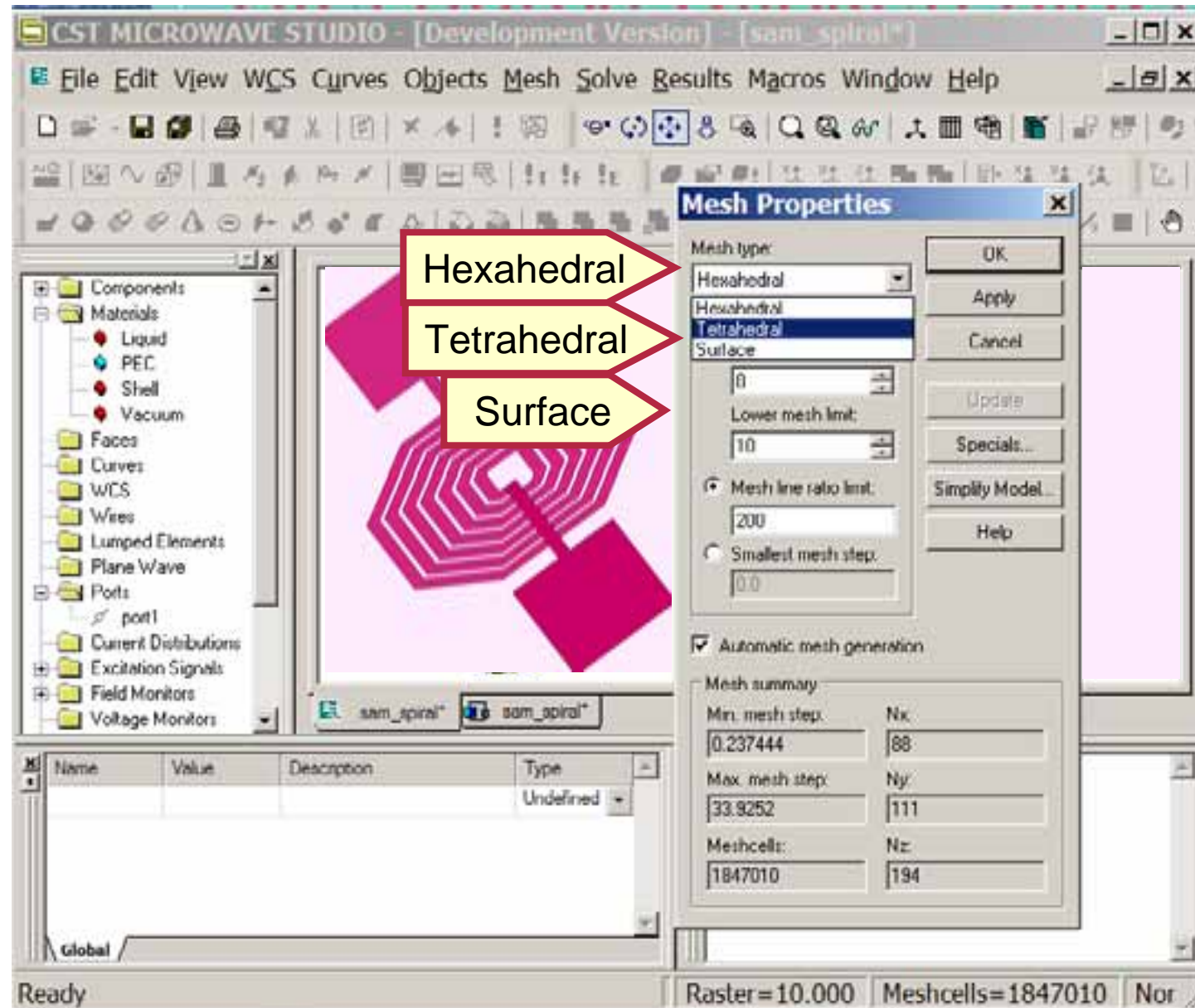
Hexahedral - Subgrids



Wide choice of mesh type



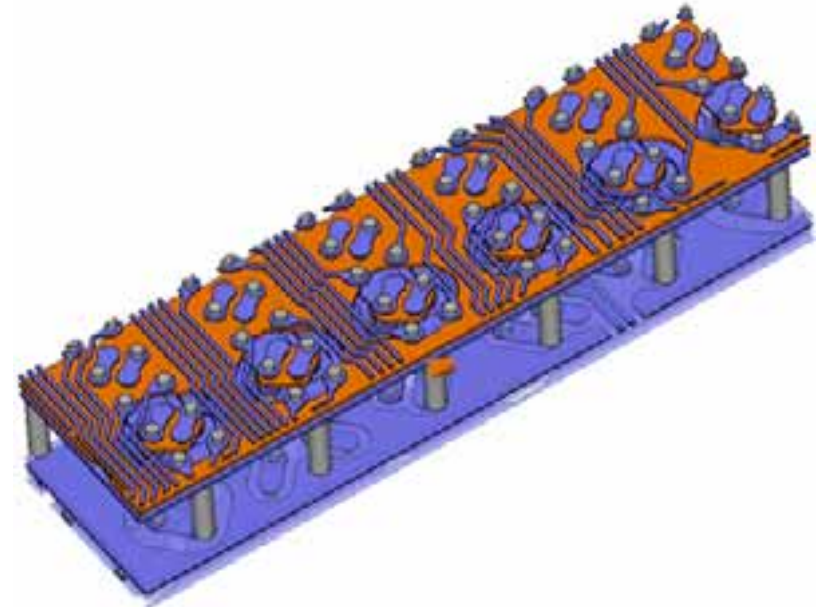
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2 Local approximation of Maxwell's Equations

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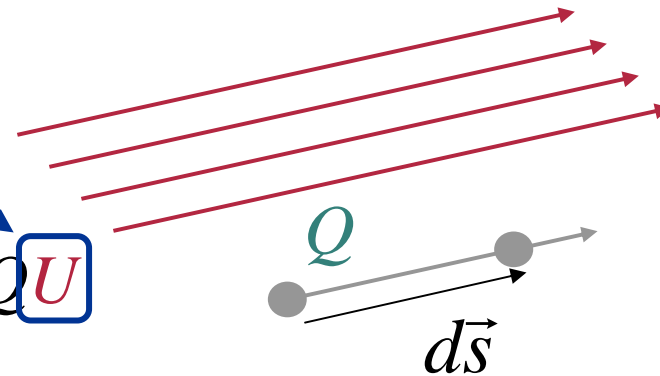
Measurable=Integral Quantities



$$\vec{F} = Q \vec{E}$$

$$\vec{E} = \vec{F} / Q$$

$$\vec{F} \cdot d\vec{s} = (Q\vec{E}) \cdot d\vec{s} = Q(\vec{E} \cdot d\vec{s}) = QU$$



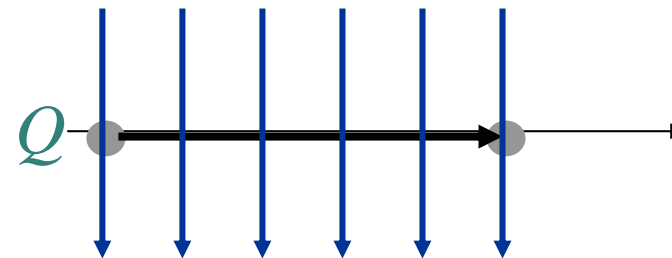
$$\vec{F} = Q \vec{v} \times \vec{B}$$

$$\Delta \vec{p} = \int \vec{F} dt$$

$$= Q \int (\vec{v} \times \vec{B}) dt = Q \vec{n} \int B v dt$$

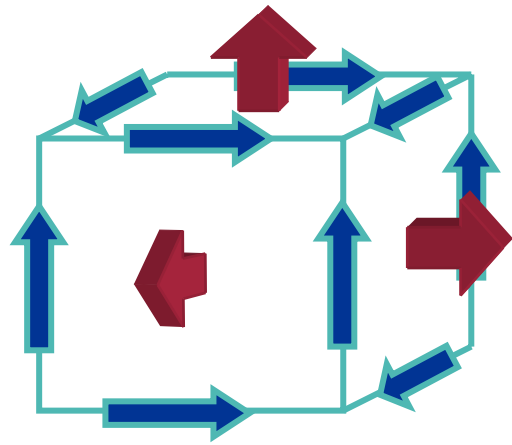
$$= Q \vec{n} \int (B ds) = Q \vec{n} (\Psi)$$

$$\vec{n} \otimes d\vec{s} = \vec{v} dt$$



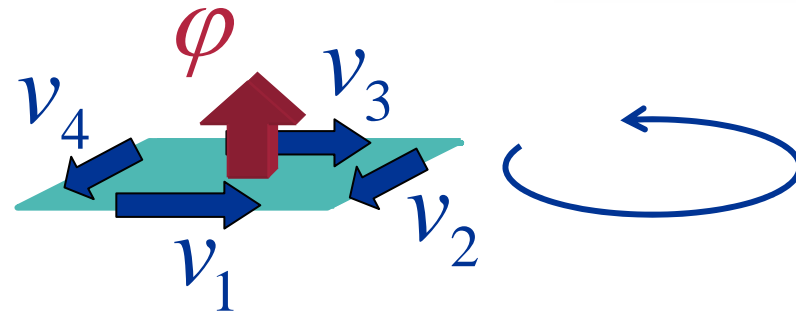


- Grid G



$$\int_L \vec{E} \cdot d\vec{s} = - \int_A \frac{\partial}{\partial t} \vec{B} \cdot d\vec{A}$$

$$v_o = - \frac{d\varphi_{S_r}}{dt}$$



$$v_1 - v_2 - v_3 + v_4 = - \frac{d}{dt} \varphi$$

$$\varphi = \int_A \vec{B} \cdot d\vec{A}$$

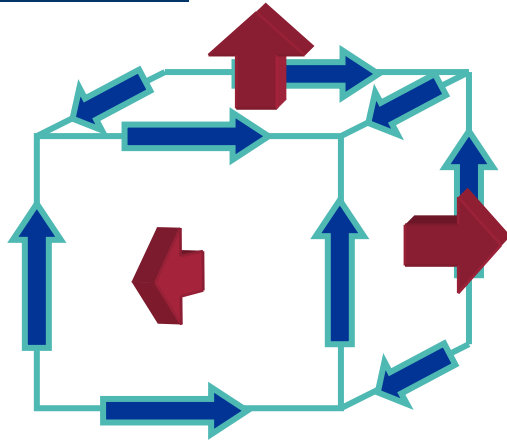
$$v = \int_L \vec{E} \cdot d\vec{s}$$

$$\sum_{i=1,4} c_i v_i = - \frac{d}{dt} \varphi$$

$$c_i = + / - 1$$



FIT - Voltage and Flux



$$\sum_{i=1,4} c_i v_i = -\frac{d}{dt} \varphi_j$$

$$\mathbf{Cv} = -\frac{d}{dt} \boldsymbol{\varphi}$$

$$\mathbf{C}\hat{\mathbf{e}} = -\frac{d}{dt} \hat{\mathbf{b}}$$

$$\mathbf{C} = \begin{pmatrix} \dots & & & & \\ & \dots & & & \\ & & -1 & +1 & \\ & & & & +1 & -1 \\ & & & & & \dots \\ & & & & & & \dots \end{pmatrix}$$

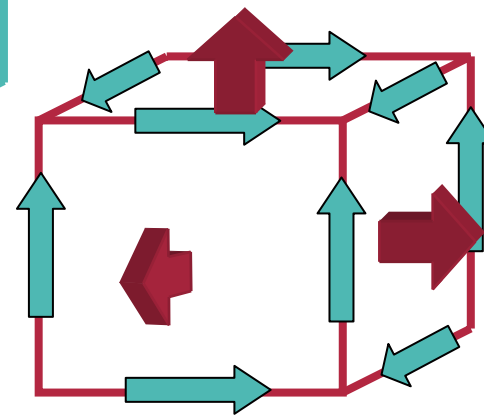
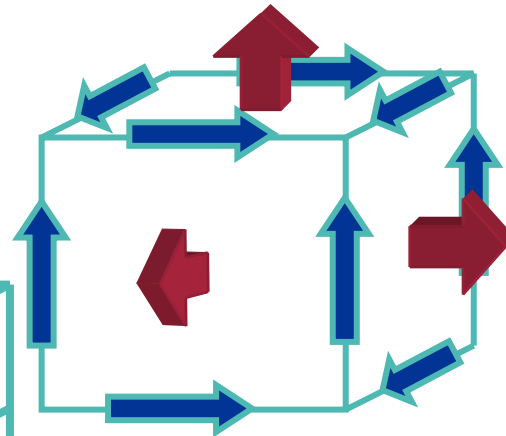
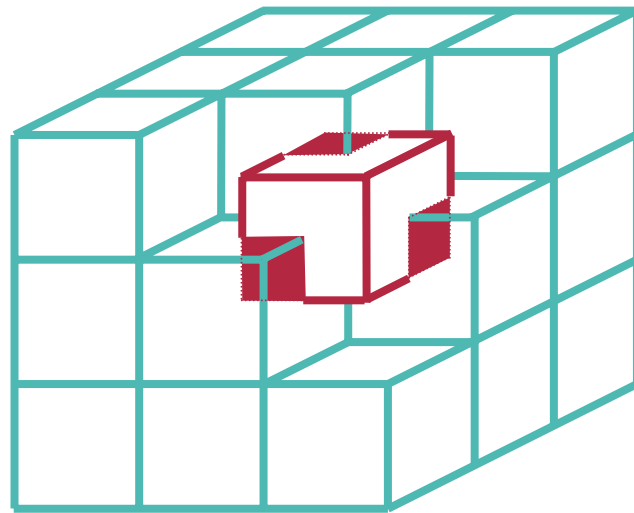
$$\mathbf{v} = \begin{pmatrix} v_1 \\ v_2 \\ \dots \\ v_N \end{pmatrix}$$

$$\boldsymbol{\varphi} = \begin{pmatrix} \varphi_1 \\ \varphi_2 \\ \dots \\ \varphi_N \end{pmatrix}$$



Grid \mathbf{G} and $\tilde{\mathbf{G}}$:

$$\mathbf{C}\hat{\mathbf{e}} = -\frac{d}{dt}\hat{\mathbf{b}}$$



$$\hat{b} = \int_A \vec{B} \cdot d\vec{A}$$

$$\hat{e} = \int_L \vec{E} \cdot d\vec{s}$$

$$\hat{d} = \int_A \vec{D} \cdot d\vec{A}$$

$$\hat{h} = \int_L \vec{H} \cdot d\vec{s}$$

„Surface charge“

„Magnetic voltage“



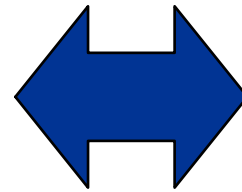
Almost Complete Discrete Form of Maxwell's Equations

$$\int_{\partial A} \vec{E} \cdot d\vec{s} = -\frac{\partial}{\partial t} \iint_A \vec{B} \cdot d\vec{A}$$

$$\int_{\partial A} \vec{H} \cdot d\vec{s} = \iint_A \left(\frac{\partial \vec{D}}{\partial t} + \vec{J} \right) \cdot d\vec{A}$$

$$\oiint_{\partial V} \vec{B} \cdot d\vec{A} = 0$$

$$\oiint_{\partial V} \vec{D} \cdot d\vec{A} = \iiint_V \rho \, dV$$



Developed
since

1975

$$\mathbf{C}\hat{\mathbf{e}} = -\hat{\dot{\mathbf{b}}}$$

$$\tilde{\mathbf{C}}\hat{\mathbf{h}} = \hat{\dot{\mathbf{d}}} + \hat{\mathbf{j}}$$

$$\tilde{\mathbf{S}}\hat{\mathbf{d}} = \mathbf{q}$$

$$\mathbf{S}\hat{\mathbf{b}} = \mathbf{0}$$

EXACT!!

continuous

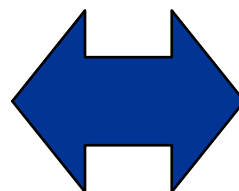
discrete



$$\vec{D} = \epsilon \cdot \vec{E} + \vec{P}$$

$$\vec{B} = \mu \cdot \vec{H} + \vec{M}$$

$$\vec{J} = \kappa \cdot \vec{E}$$



?



$$\mathbf{C}\hat{\mathbf{e}} = -\dot{\hat{\mathbf{b}}}$$

$$\tilde{\mathbf{C}}\hat{\mathbf{h}} = \dot{\hat{\mathbf{d}}} + \hat{\mathbf{j}}$$

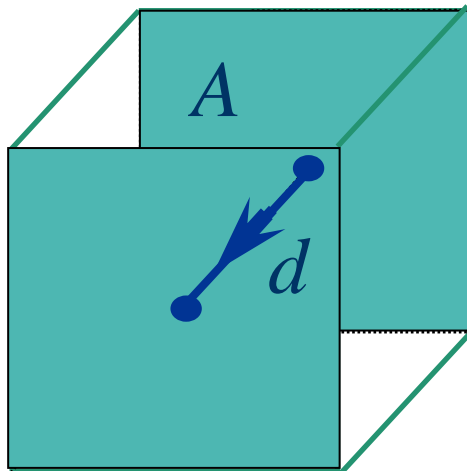
$$\tilde{\mathbf{S}}\dot{\hat{\mathbf{d}}} = \mathbf{q}$$

$$\mathbf{S}\dot{\hat{\mathbf{b}}} = \mathbf{0}$$

+

Material relations $\hat{\hat{\mathbf{d}}} - \hat{\mathbf{e}}, \hat{\hat{\mathbf{b}}} - \hat{\mathbf{h}}$

*Equivalent of branch
constitutive equations*



$$\hat{\mathbf{e}} \approx \vec{\mathbf{E}} \cdot d\vec{\mathbf{s}}$$

$$\hat{\hat{\mathbf{d}}} = \mathbf{M}_\varepsilon \hat{\mathbf{e}} \quad \mathbf{M}_\varepsilon: \frac{\varepsilon A}{d} \quad \text{Capacitance}$$

Similarly:

$$\hat{\hat{\mathbf{b}}} = \mathbf{M}_v^{-1} \hat{\mathbf{h}} \quad \mathbf{M}_v^{-1}: \quad \text{Inductance}$$



Maxwell's Grid Equations

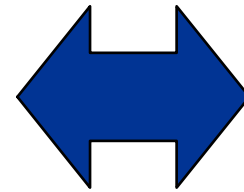


$$\int_{\partial A} \vec{E} \cdot d\vec{s} = -\frac{\partial}{\partial t} \iint_A \vec{B} \cdot d\vec{A}$$

$$\int_{\partial A} \vec{H} \cdot d\vec{s} = \iint_A \left(\frac{\partial \vec{D}}{\partial t} + \vec{J} \right) \cdot d\vec{A}$$

$$\oiint_{\partial V} \vec{B} \cdot d\vec{A} = 0$$

$$\oiint_{\partial V} \vec{D} \cdot d\vec{A} = \iiint_V \rho \, dV$$



Developed

$$\mathbf{C}\hat{\mathbf{e}} = -\dot{\hat{\mathbf{b}}}$$

$$\tilde{\mathbf{C}}\hat{\mathbf{h}} = \dot{\hat{\mathbf{d}}} + \hat{\mathbf{j}}$$

$$\tilde{\mathbf{S}}\hat{\mathbf{d}} = \mathbf{q}$$

EXACT!!

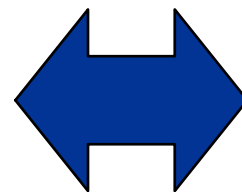
Choice of FD/FE/FI/FV....

1975

$$\vec{D} = \epsilon \cdot \vec{E} + \vec{P}$$

$$\vec{B} = \mu \cdot \vec{H} + \vec{M}$$

$$\vec{J} = \kappa \cdot \vec{E}$$



$$\hat{\mathbf{d}} = \mathbf{M}_\epsilon \hat{\mathbf{e}} + \hat{\mathbf{p}}$$

$$\hat{\mathbf{b}} = \mathbf{M}_\mu^{-1} \hat{\mathbf{h}} + \hat{\mathbf{m}}$$

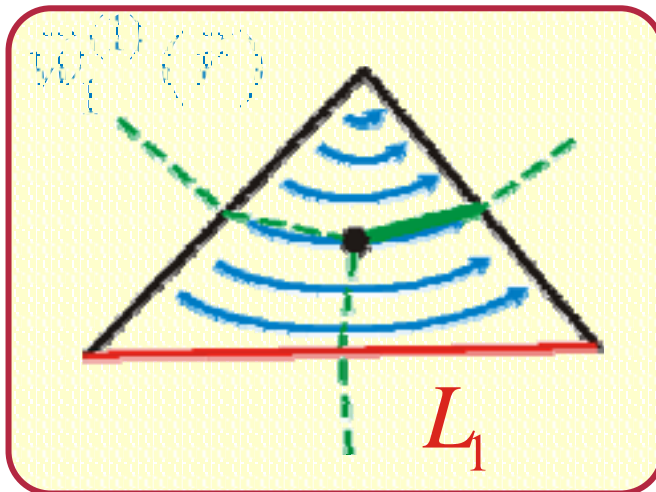
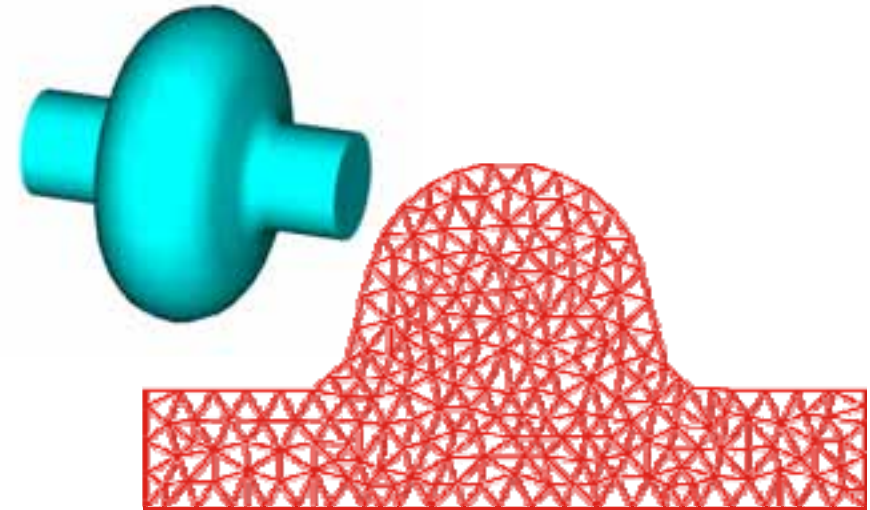
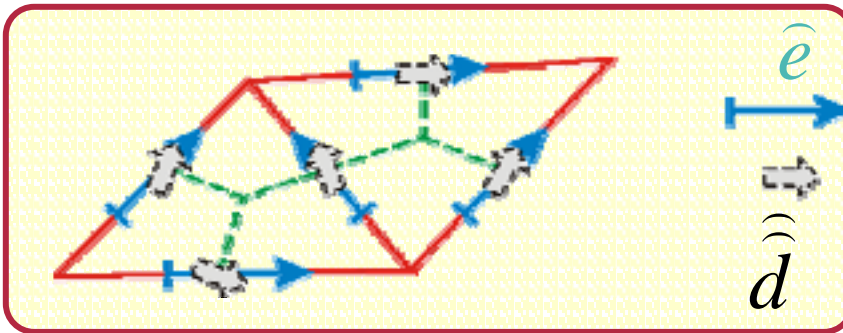
$$\hat{\mathbf{j}} = \mathbf{M}_\sigma \hat{\mathbf{e}}$$



FIT on Triangular Grids

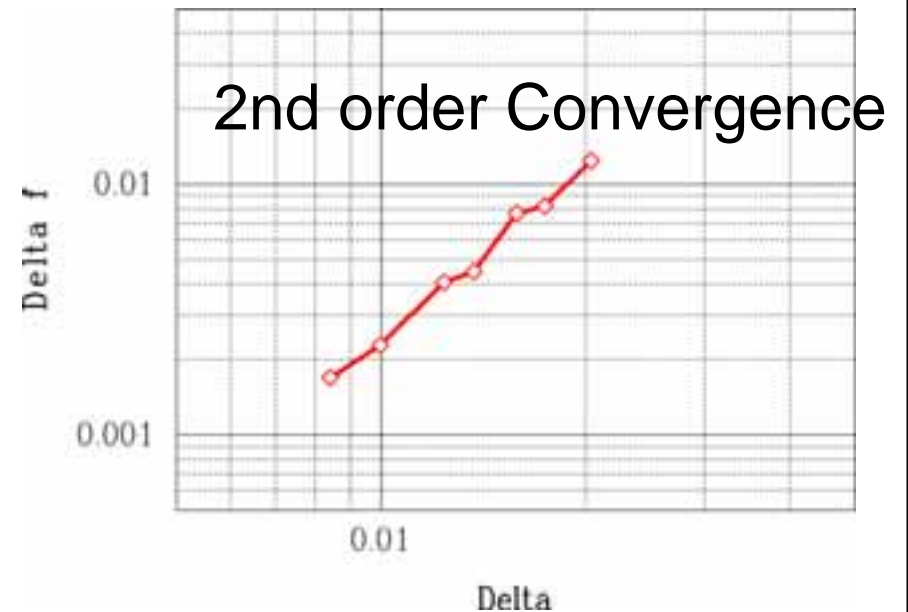


Allocation of integral components
van Rienen **1983**



Discrete Material Relation
based on Whitney elements

R. Schuhmann **2001**





Circuit mesh analysis

$$\frac{\partial}{\partial t} = 0$$

Field analysis

Circuit equations

$$\mathbf{C}\mathbf{v} = 0$$

$$\mathbf{C}^T \mathbf{i}_m = \mathbf{i}$$

$$\mathbf{v} = \mathbf{R}\mathbf{i} + \mathbf{v}_s$$

$$\mathbf{C}\mathbf{R}\mathbf{C}^T \mathbf{i}_m = -\mathbf{C}\mathbf{v}_s$$

Field equations

$$\mathbf{C}\hat{\mathbf{e}} = 0$$

$$\mathbf{C}^T \hat{\mathbf{h}} = \hat{\mathbf{j}}$$

$$\hat{\mathbf{e}} = \mathbf{M}_\rho \hat{\mathbf{j}} + \hat{\mathbf{e}}_s$$

$$\mathbf{C}\mathbf{M}_\rho \mathbf{C}^T \hat{\mathbf{h}} = -\mathbf{C}\hat{\mathbf{e}}_s$$

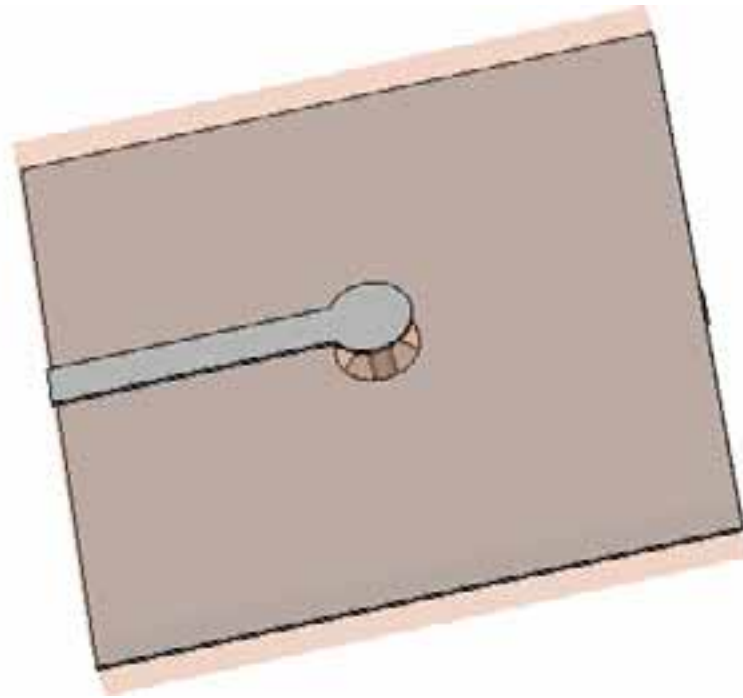
C :
incidence matrix of edges to the
independent meshes of the network



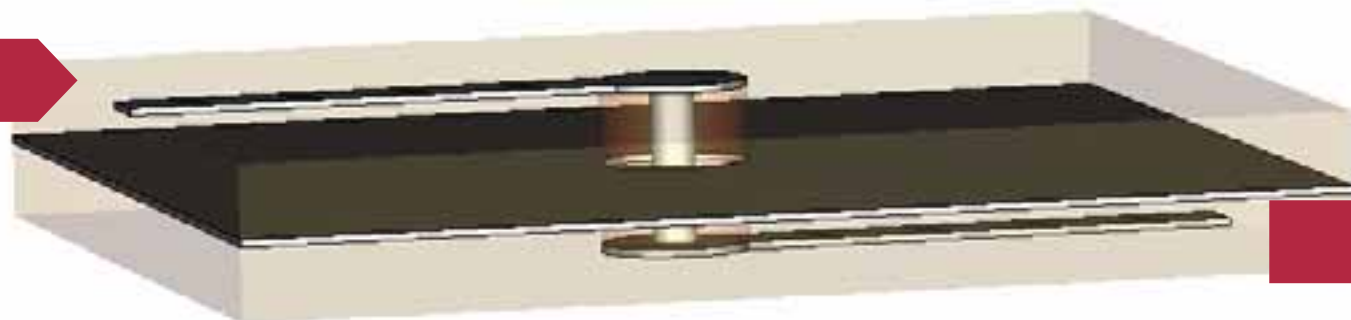
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Simple Via Structure



Input port

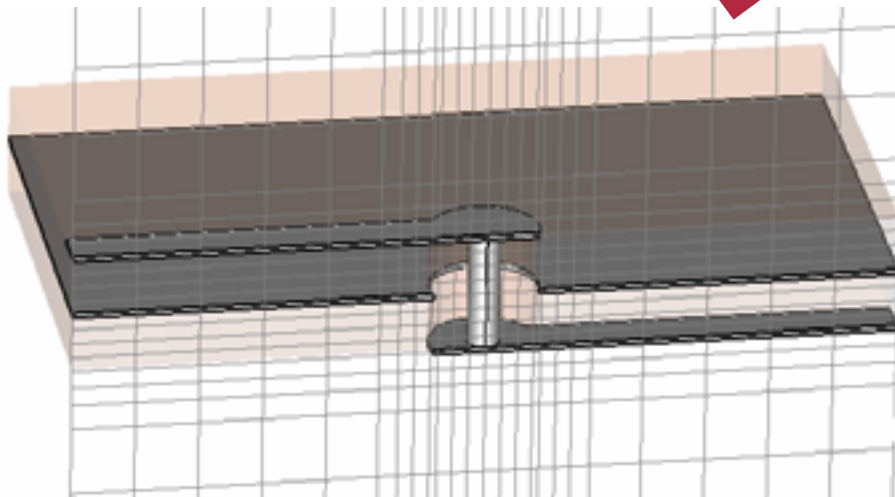


Output port

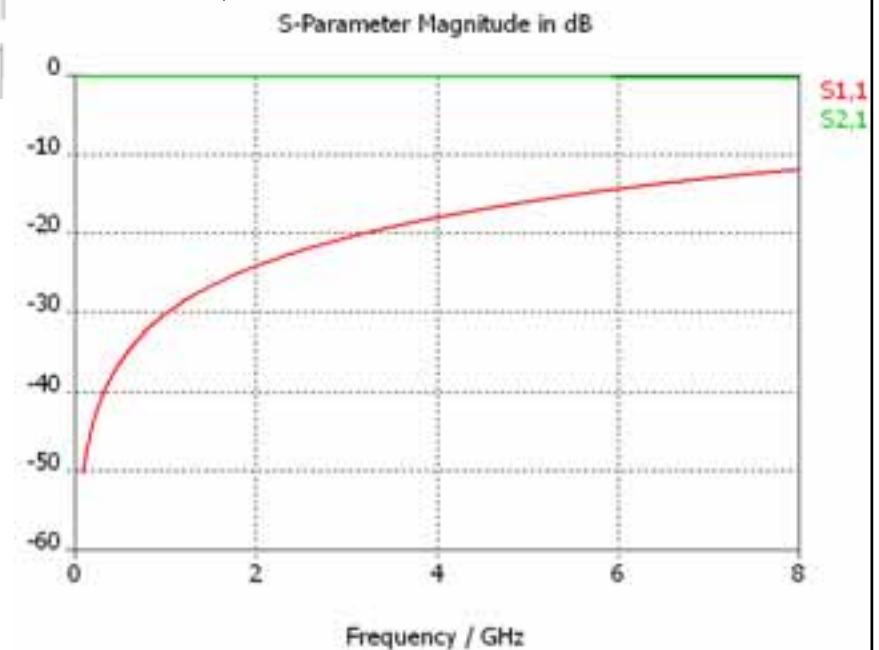


- HEX Transient Solution
- HEX Frequency Domain
- TET Frequency Domain
- Model Order Reduction

- **HEX Transient Solution** $\tilde{\mathbf{C}}\mathbf{M}_v\mathbf{C}\hat{\mathbf{e}} + \mathbf{M}_\kappa \frac{d}{dt} \hat{\mathbf{e}} + \mathbf{M}_\varepsilon \frac{d^2}{dt^2} \hat{\mathbf{e}} = -\frac{d}{dt} \hat{\mathbf{j}}_s$



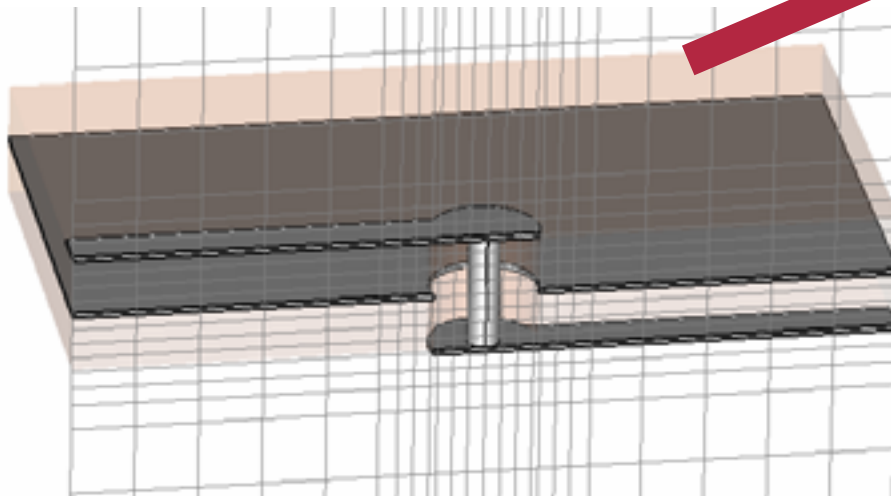
FFT(Output) / FFT(Input)



- HEX Frequency Domain
- TET Frequency Domain
- Model Order Reduction

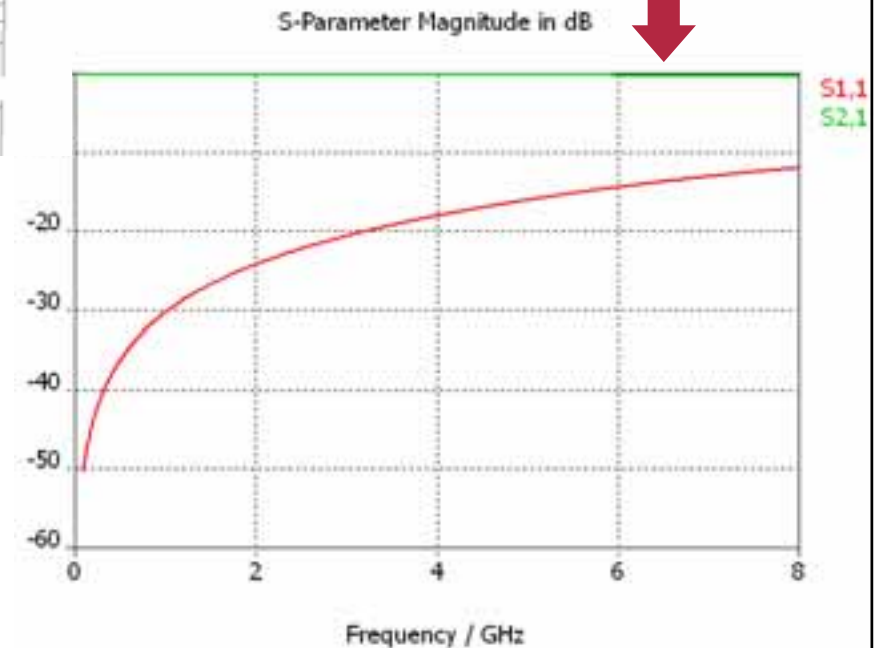
- HEX Transient Solution
- **HEX Frequency Domain**

$$(\tilde{\mathbf{C}}\mathbf{M}_v\mathbf{C} + i\omega\mathbf{M}_\kappa - \omega^2\mathbf{M}_\varepsilon)\hat{\mathbf{e}} = -i\omega\hat{\mathbf{j}}_s$$

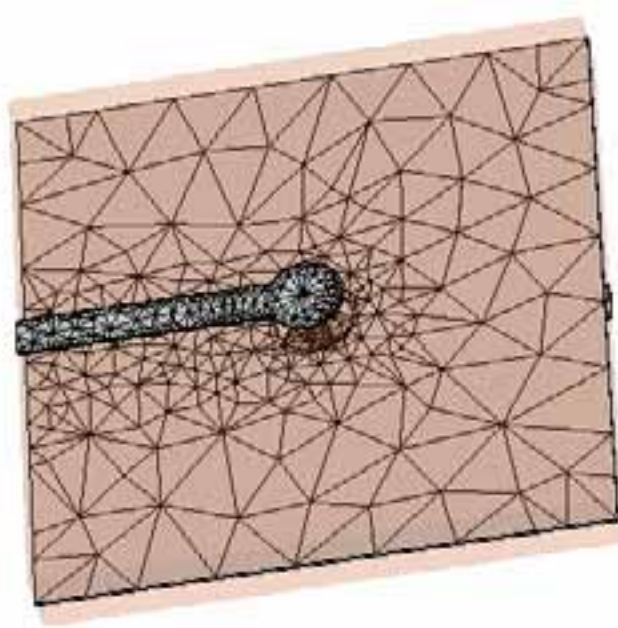


$$\mathbf{A}\hat{\mathbf{e}} = \mathbf{r}$$

- TET Frequency Domain
- Model Order Reduction

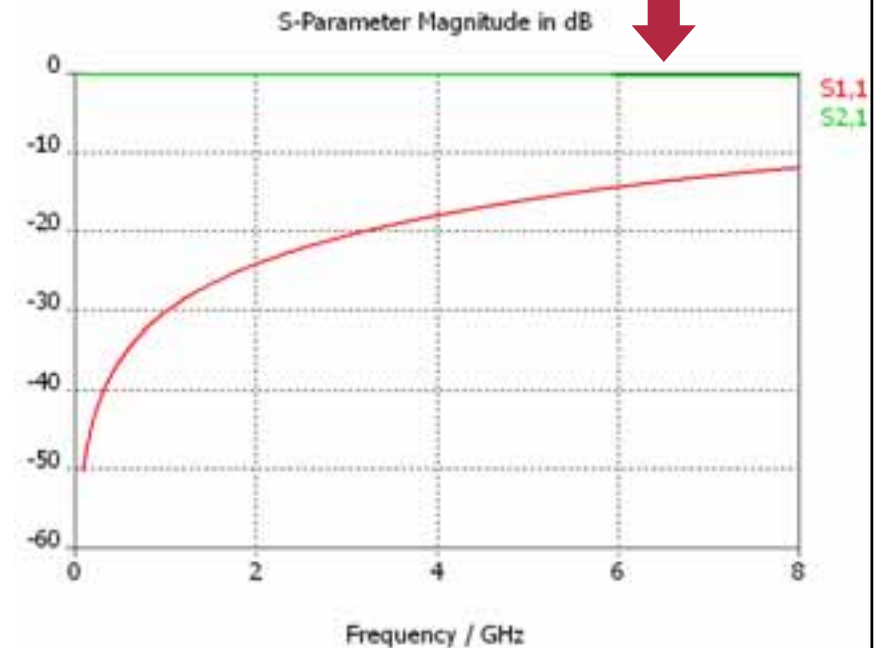


- HEX Transient Solution
- HEX Frequency Domain
- **TET Frequency Domain**



$$(\tilde{\mathbf{C}}\mathbf{M}_v\mathbf{C} + i\omega\mathbf{M}_\kappa - \omega^2\mathbf{M}_\varepsilon)\hat{\mathbf{e}} = -i\omega\hat{\mathbf{j}}_s$$

$$\mathbf{A}\hat{\mathbf{e}} = \mathbf{r}$$



- Model Order Reduction



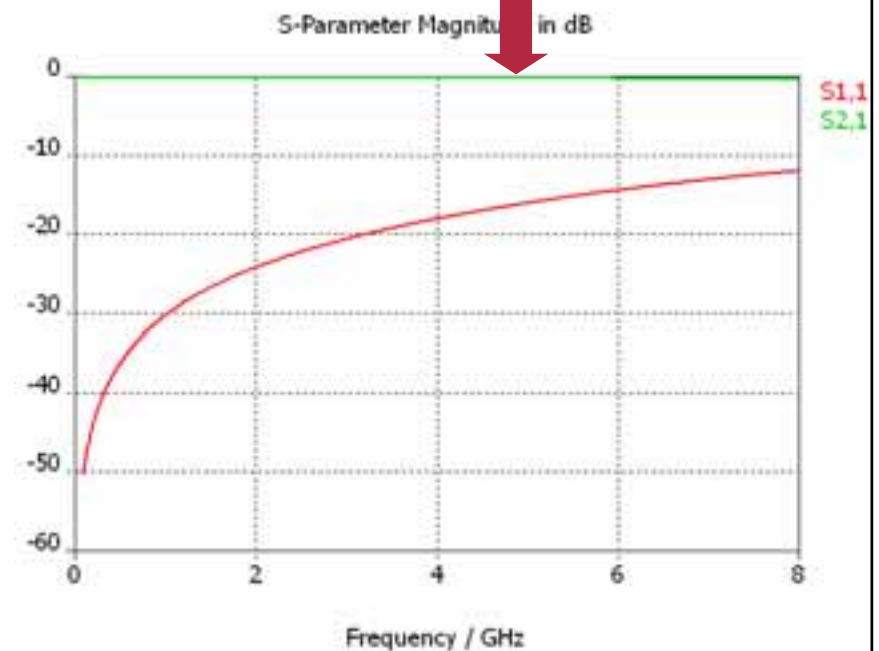
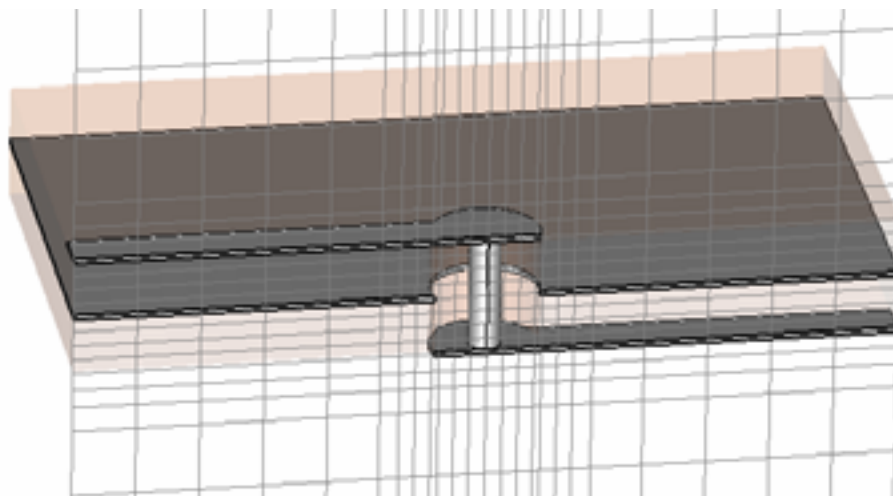
- HEX Transient Solution
- HEX Frequency Domain
- TET Frequency Domain
- **Model Order Reduction**

$$(\tilde{\mathbf{C}}\mathbf{M}_v\mathbf{C} + i\omega\mathbf{M}_\kappa - \omega^2\mathbf{M}_\varepsilon)\hat{\mathbf{e}} = -i\omega\hat{\mathbf{j}}_s$$

$$\mathbf{A}_{N \times N}\hat{\mathbf{e}} = \mathbf{r}$$

MOR

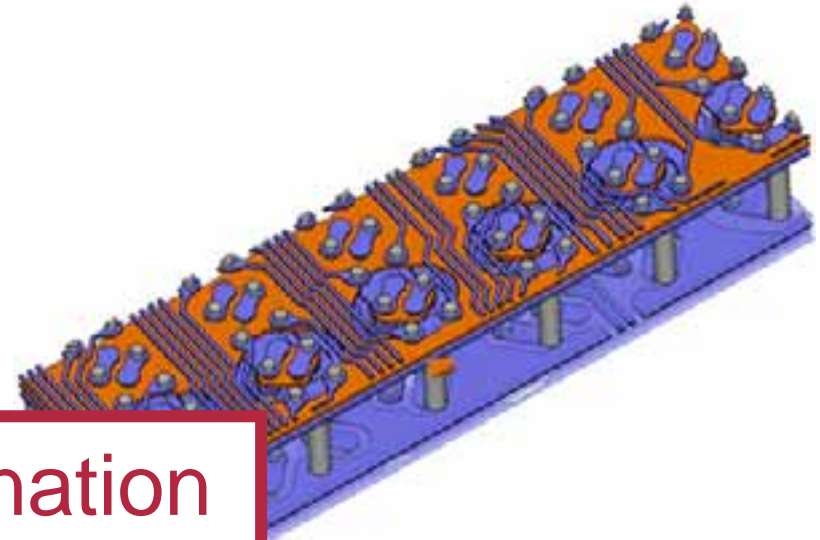
$$\mathbf{A}_{n \times n}\hat{\mathbf{e}} = \mathbf{r}$$





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- Staircase grid
- Tetrahedral grid
- Surface mesh
- Boundary fitting
-



Which combination is the best ?

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Solving the algebraic system

- Direct solver
- Iterative solver
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- Time stepping solver
-



Selection of the “best” Algorithm



$$G = \frac{Q}{\$}$$

Required accuracy

Reliability

Robustness

Absolute Calc. Time

....

CPU

Memory

Manpower

....



Example of User Choice



Type of solver

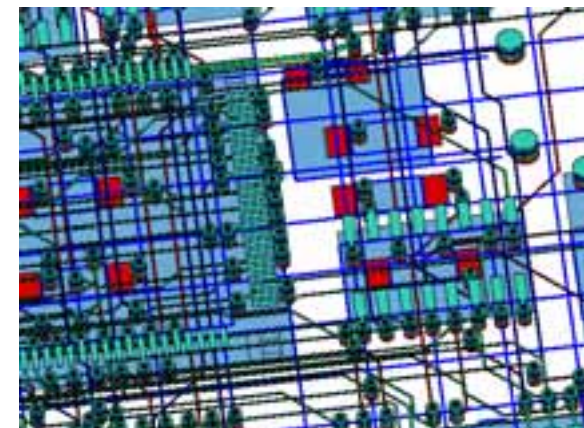
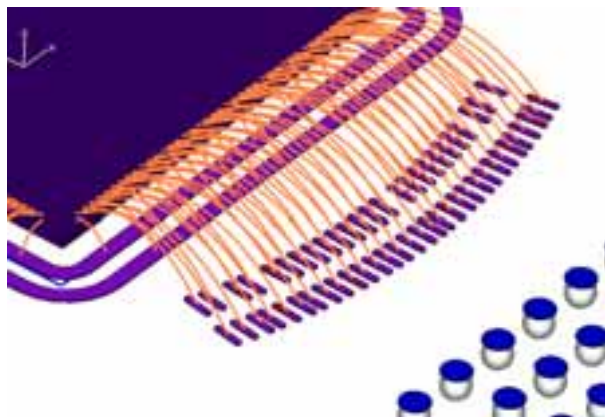
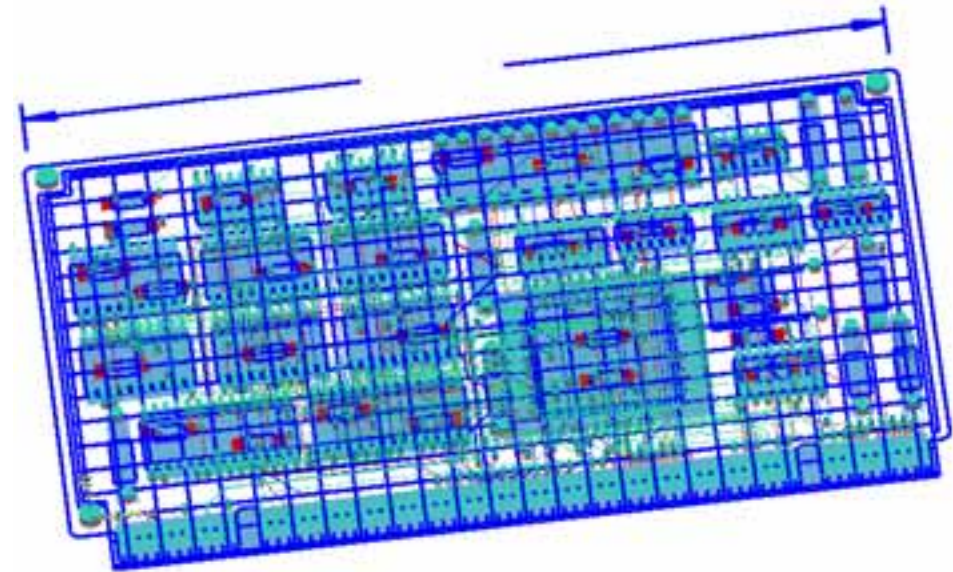
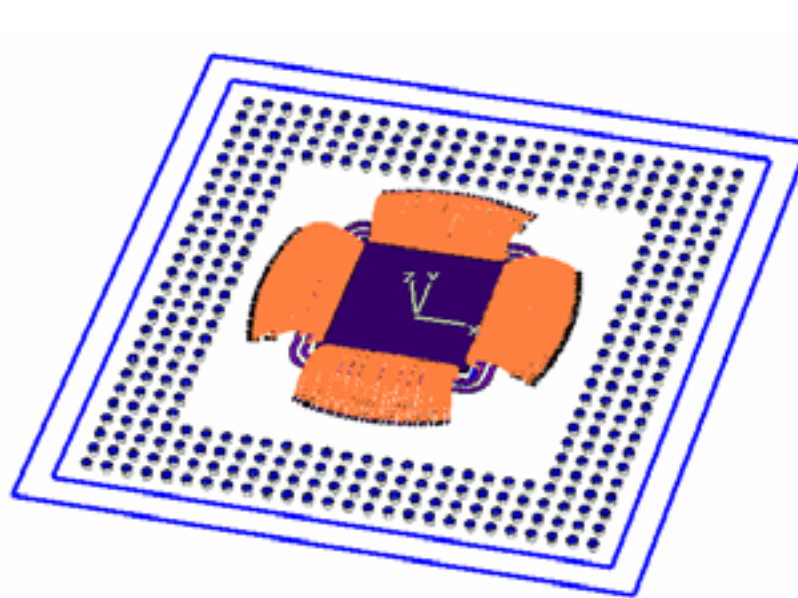
Type of mesh



- Introduction
- State of the art
 - Three steps in solving an EM Problem
 - Finite Integration Technique as universal method
 - Wide choice of solution methods
- **Future trends**
 - **Geometrically complex problems**
 - EMC, Signal and Power integrity
 - Network Extraction, Passivity
 - Coupled problems
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- Conclusions



Structures get more complex

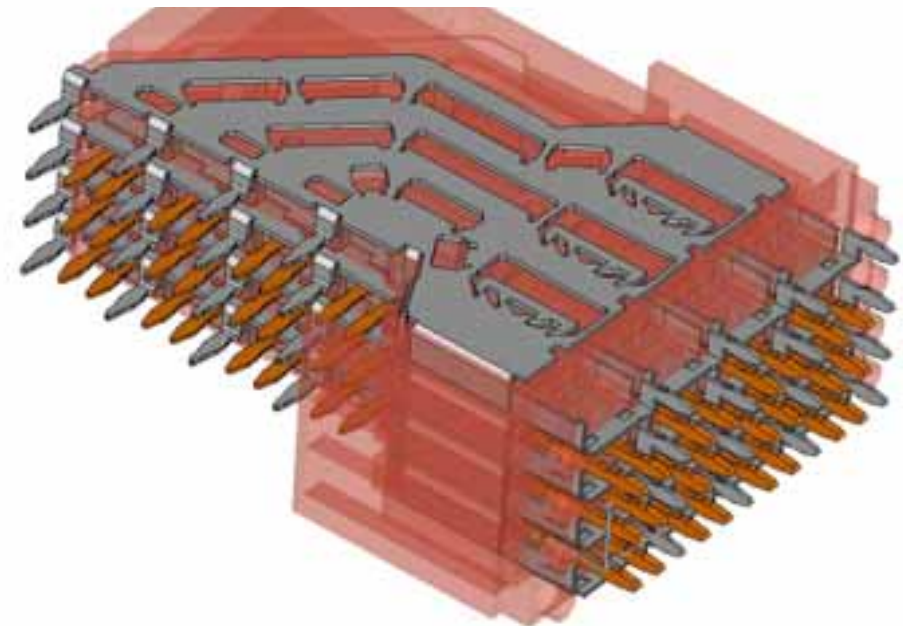
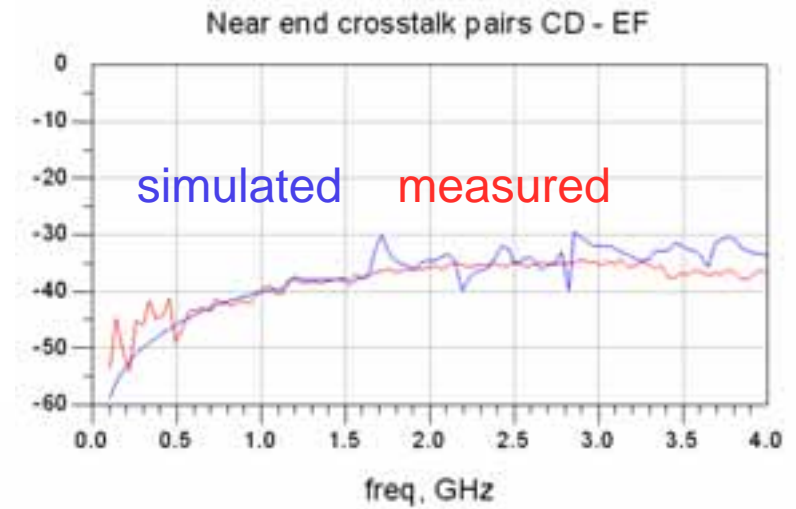
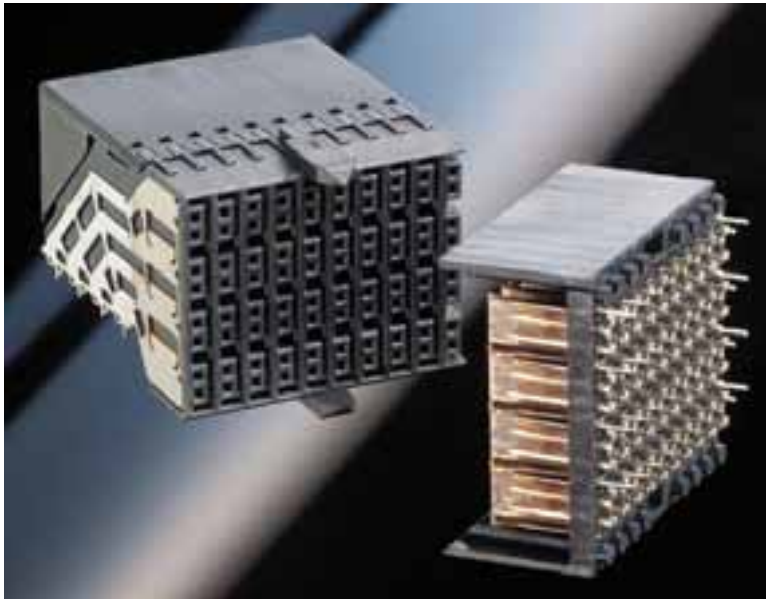




ERNI ERmet zeroXT High Speed SMT Connector



Can handle differential signals up to 10 GBit/s



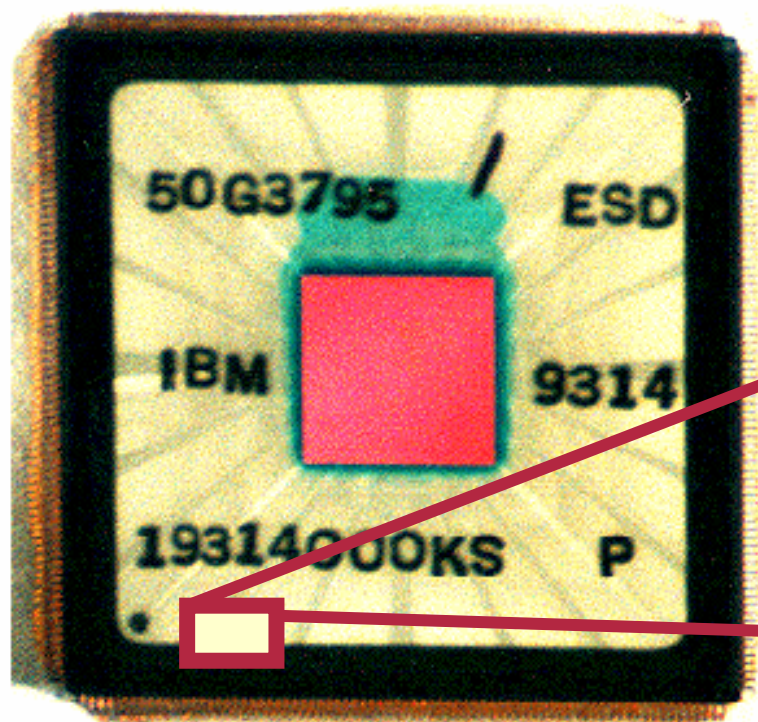
ERNI:

... the connector could be manufactured without a major re-design in one pass....”

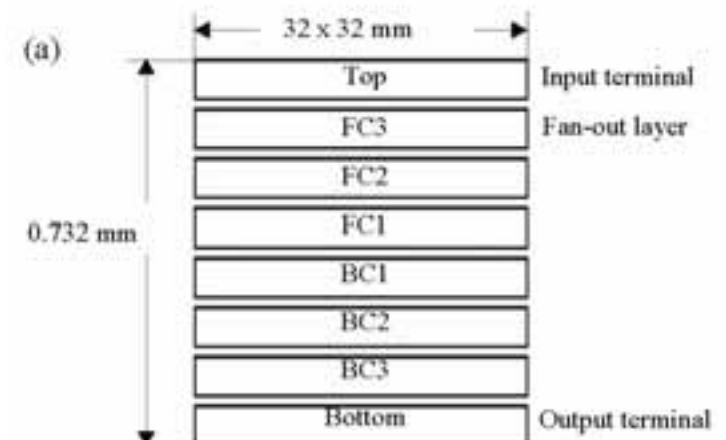
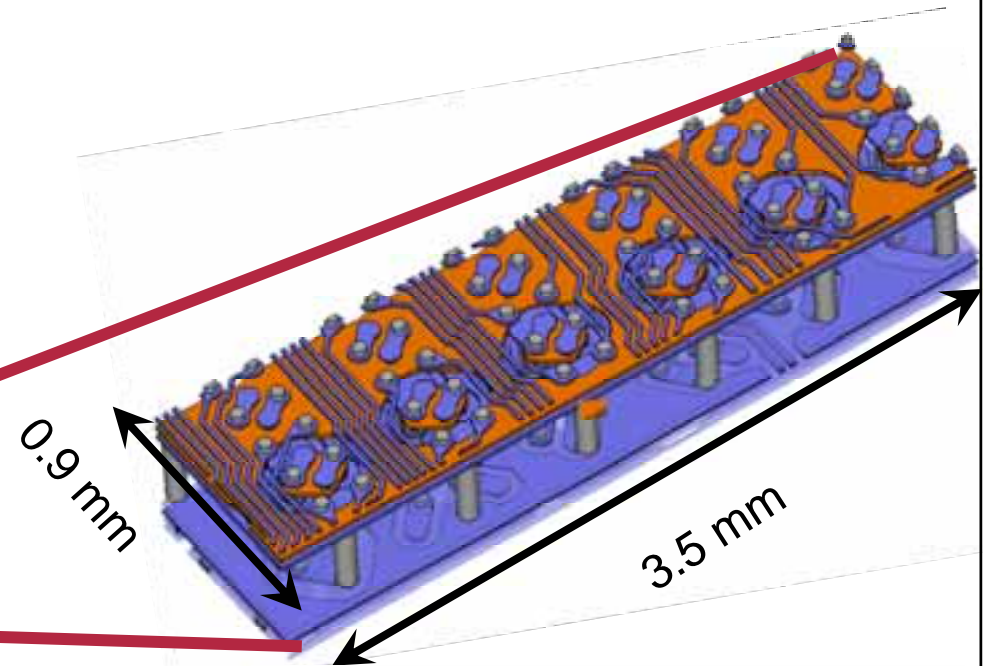




- IBM Example



32 mm

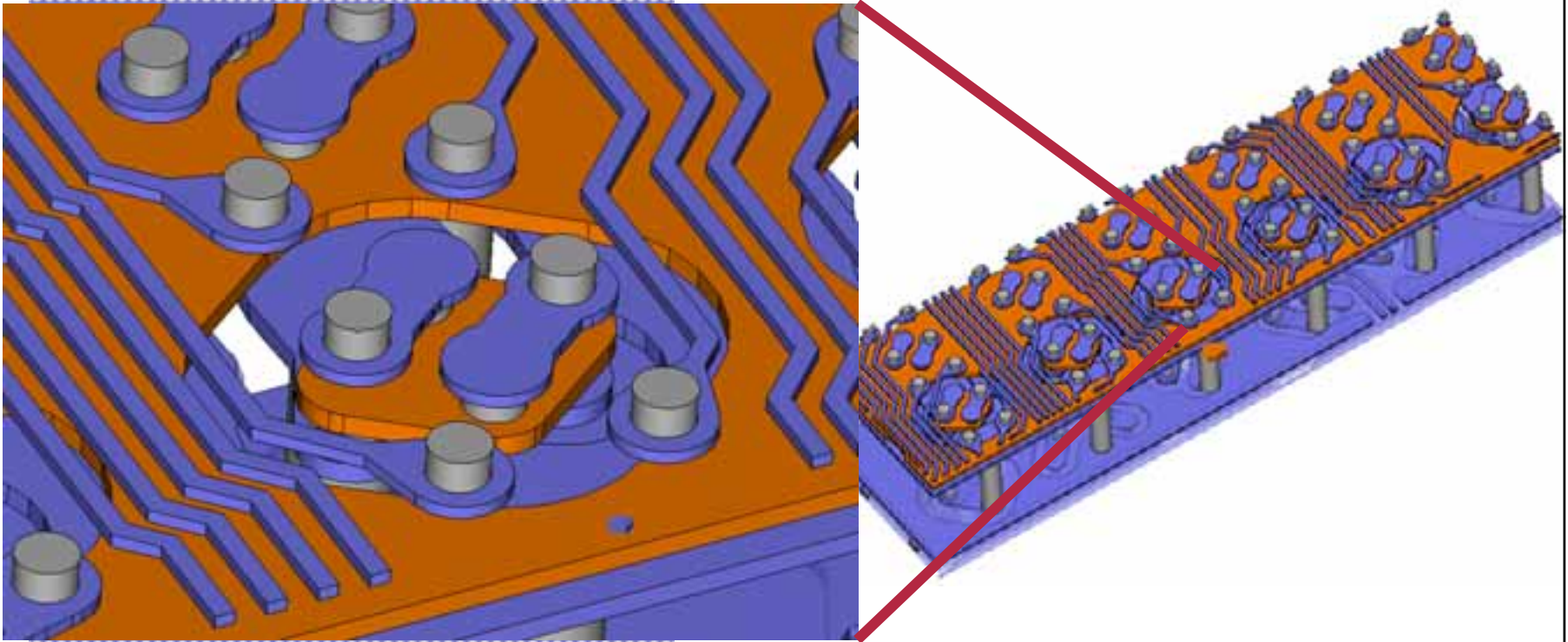




E-Small Very Large Problems



0.8 mm





- Use commercial software „as is“
Limited by memory size of my computer (5GB)
Size of domain only 25% of entire structure
 - **Time domain hexahedral mesh**
(30 million cells)
 - **Frequency domain tetrahedral mesh**
(5.3 million tet's)

Could be easily extended by a bigger computer
- New parallel software
 - **Time domain hexahedral mesh (650 million cells)**

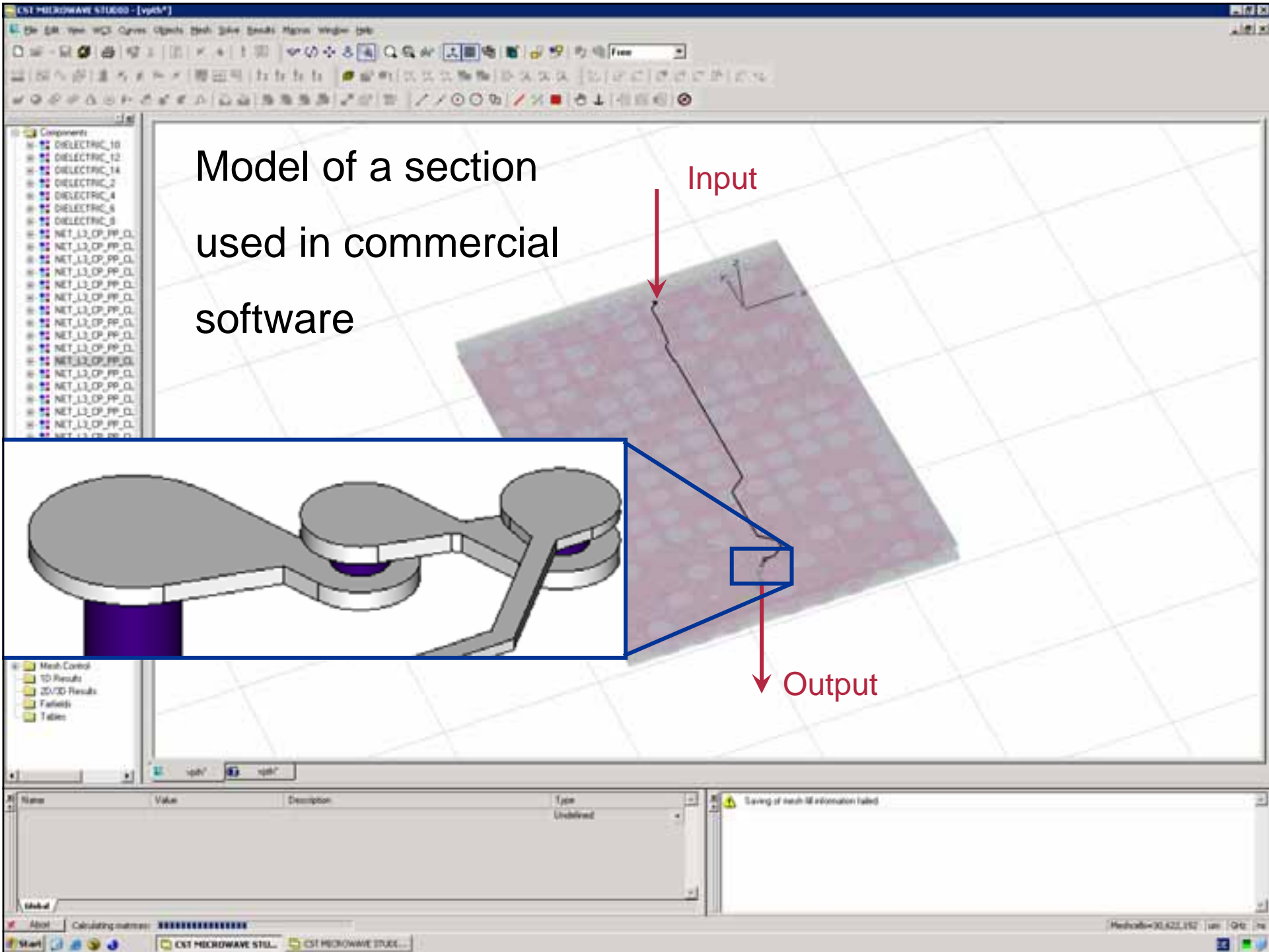
Not yet with all features

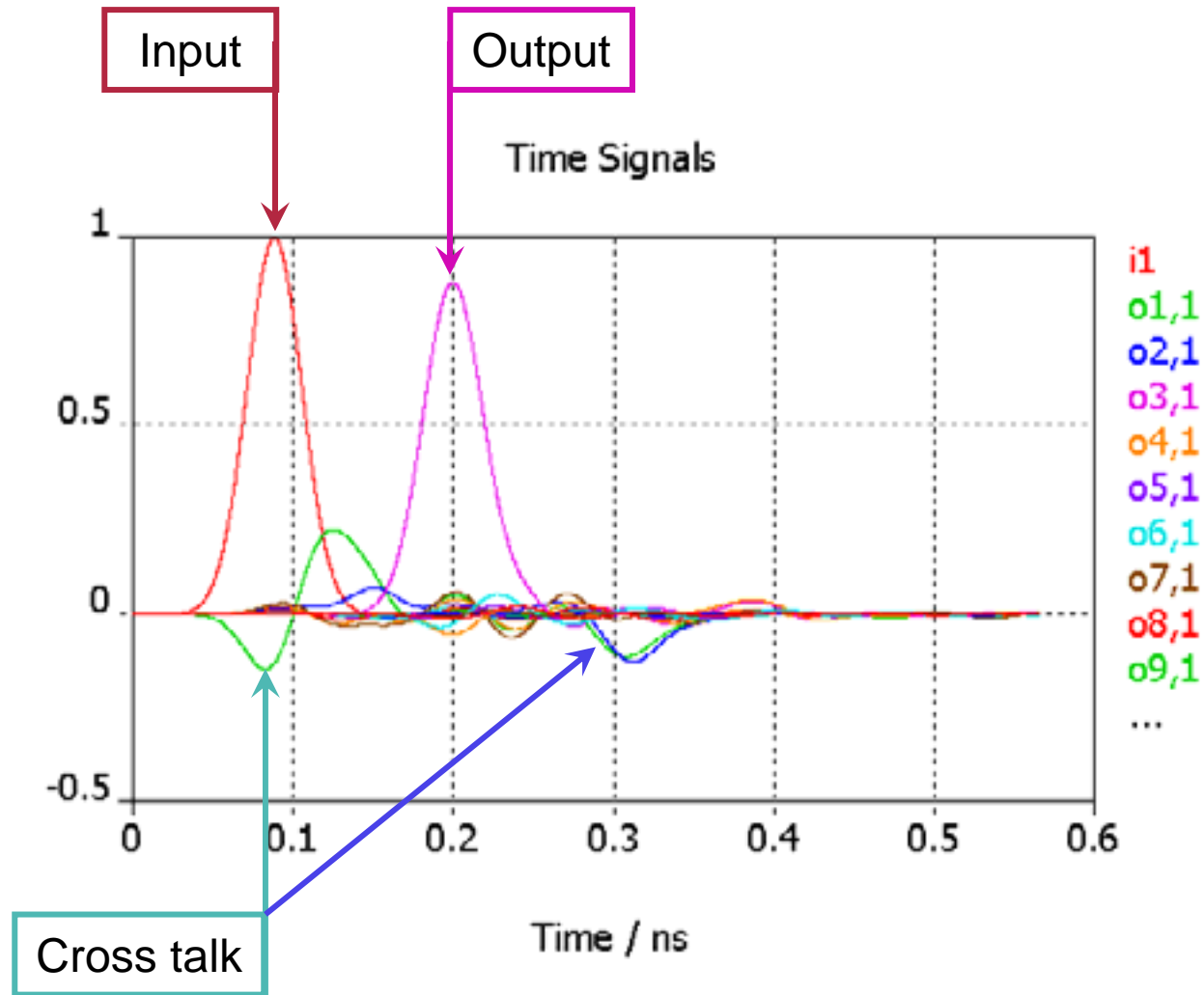


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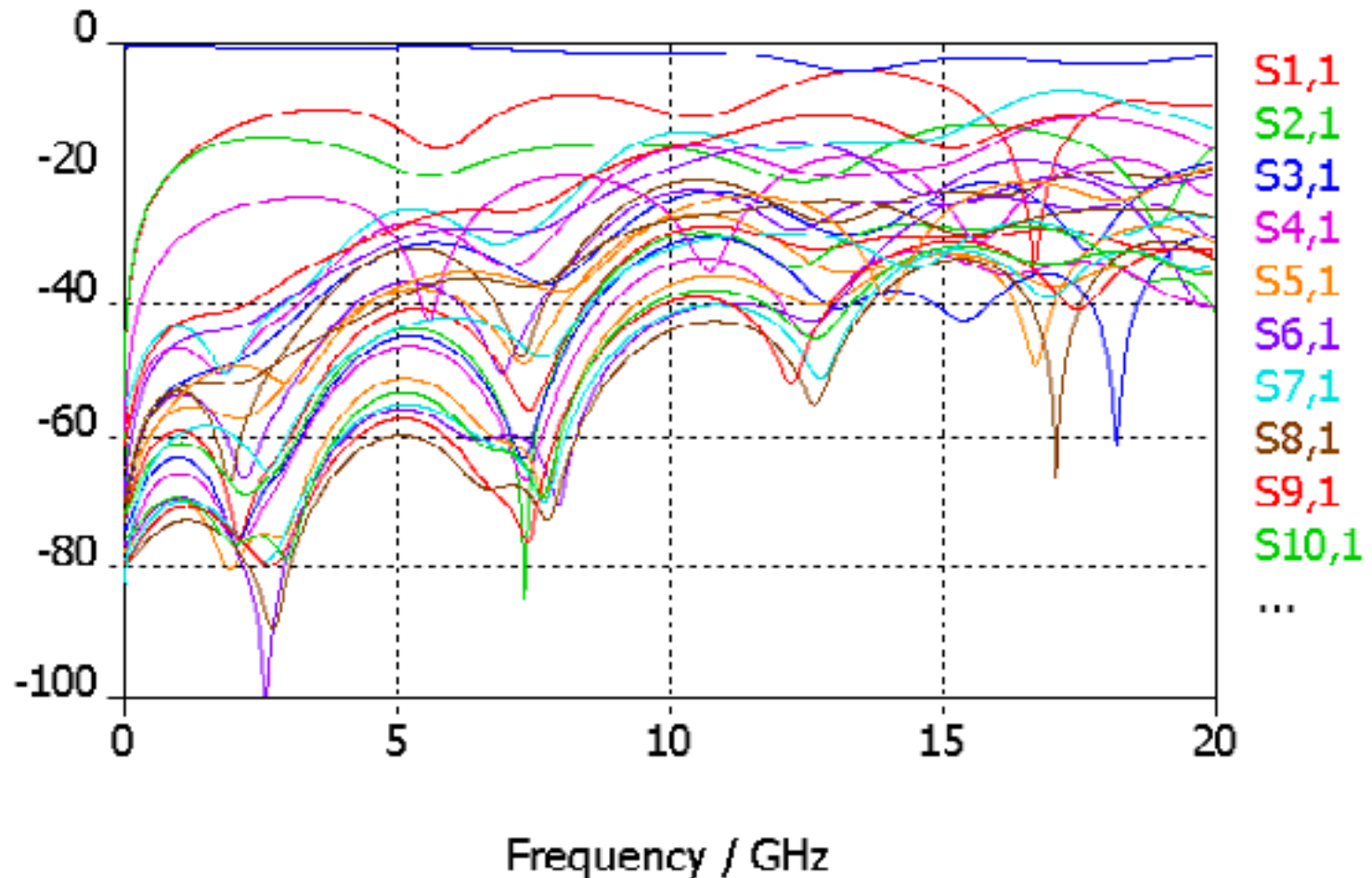




FFT(Output) / FFT(Input)

⇒ S-Parameter for 0 to 20 GHz in **One Go!**

S-Parameter Magnitude in dB



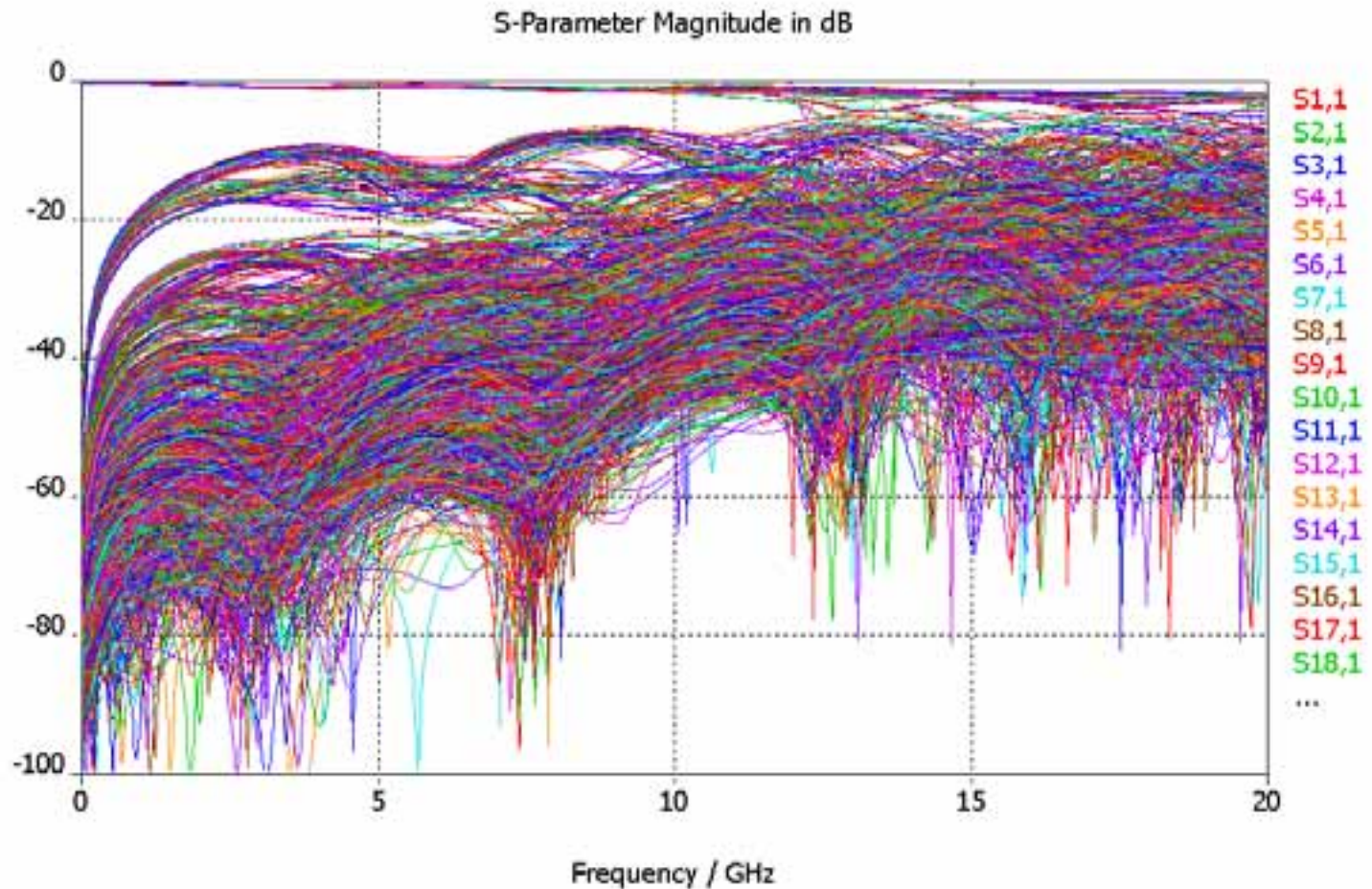


All S-parameter in one Plot



$\text{FFT}(\text{Output}) / \text{FFT}(\text{Input})$

⇒ S-Parameter for 0 to 20 GHz in **One Go! 1600 curves!**

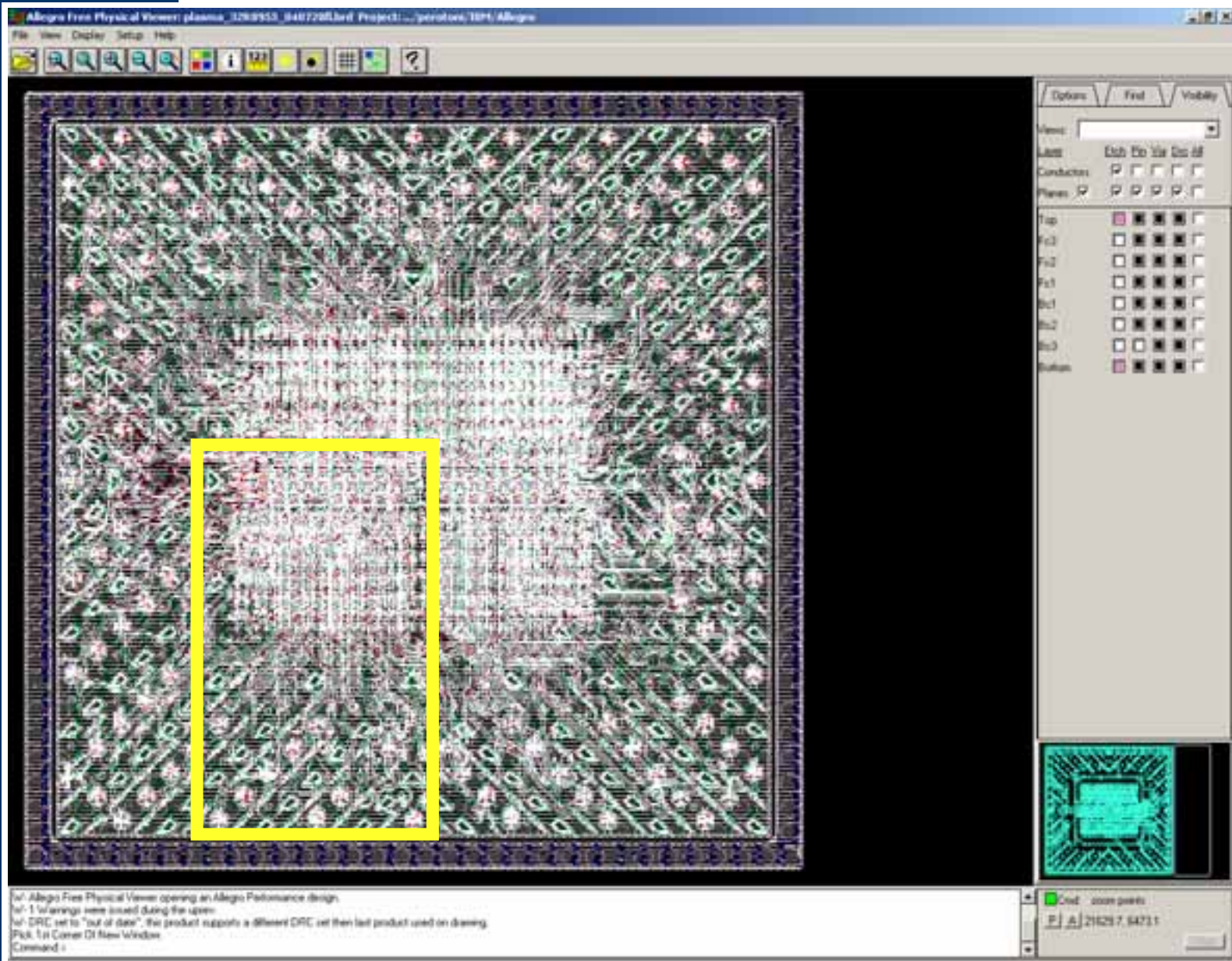


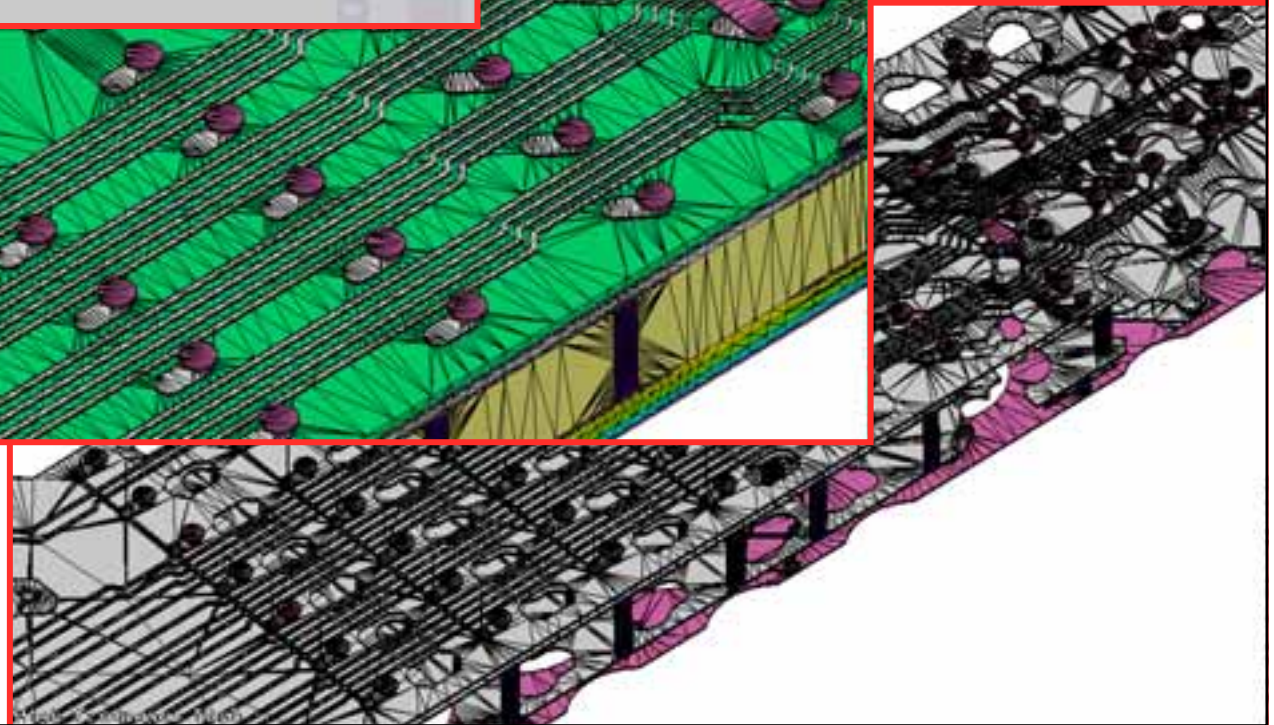
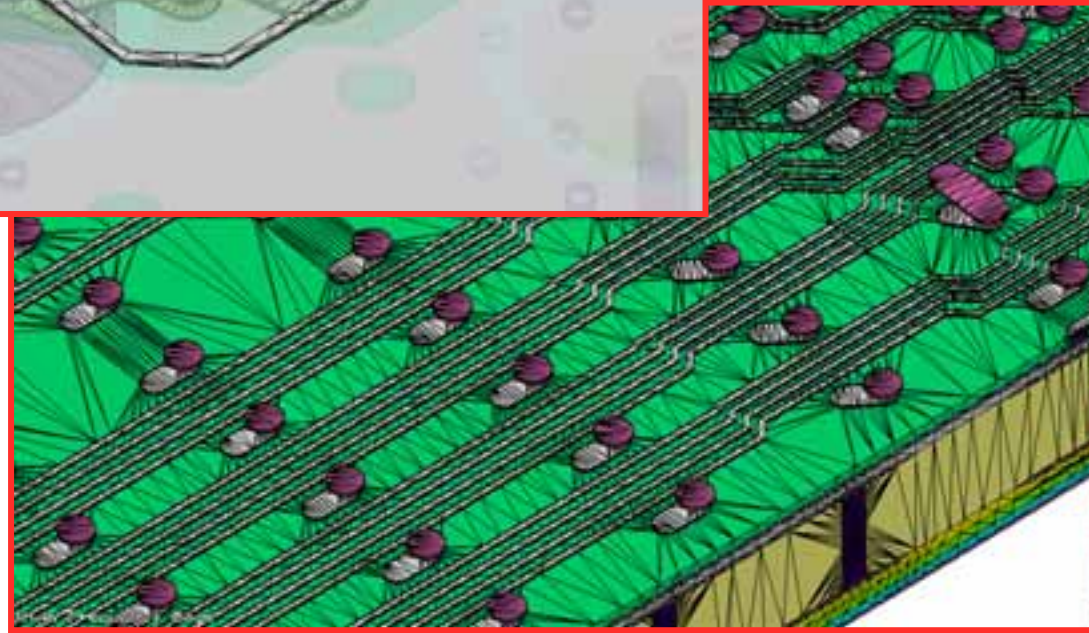
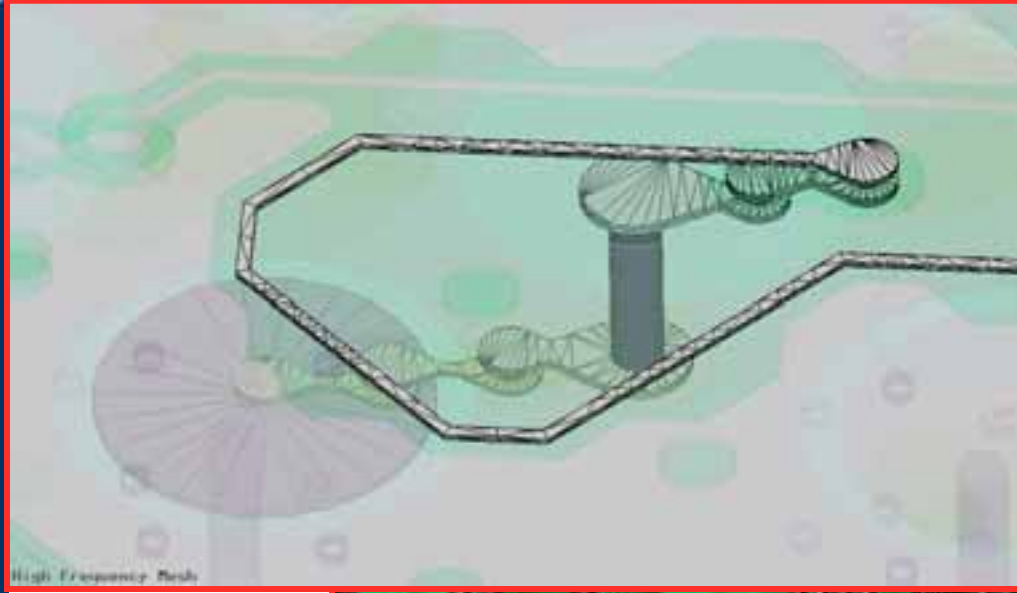


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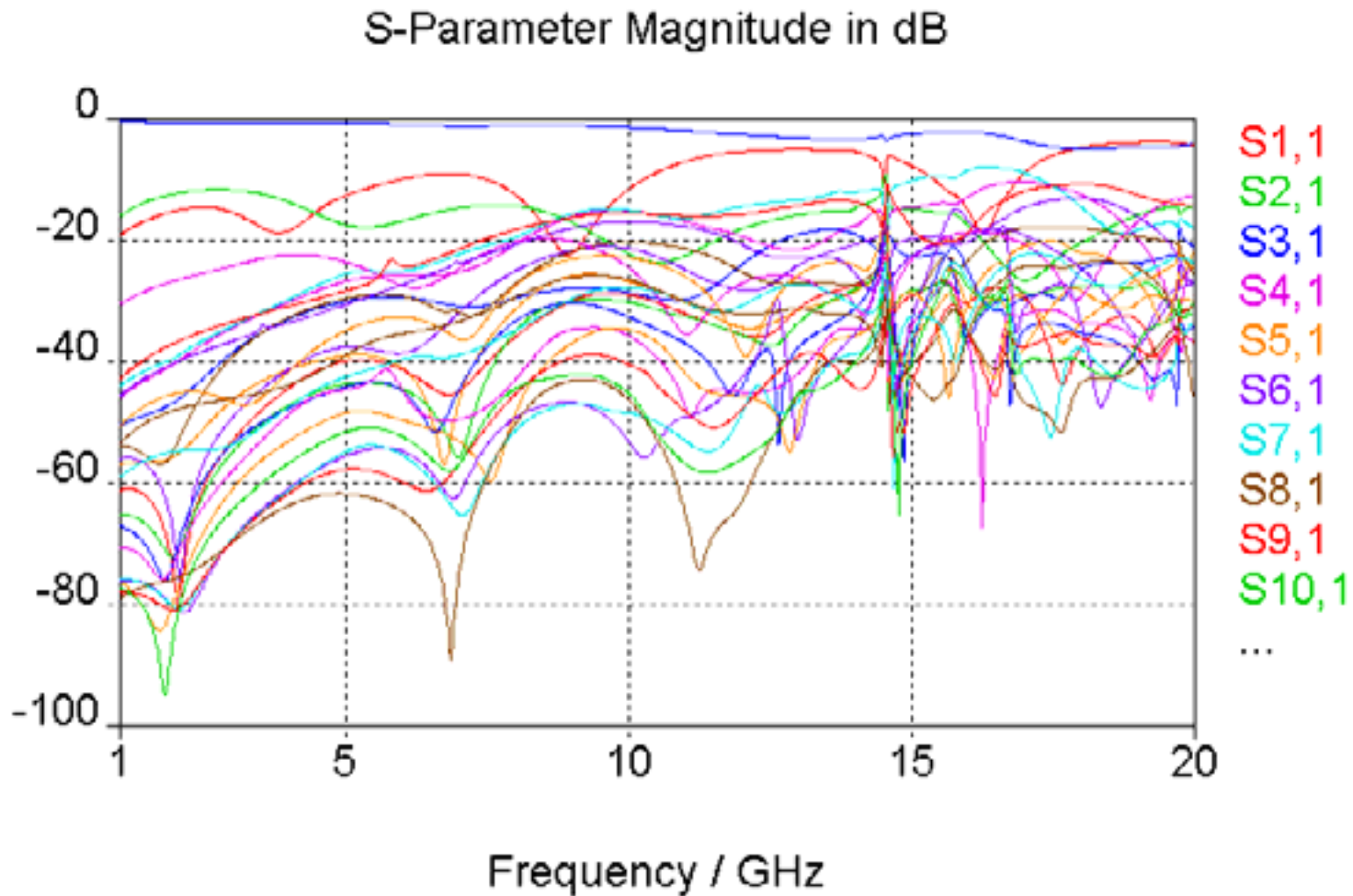
Not yet with all features







5.3 million tet's, broad band frequency domain

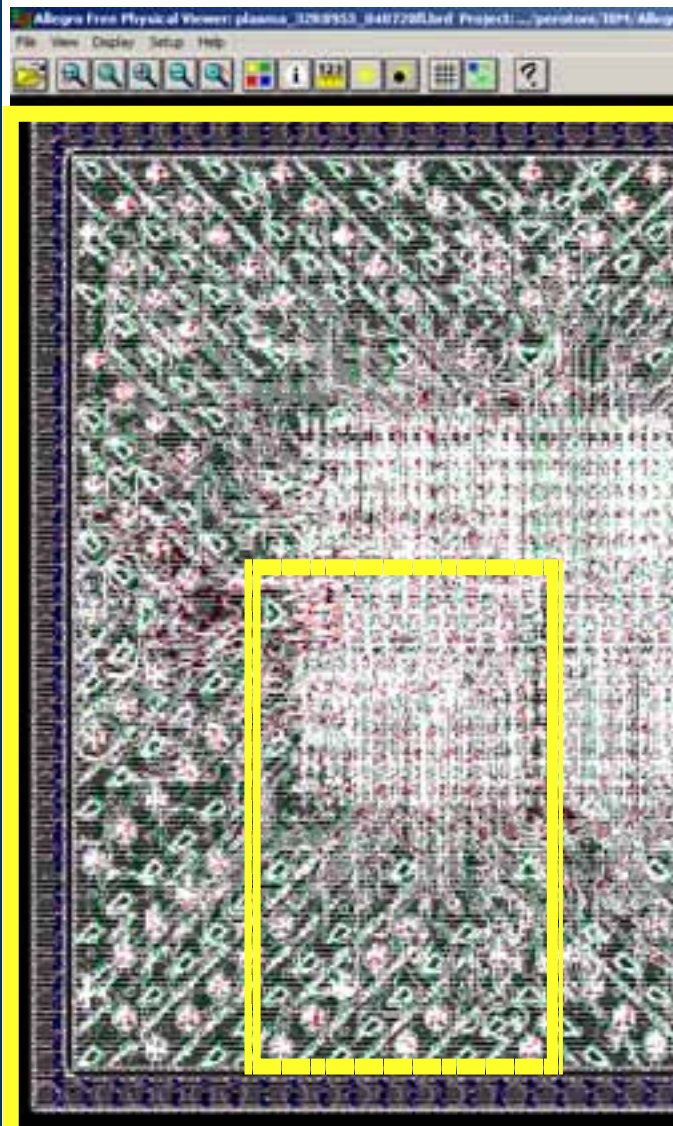




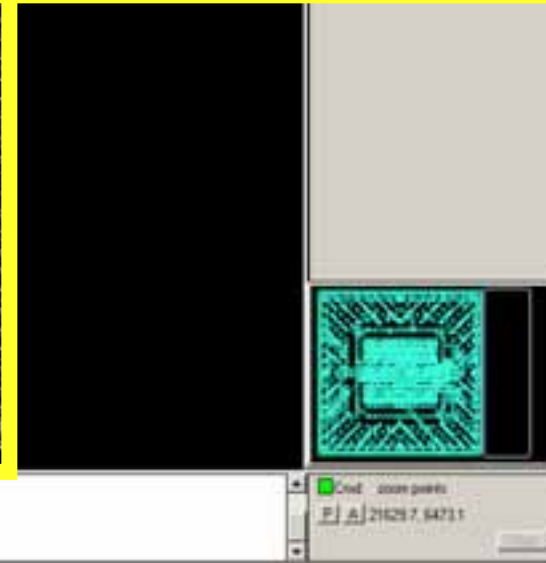
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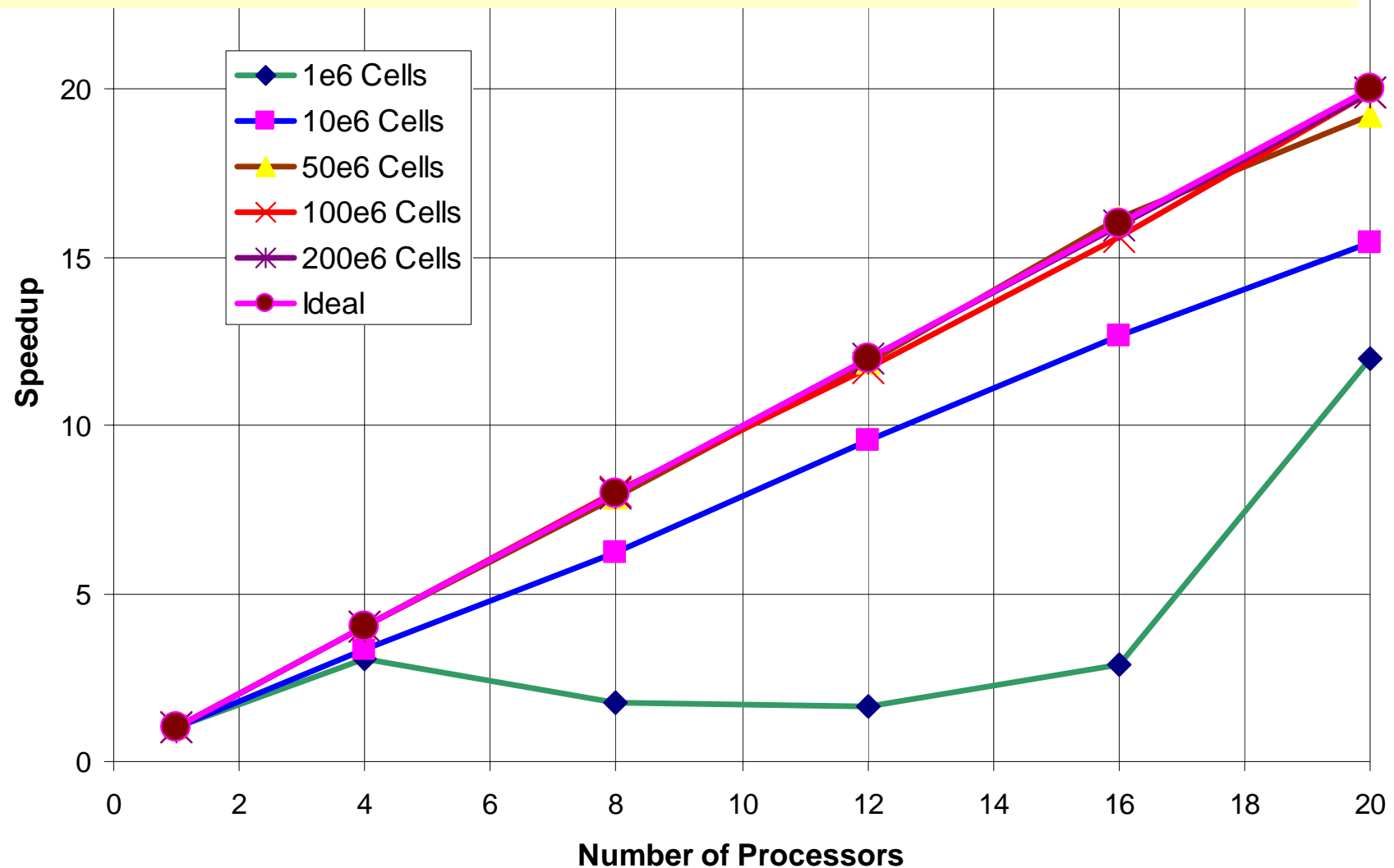
- New dedicated parallelized code
- FIT method Hexahedral discretization time domain
- Parallelized Domain partitioning algorithm
- The **complete model** was simulated (**not only a small part of it!**)
- The **complete model** was simulated **without any geometrical simplification**
- 3,900,000,000 DoFs
24-CPU Cluster - Meshing: 3 hours



for Allegro Free Physical Viewer opening an Allegro Performance design.
!- 1 warnings were issued during the update.
!- DRC set to "out of date". This product supports a different DRC set than last product used in drawing.
Pick 1 in Corner of New Window
Command :



Speedup for a simple test model (no ports)

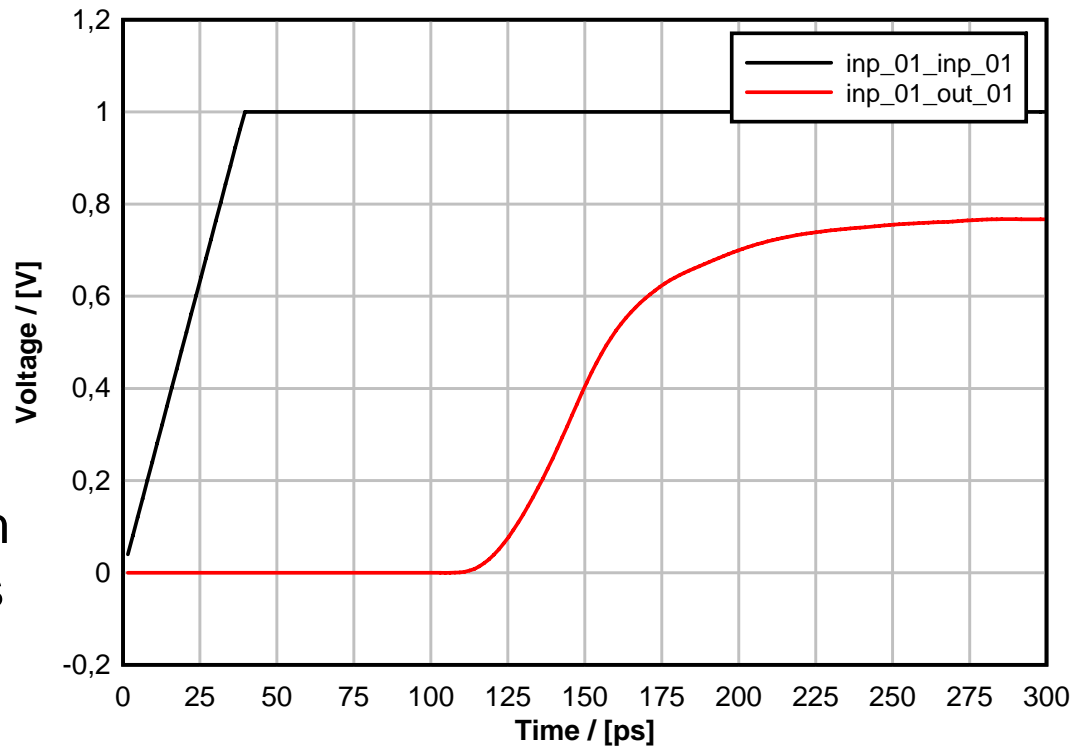




Input

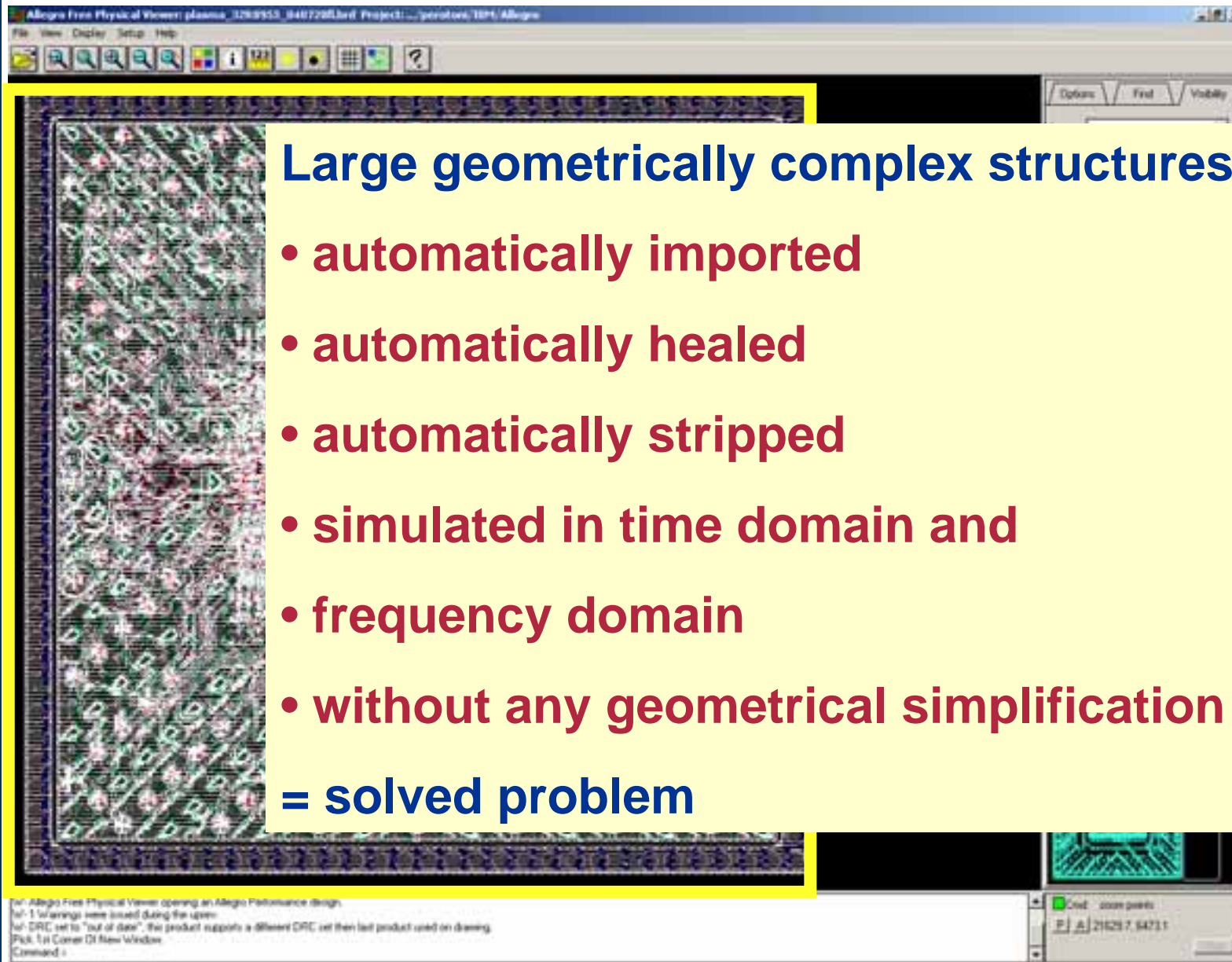
Output

Good agreement with
the measured results
provided by IBM:



Dedicated talk/paper
on Wednesday

EPEP - Session XIII



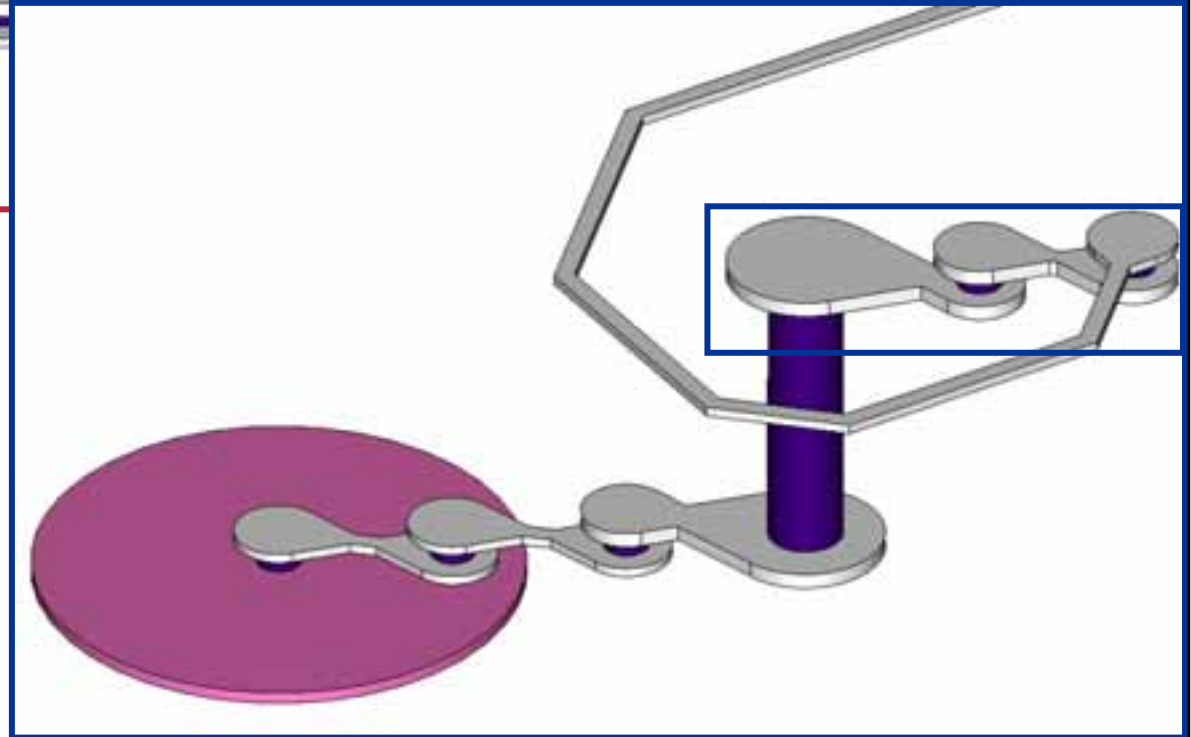
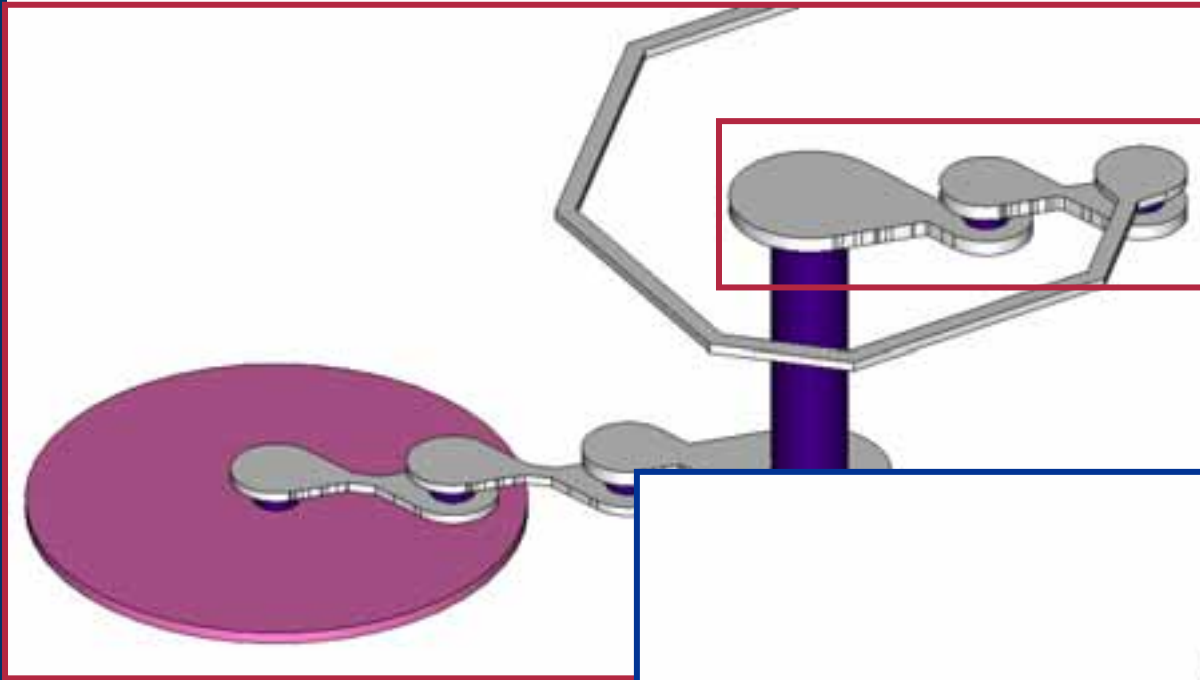
Large geometrically complex structures can be

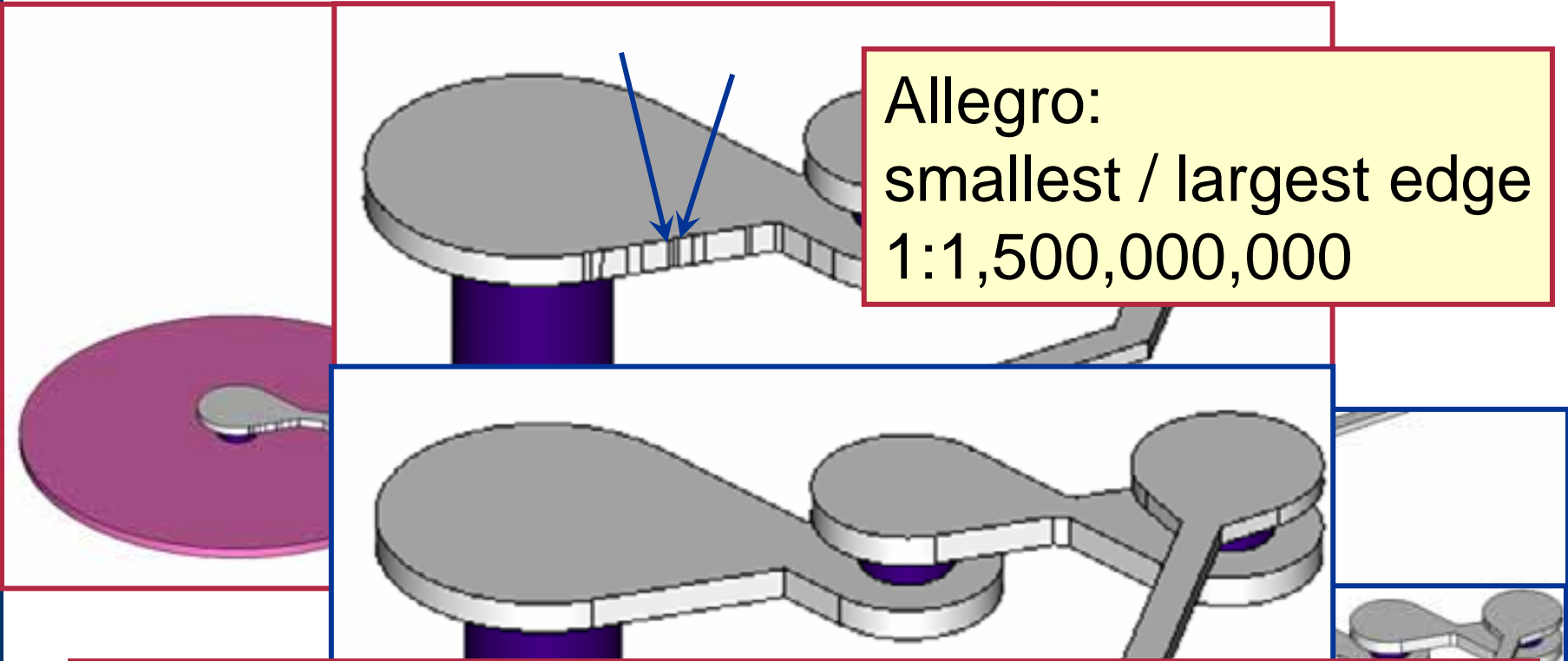
- automatically imported
 - automatically healed
 - automatically stripped
 - simulated in time domain and
 - frequency domain
 - without any geometrical simplification
- = solved problem**



80-100 Mcells / 1 sec for a realistic application (ideal up to **400 Mcells/sec**)

- ~ Factor 10 with respect to 32 bit processor
- ~ Factor 5 with respect to 64 bit processor
- ~ Factor 2 with respect to Woodcrest





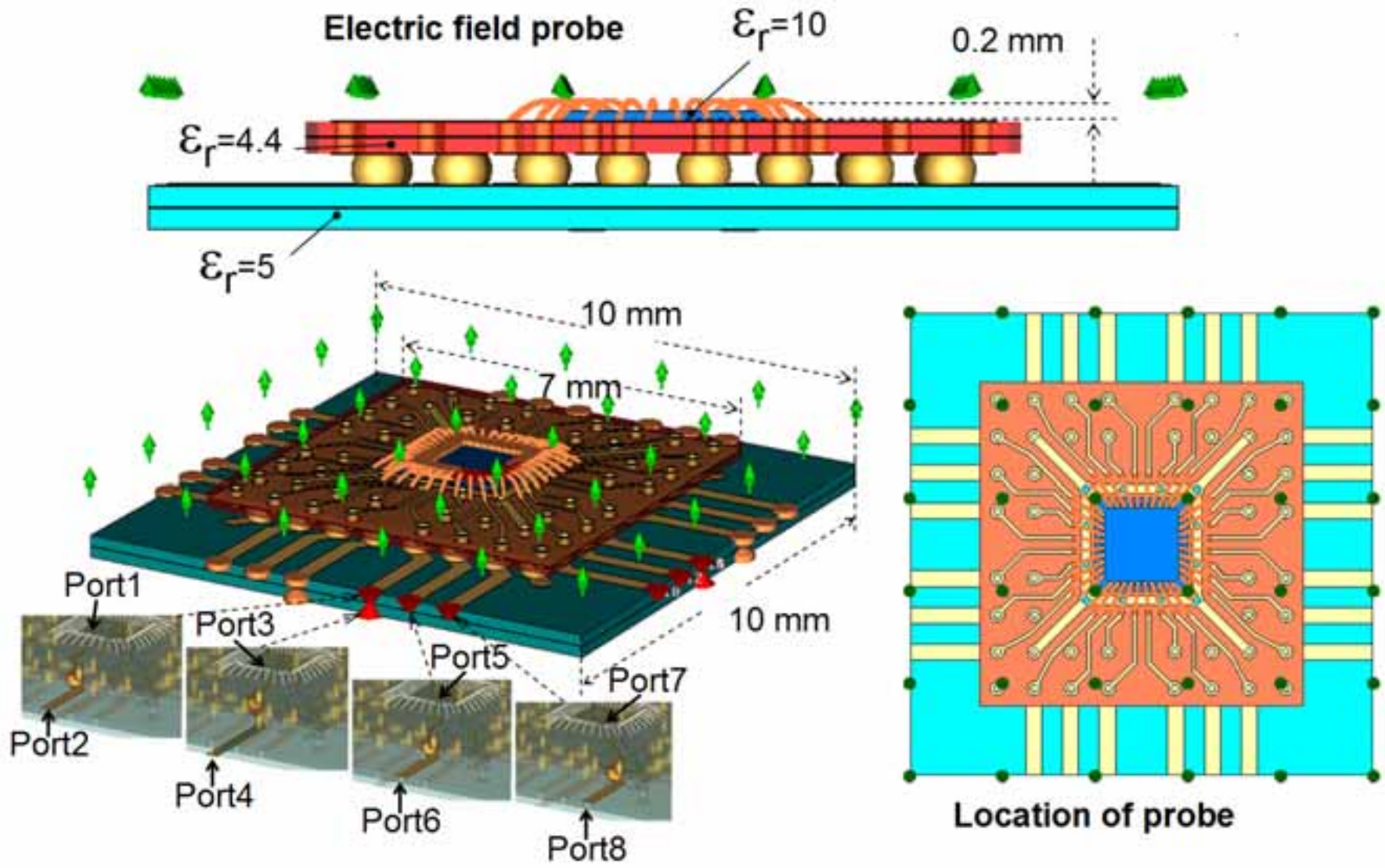
CST MICROWAVE STUDIO®:
Fully automatic clean-up and healing
No simplification of the model,
Just healing and stripping unnecessary edges

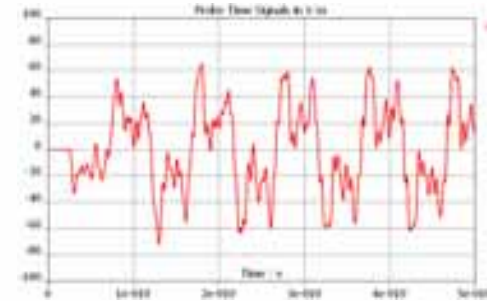
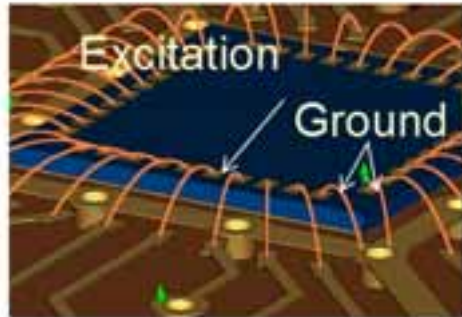


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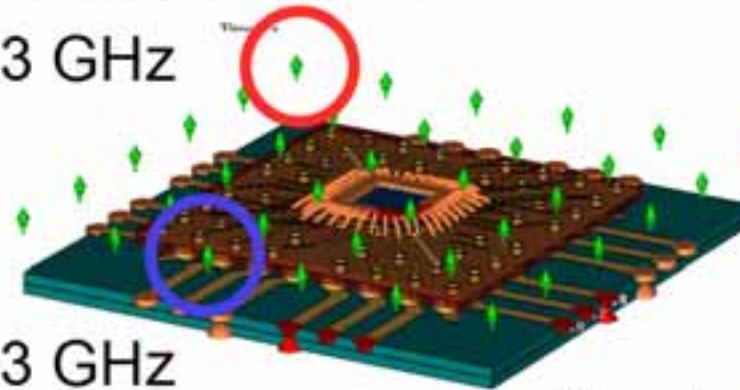
Wire Bonding and Package Simulation Model





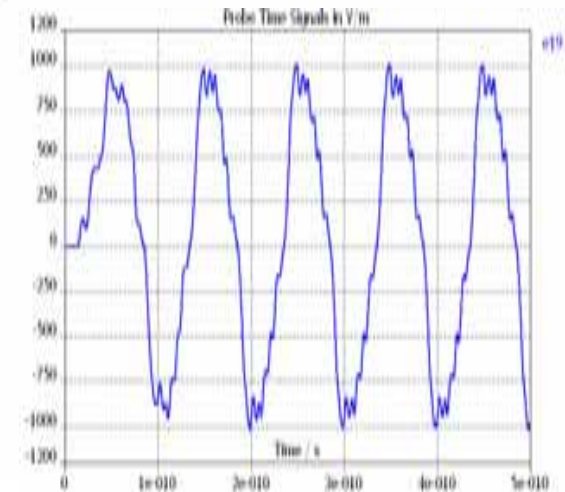
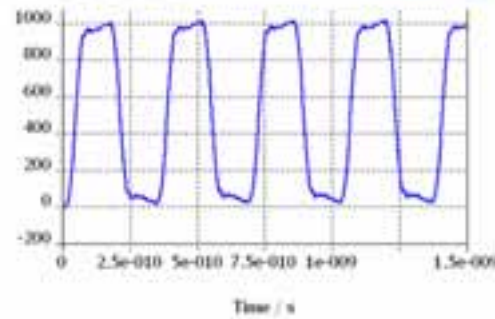
3 GHz

10 GHz



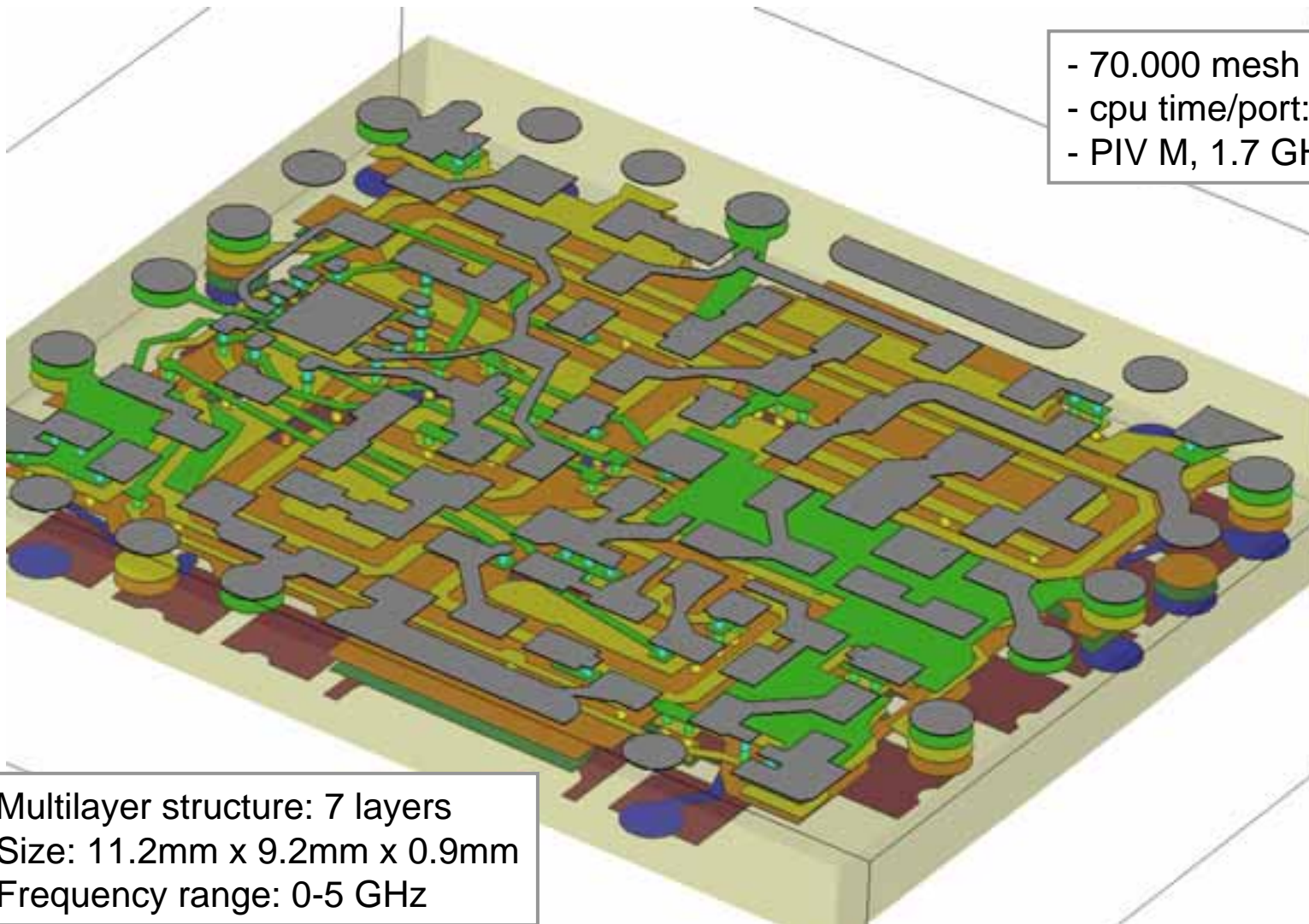
3 GHz

10 GHz





Multilayer structure

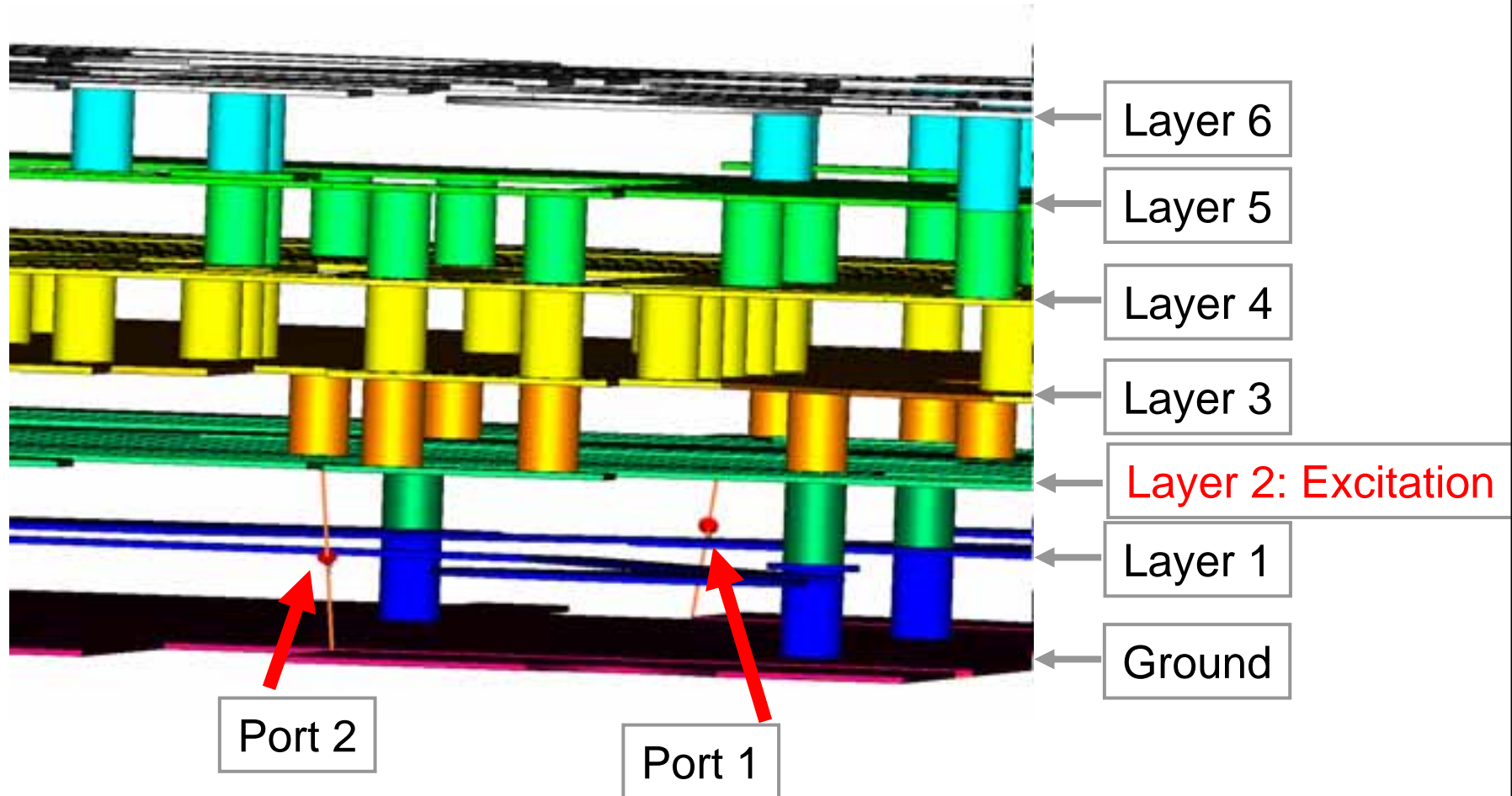


- 70.000 mesh cells
- cpu time/port: 560 s
- PIV M, 1.7 GHz

Multilayer structure: 7 layers
Size: 11.2mm x 9.2mm x 0.9mm
Frequency range: 0-5 GHz

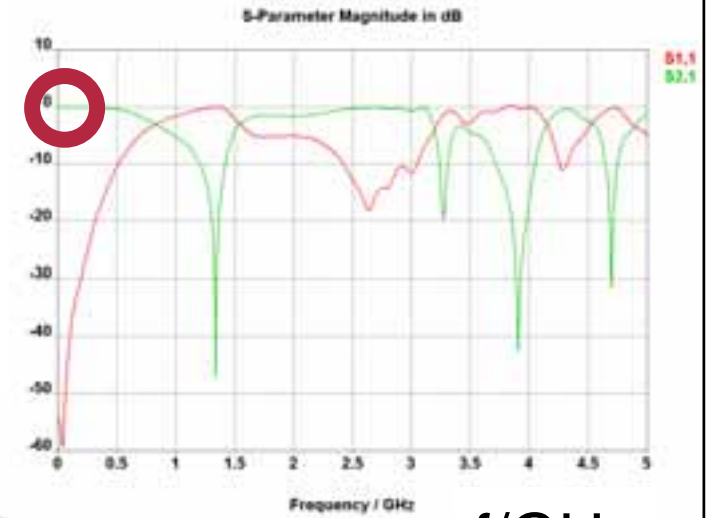


2-Port Study

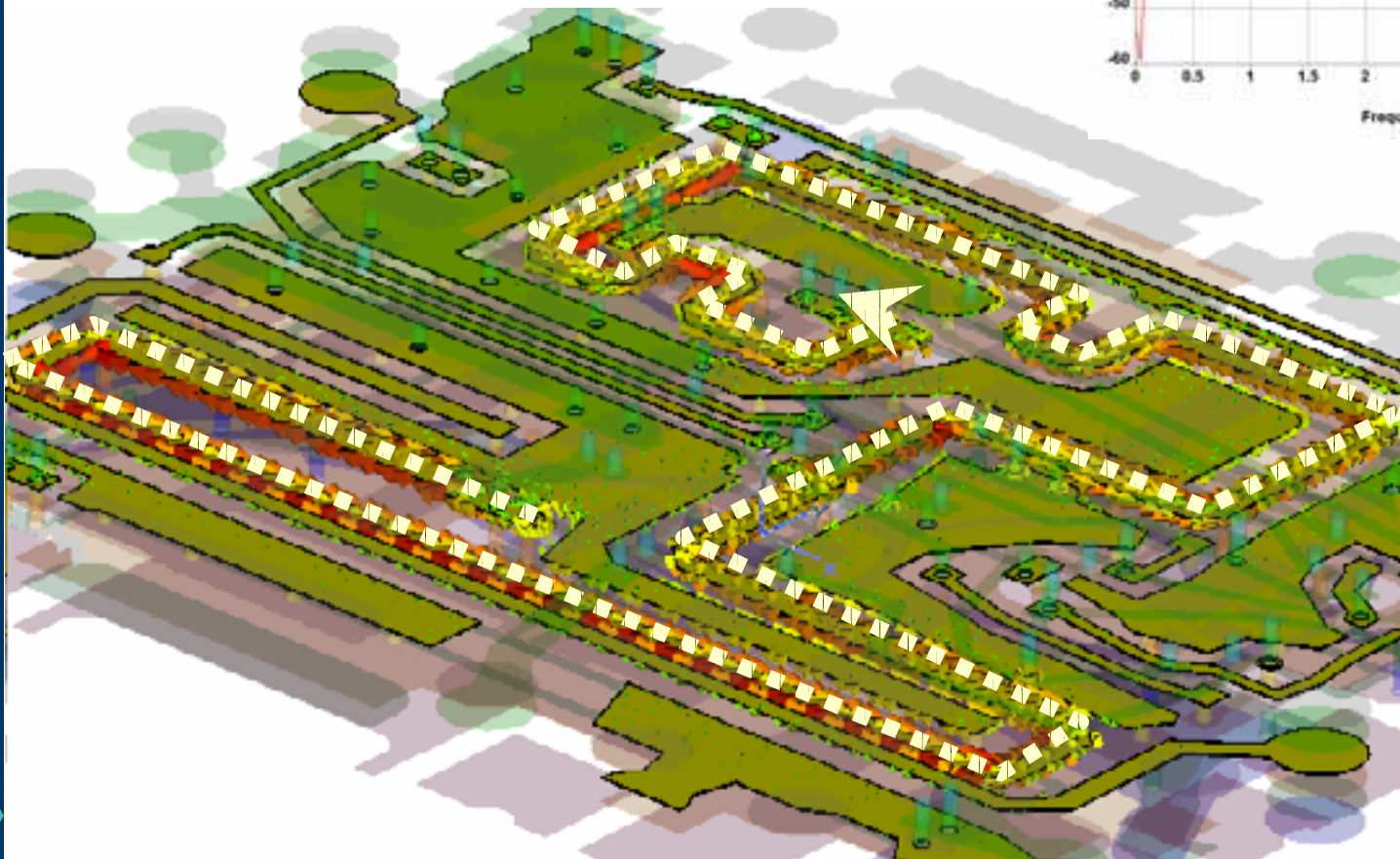




S_{11} , S_{21} 



f/GHz

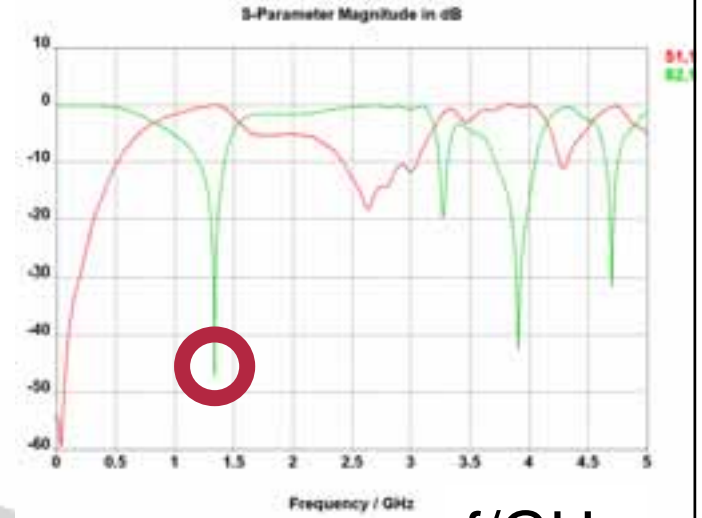




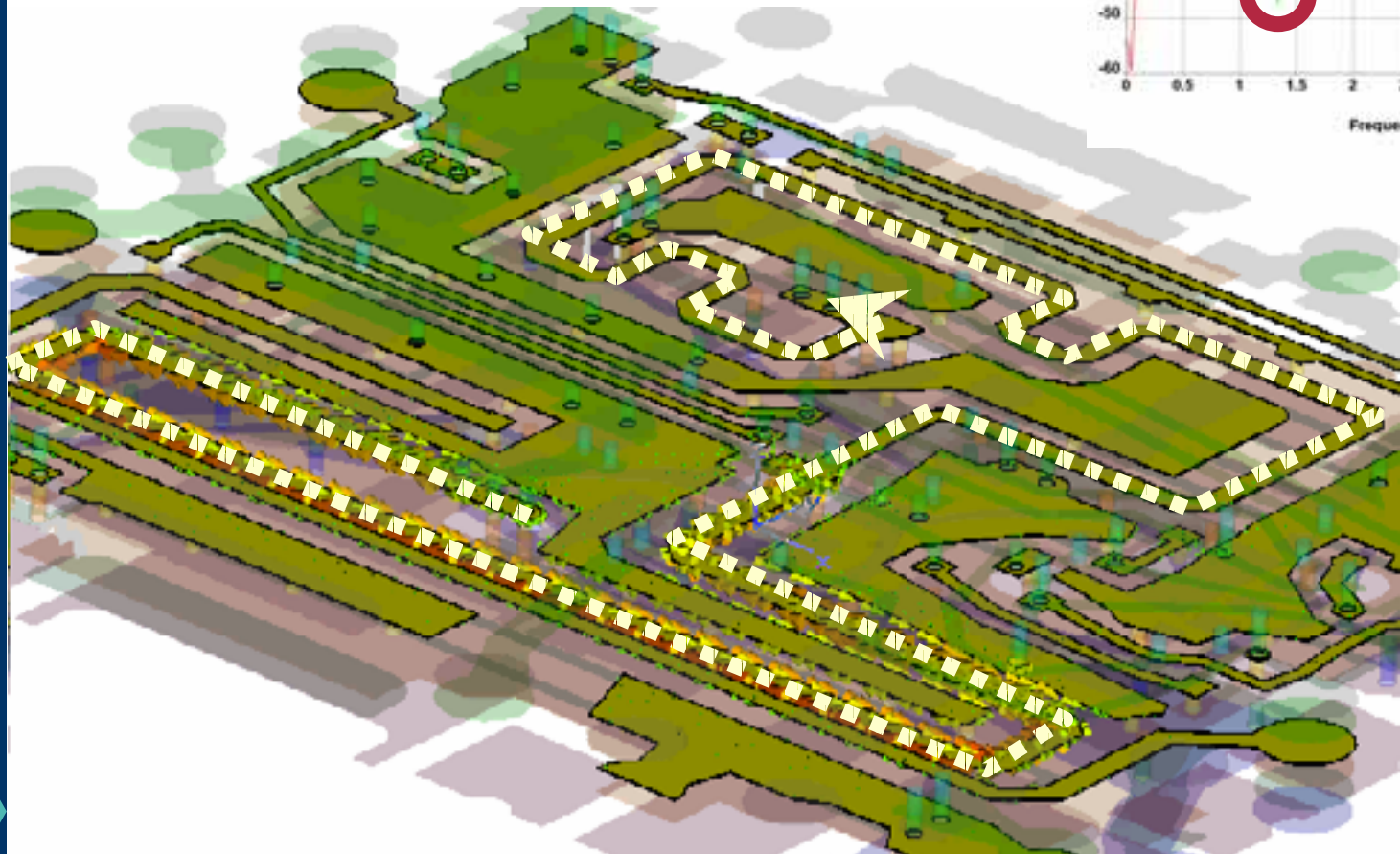
1.34 GHz



S_{11} , S_{21}



f/GHz

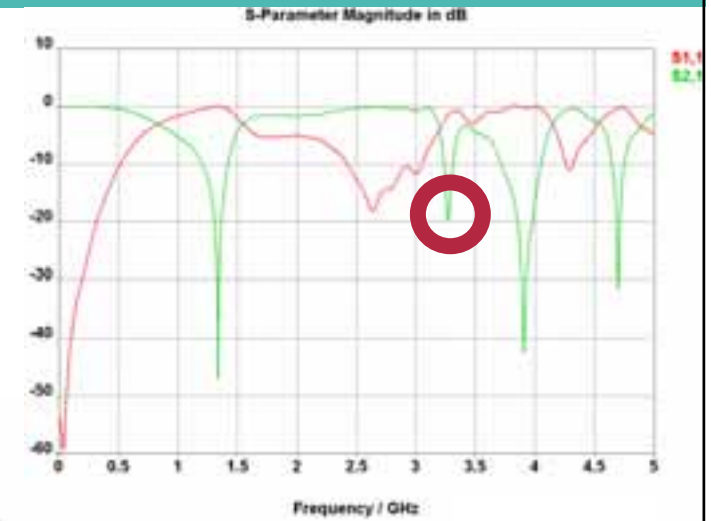




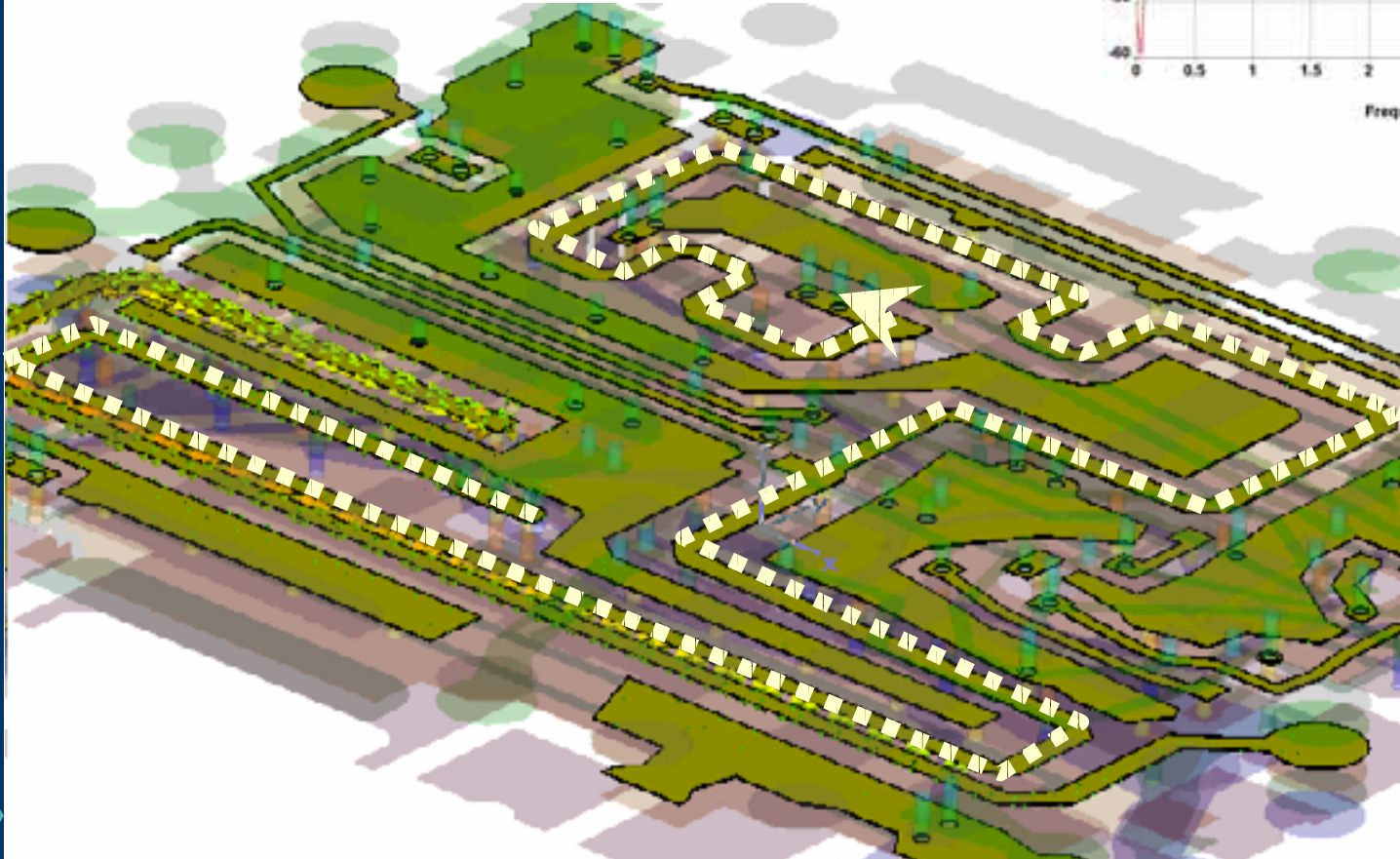
3.26 GHz



S_{11} , S_{21}

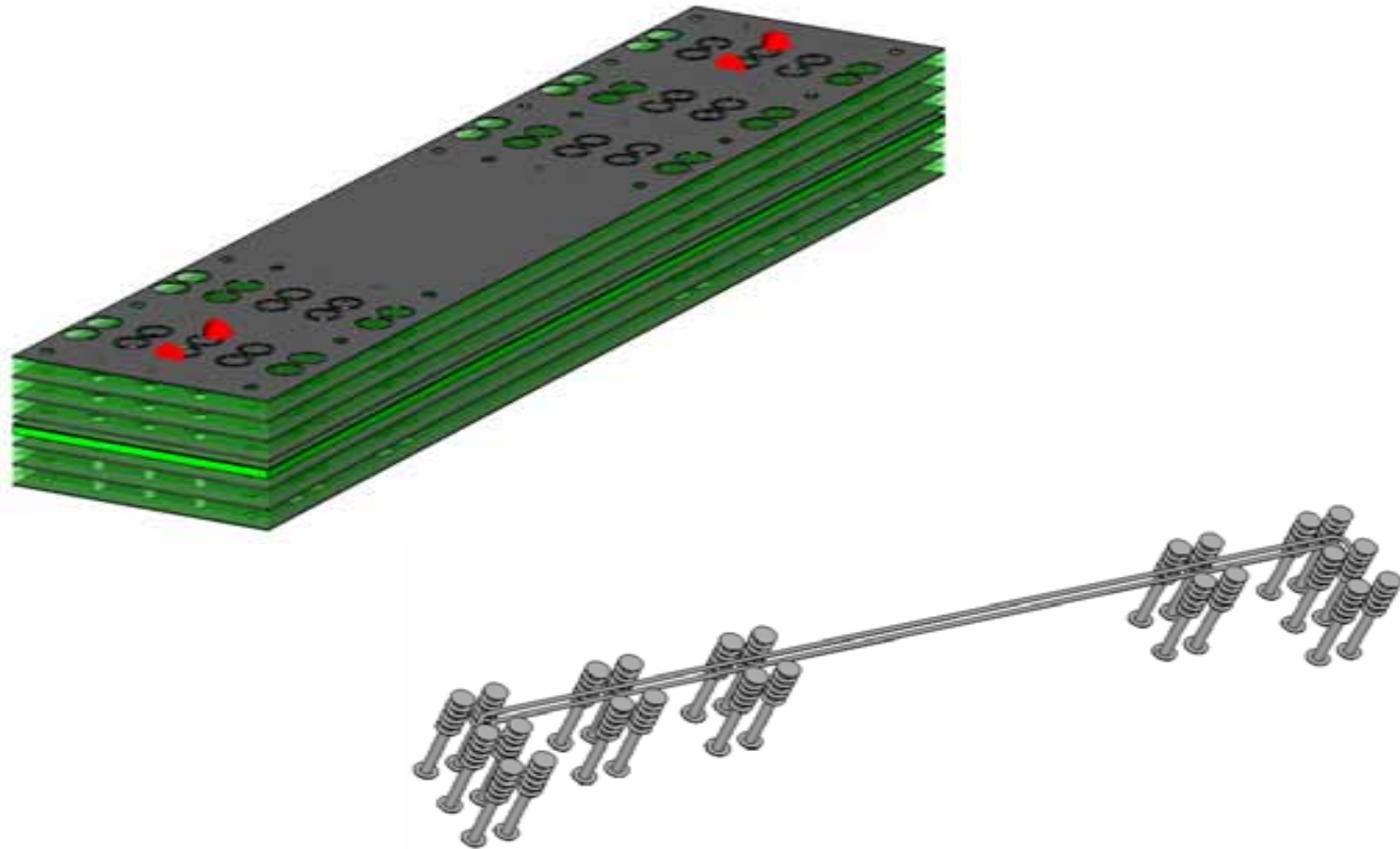


f/GHz



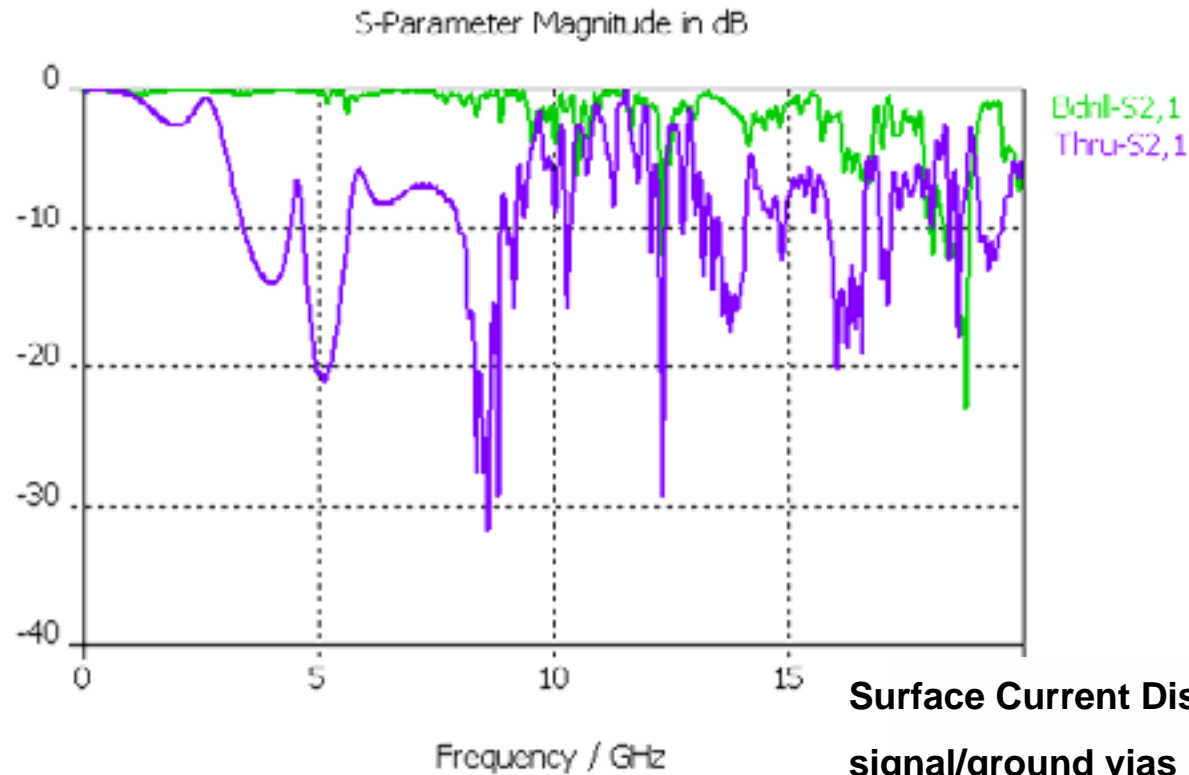


Allegro import of backplane pair

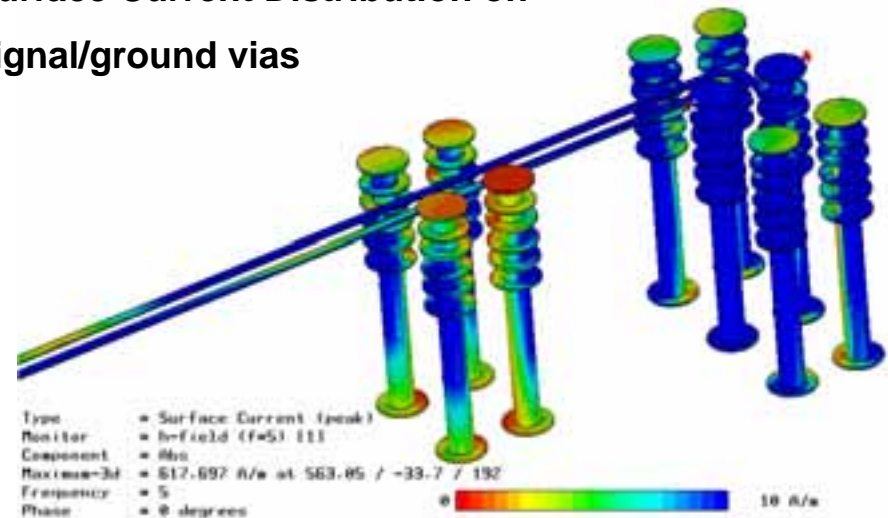




S21 Thru via vs. back drilled via

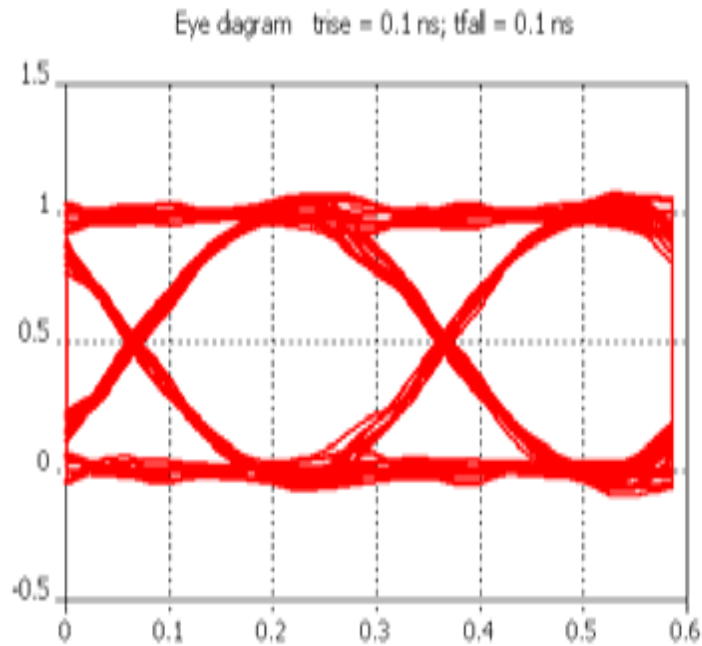


Surface Current Distribution on signal/ground vias

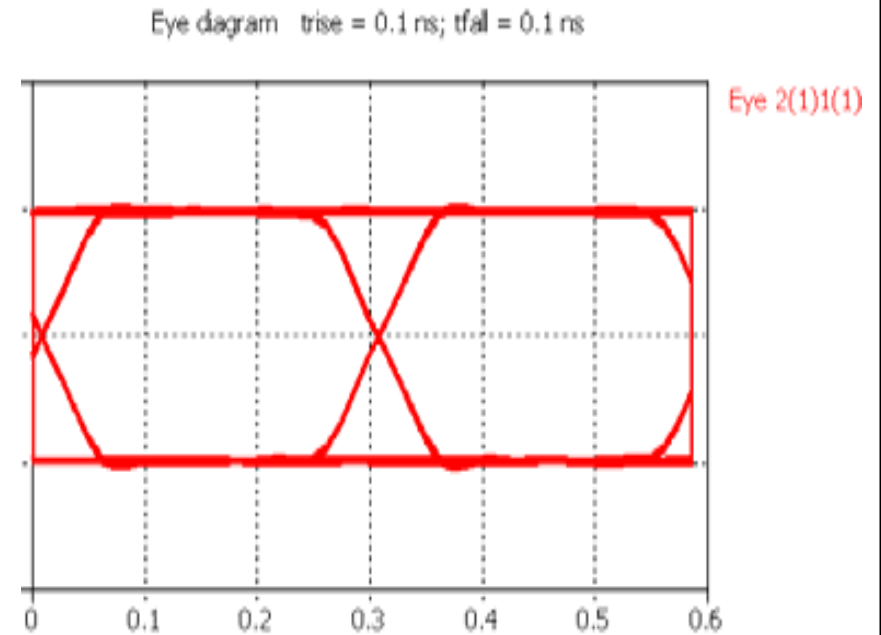




Backplane pair Eye Pattern Through vs. Back Drill Via



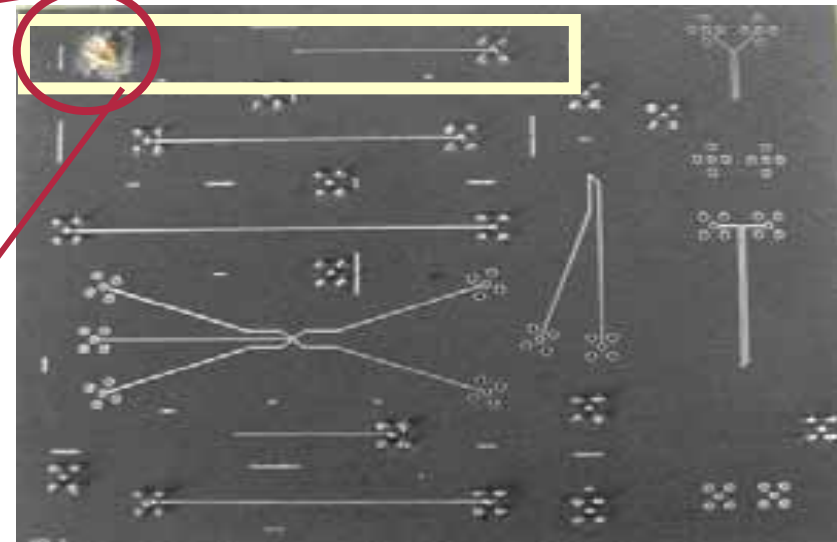
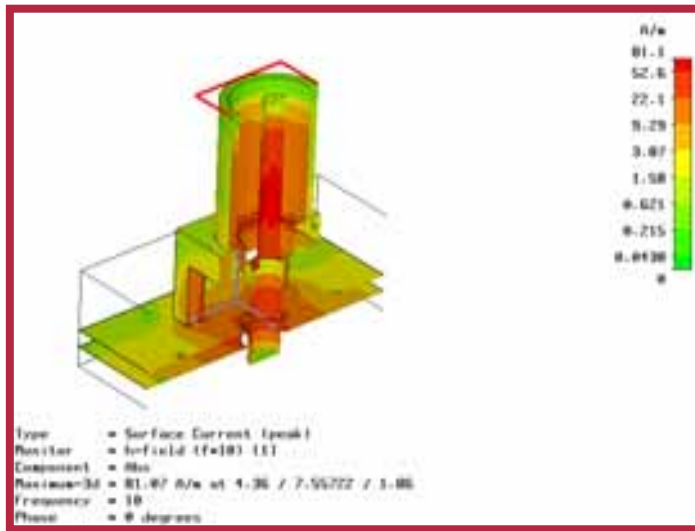
Through Hole Via



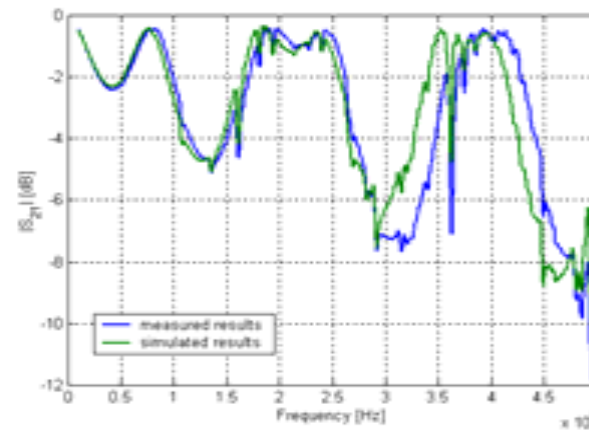
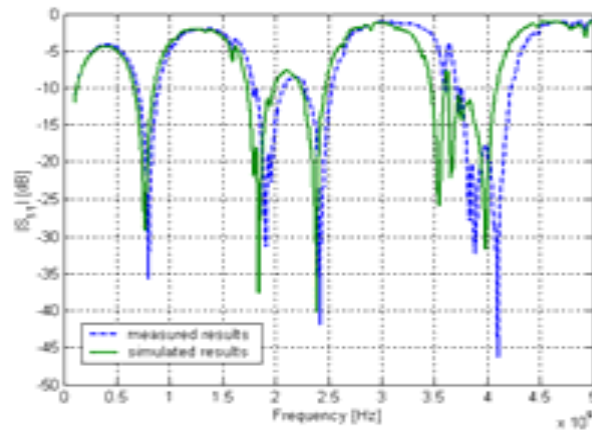
Back Drill Via

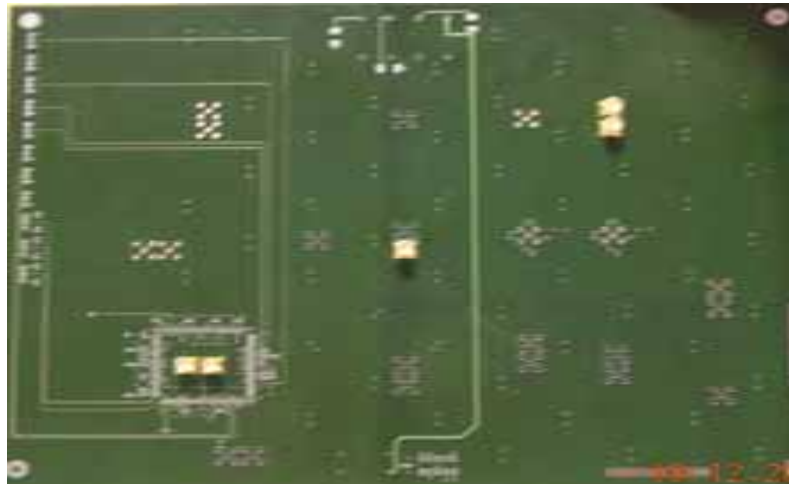


Stripline and via hole on PCB board



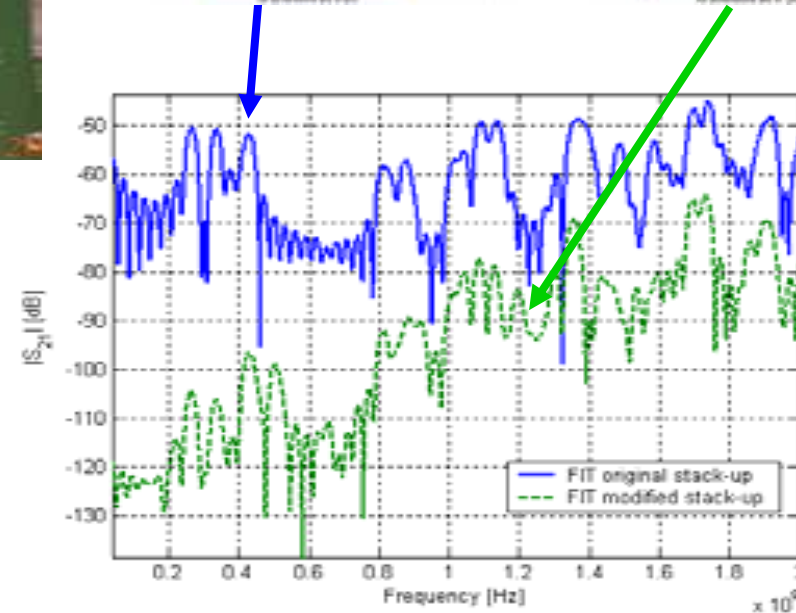
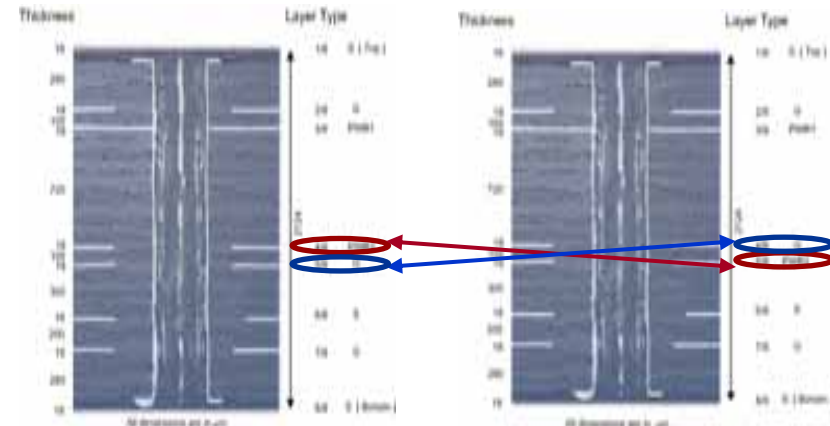
measured simulated





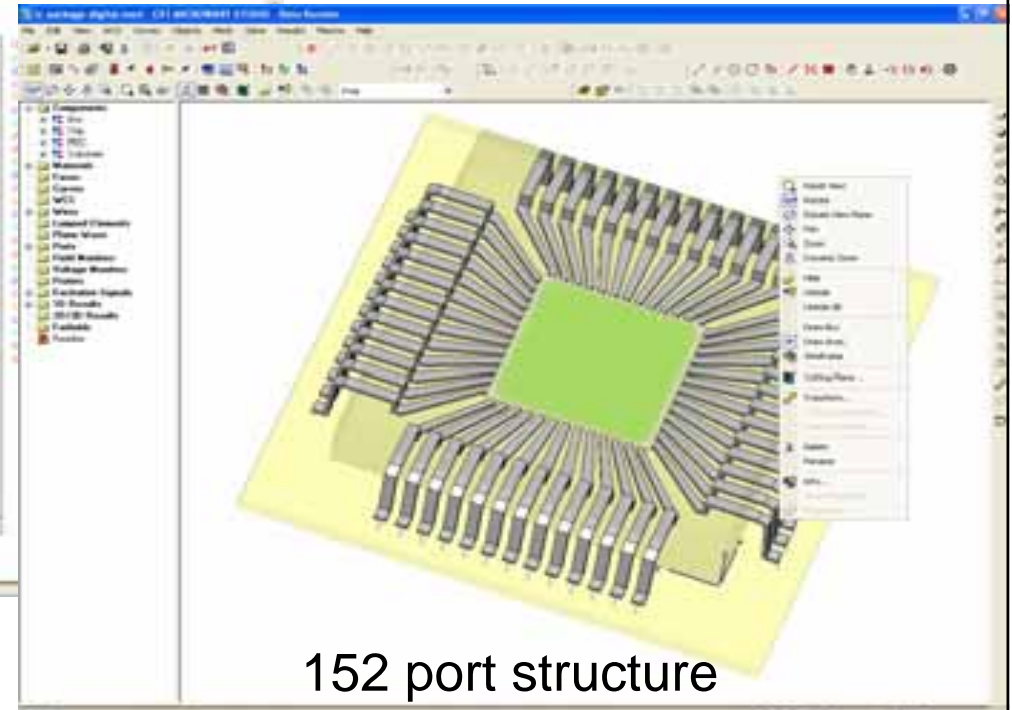
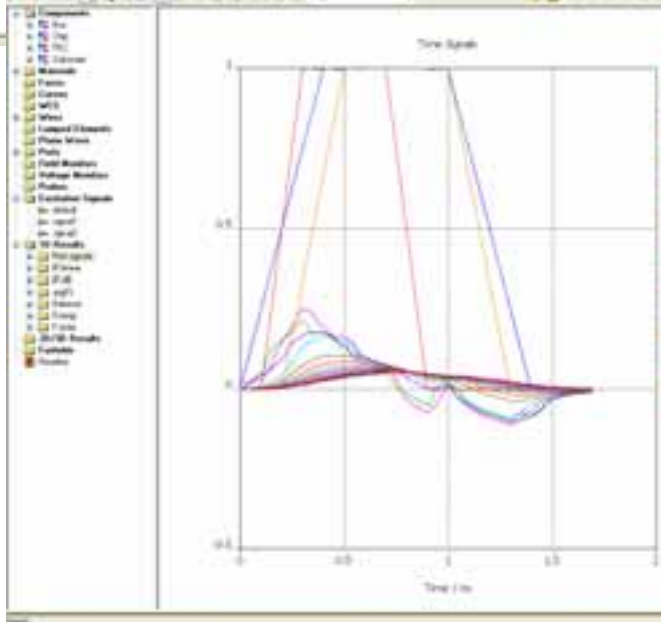
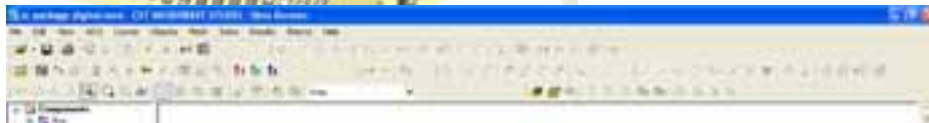
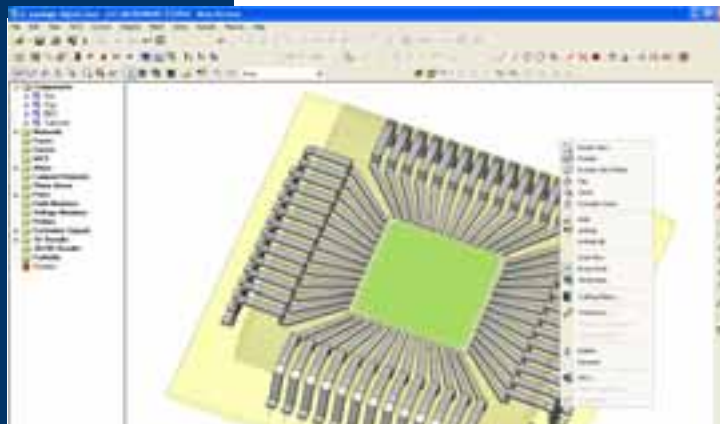
Swapping **PWR1**
and **PWR2** drastically
reduces the coupling
between the power planes

Test board: Siemens C.N.X.- UAq EMC Lab
Model and simulation: UAq EMC Lab (L'Aquila, Italy)
Courtesy Prof. A. Orlandi





IC Package – Digital signal simulation





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SPICE Model Extraction

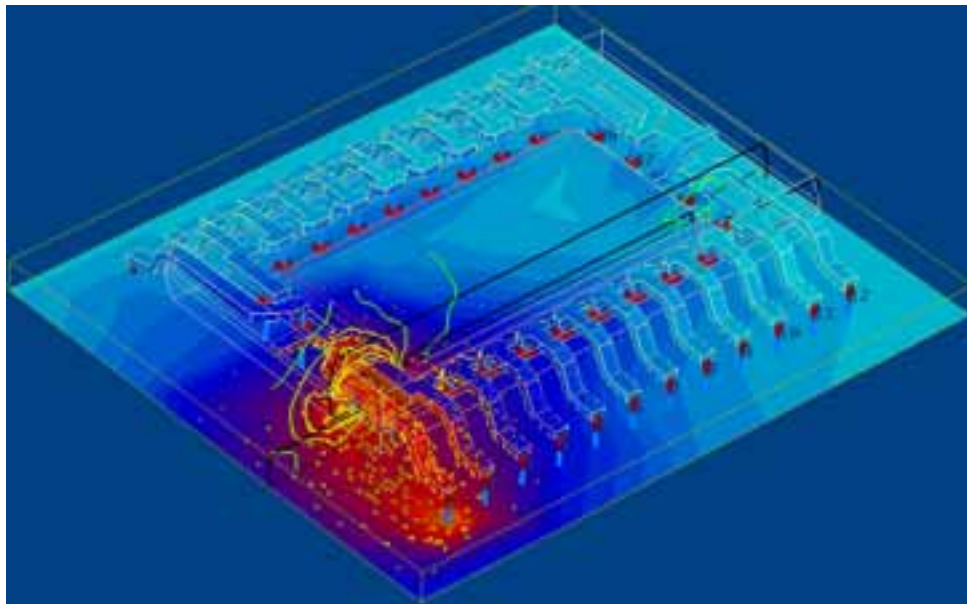


Static extraction

- Based on quasistatic fields
- Computes SPICE network from L,C
- Does not contain dynamic effects

Dynamic extraction

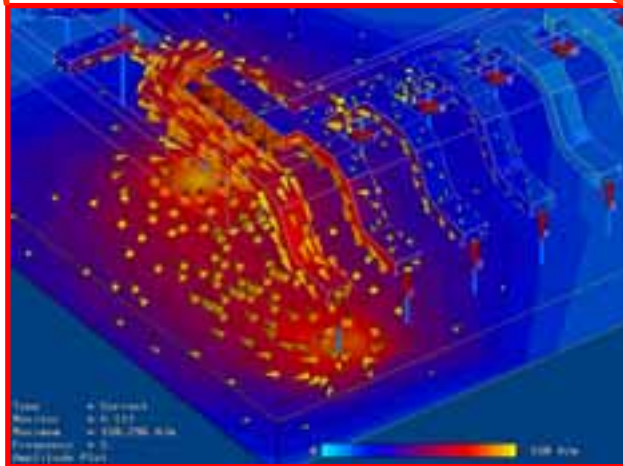
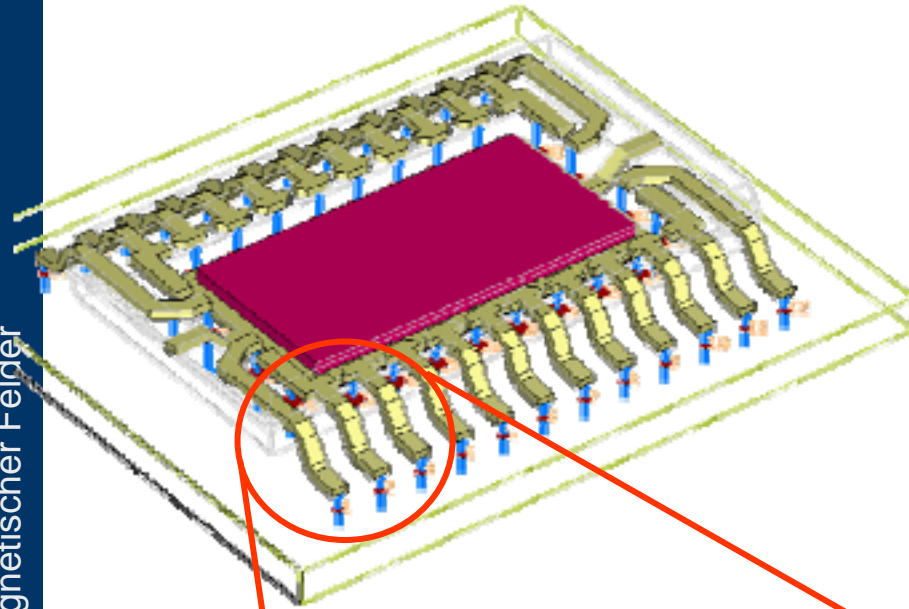
- Based on dynamic EM fields
- Computes SPICE network from S-parameters
- Allows cascaded networks



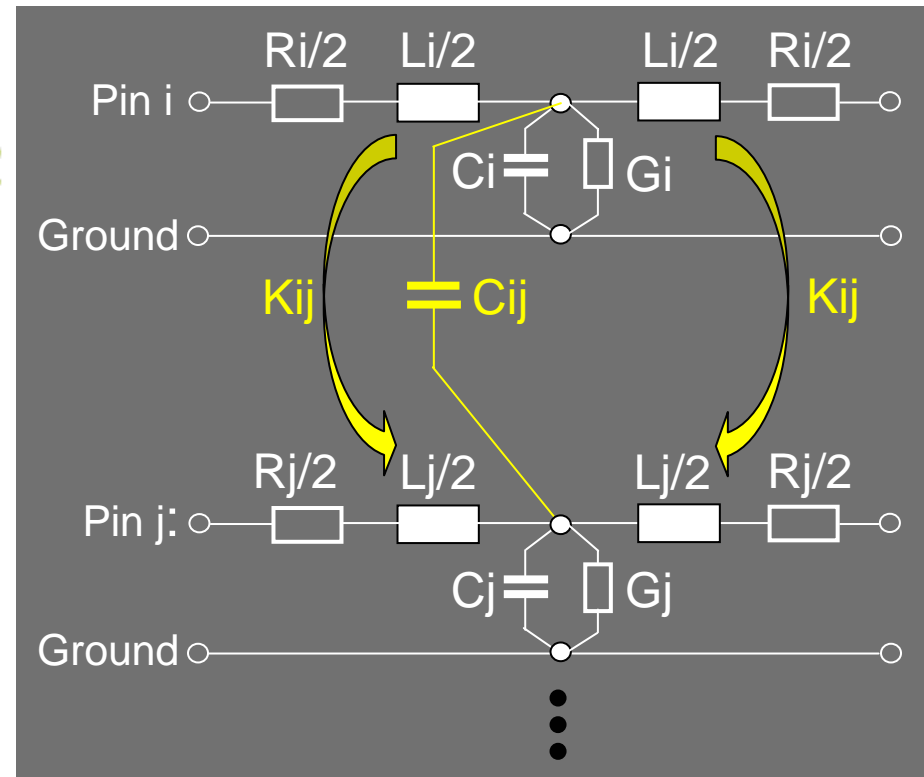
Full EM-SPICE



SPICE Model 1



Fixed topology, R,L,C,G elements



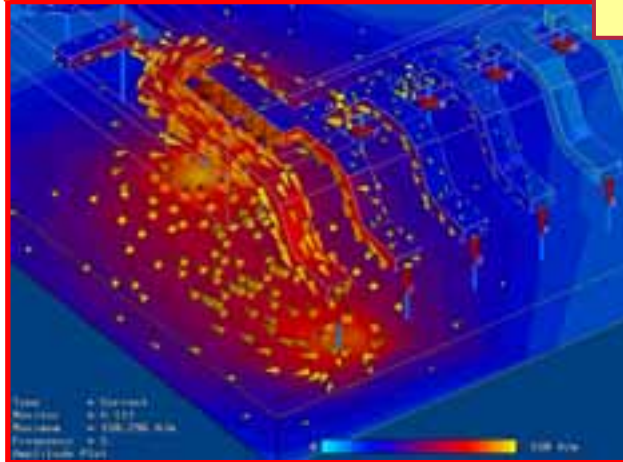
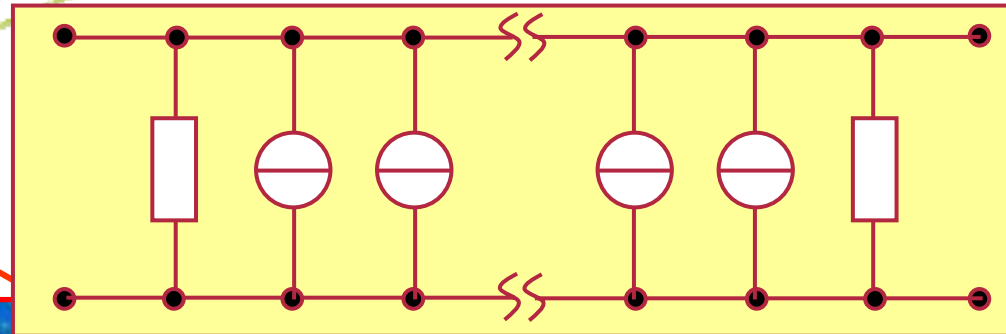
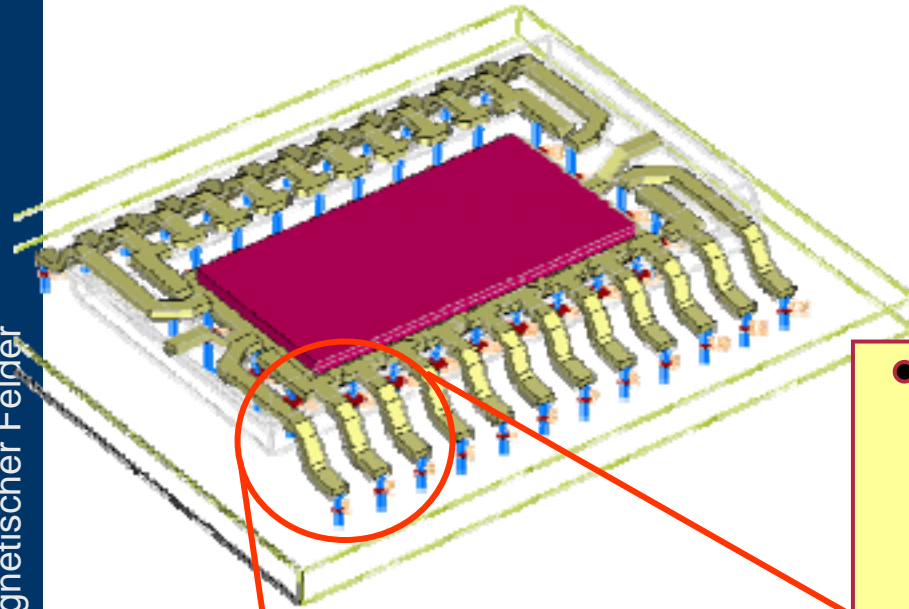
Cascaded SPICE models needed to fit for larger frequency bands !



SPICE Model 2: Extraction



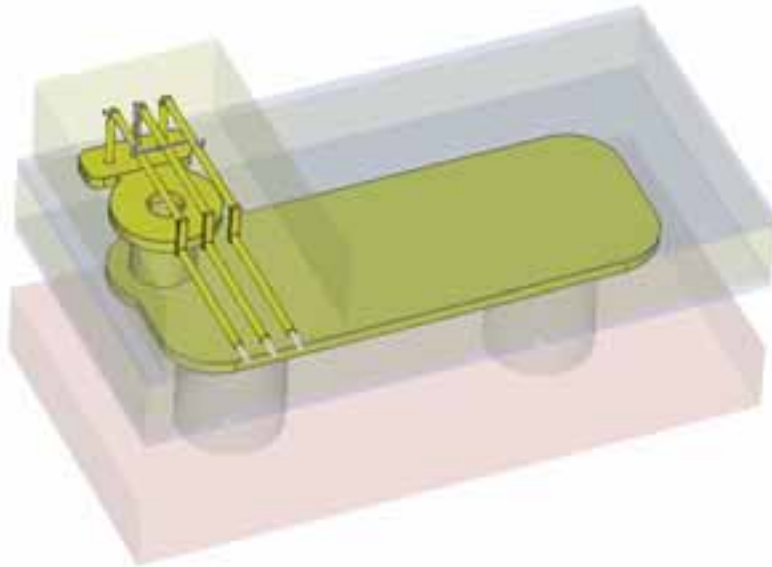
Flexible topology, R,L,C,G elements
+ controlled sources



Fits naturally large frequency bands
Model should be stable and **passive** !



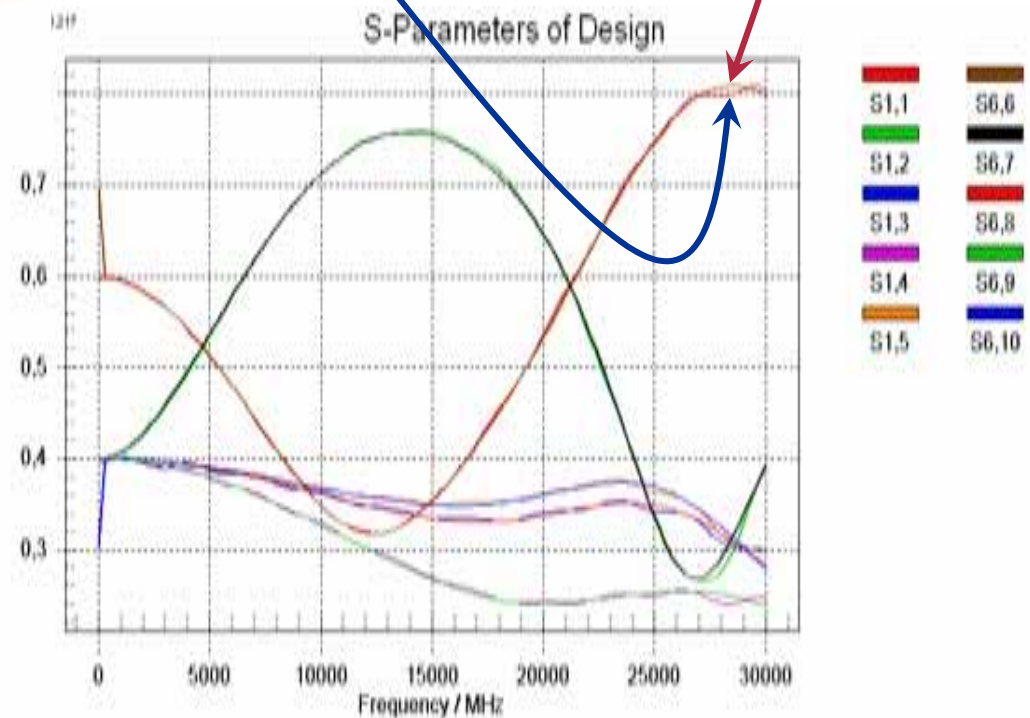
Automatically Generated Netlist



Section of BGA integrated circuit package

Full-wave

Extracted network model



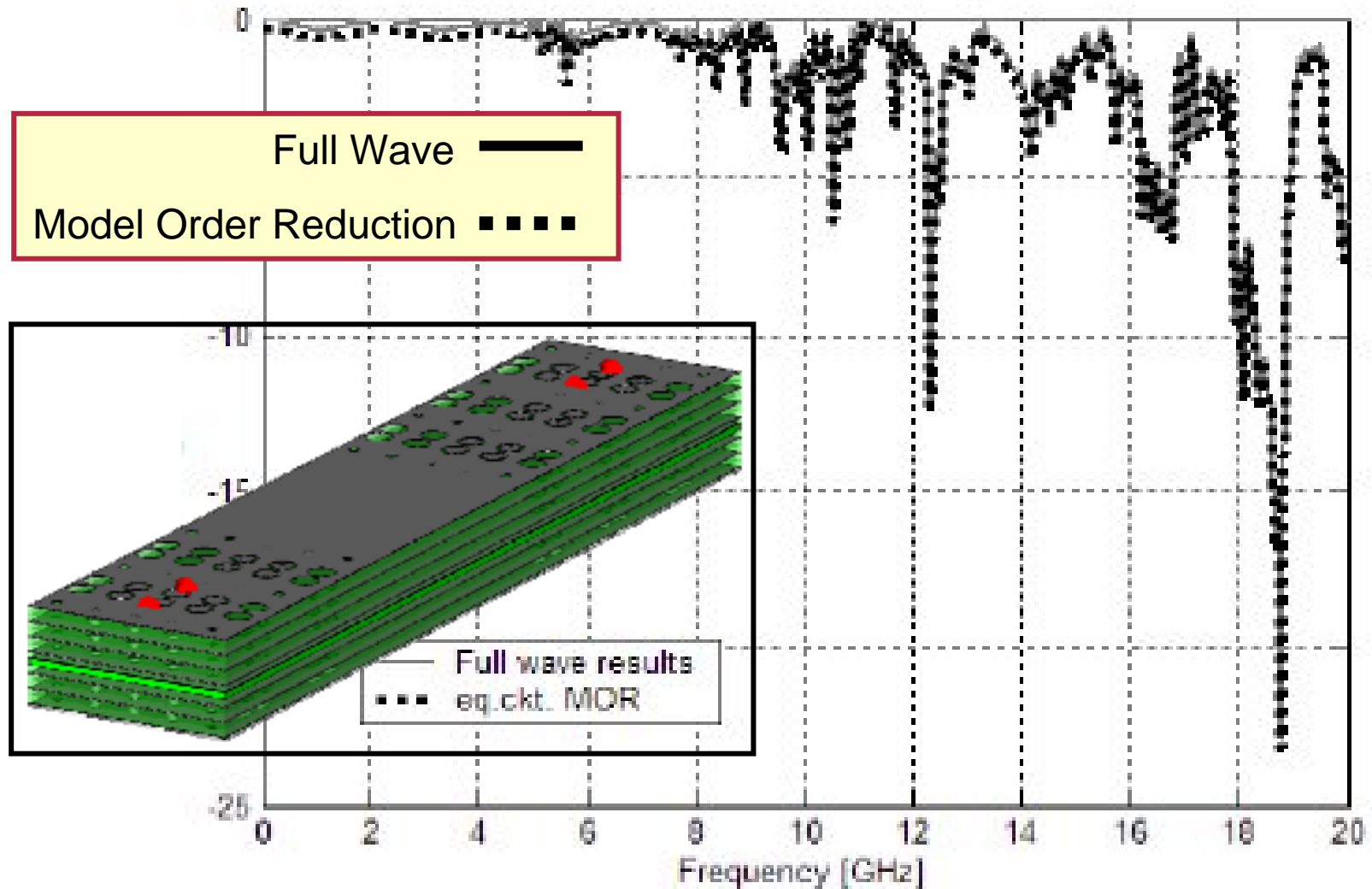
- 5 Port structure (discrete)
- Port impedance: 50 Ohm



SPICE Model Accuracy



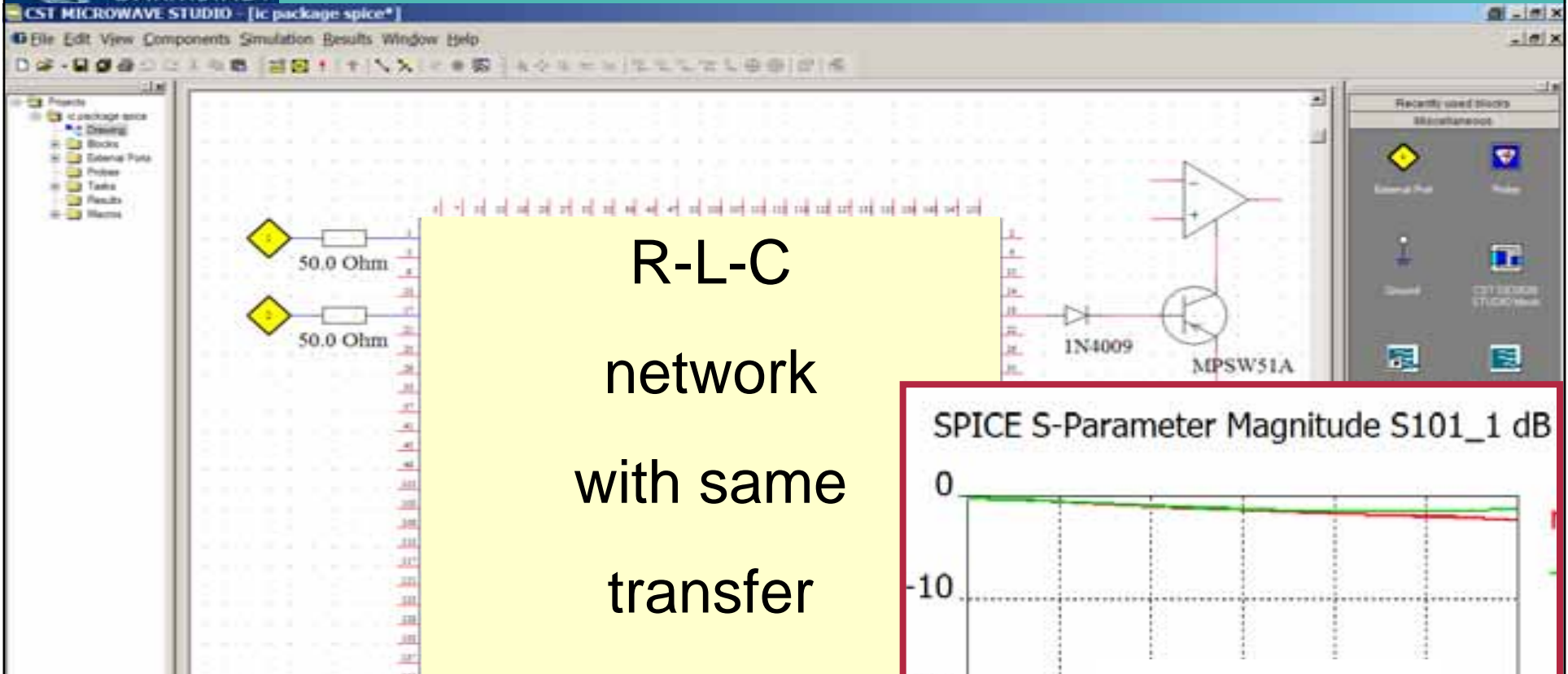
S21 of MWS simulation and extracted model



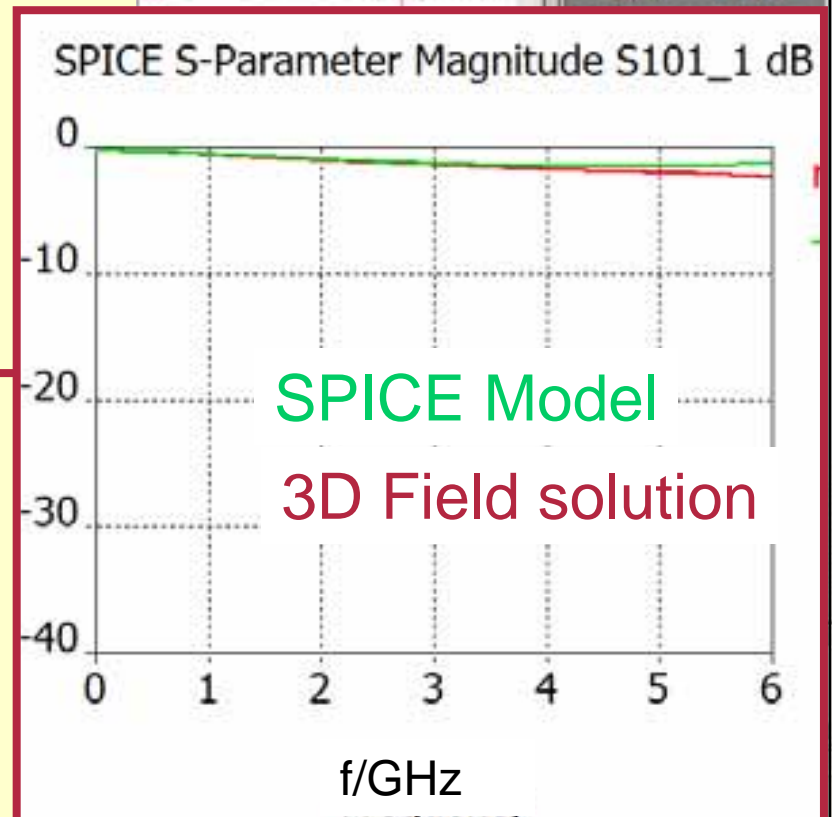


Cross Talk on Micro Chips

The screenshot displays the CST MICROWAVE STUDIO interface. The central workspace shows a 3D model of a microchip on a yellow substrate with a green die. The chip is connected to a circuit with two 50.0 Ohm resistors, a 1N4009 diode, and an MPSW51A transistor. The software interface includes a menu bar (File, Edit, View, Components, Simulation, Results, Window, Help), a toolbar, a project tree on the left, and a component library on the right. The bottom status bar shows units (mm, GHz, ps, °C, V, A, Ohm, S, pF, nH) and the time 09:19.



Network parameter
extraction for a 152x152
S-parameter matrix is
still a challenge for many extractors !

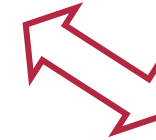
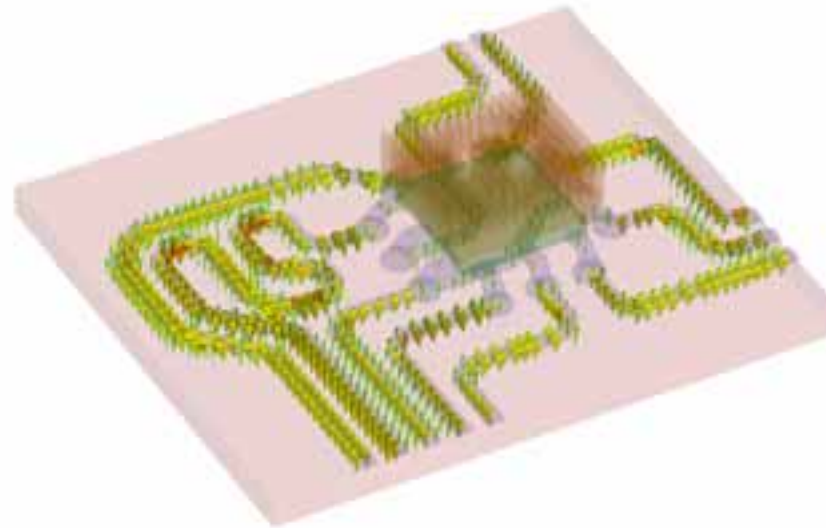




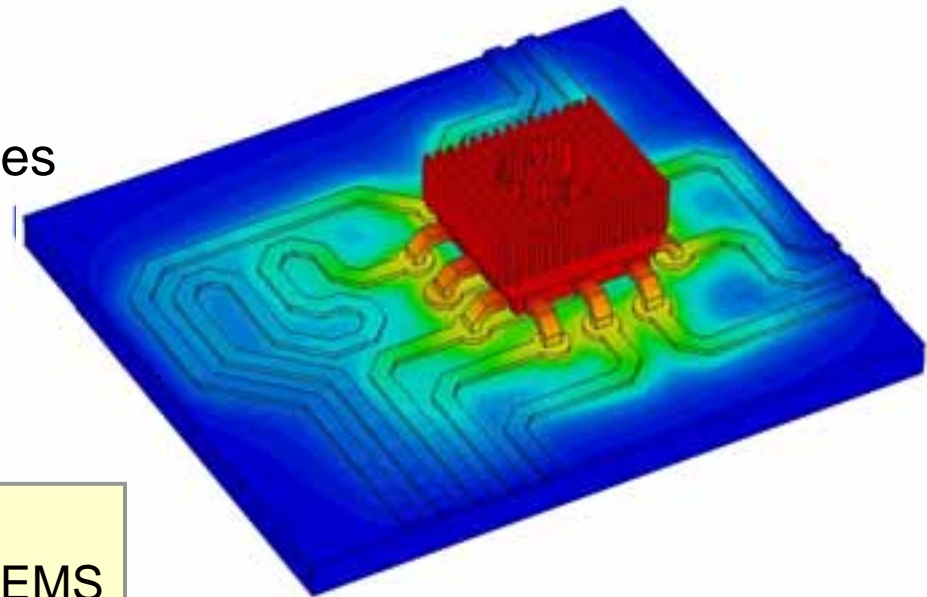
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 - Geometrically complex problems
 - EMC, Signal and Power integrity
 - Network Extraction, Passivity
 - **Coupled problems**
 - Integrated flows
- Conclusions



HF- Thermal Solver Coupling



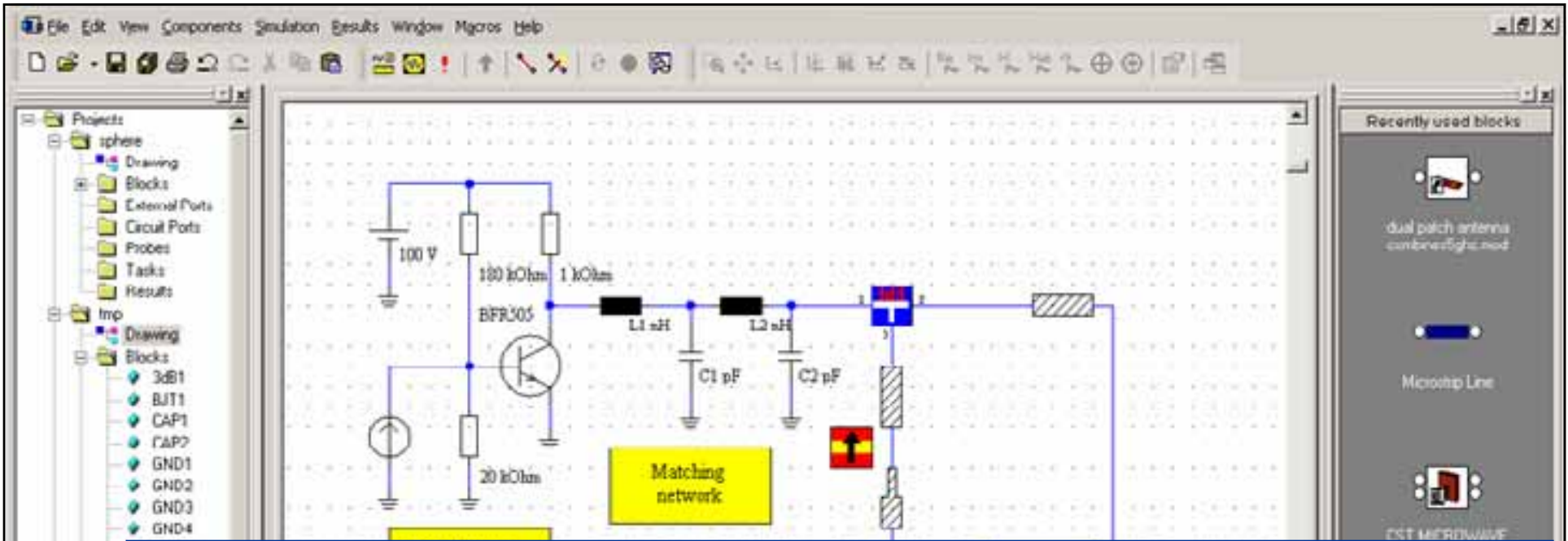
Thermal Analysis of electric losses



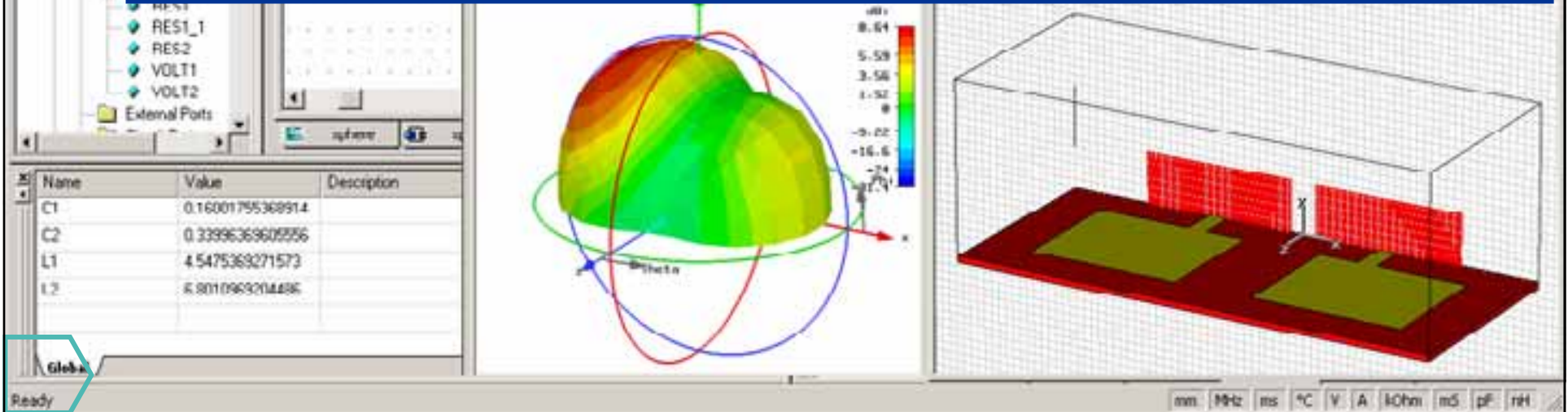
1. Currents: CST MWS
2. Temperature Analysis: CST EMS



- Introduction
- State of the art
 - Three steps in solving an EM Problem
 - Finite Integration Technique as universal method
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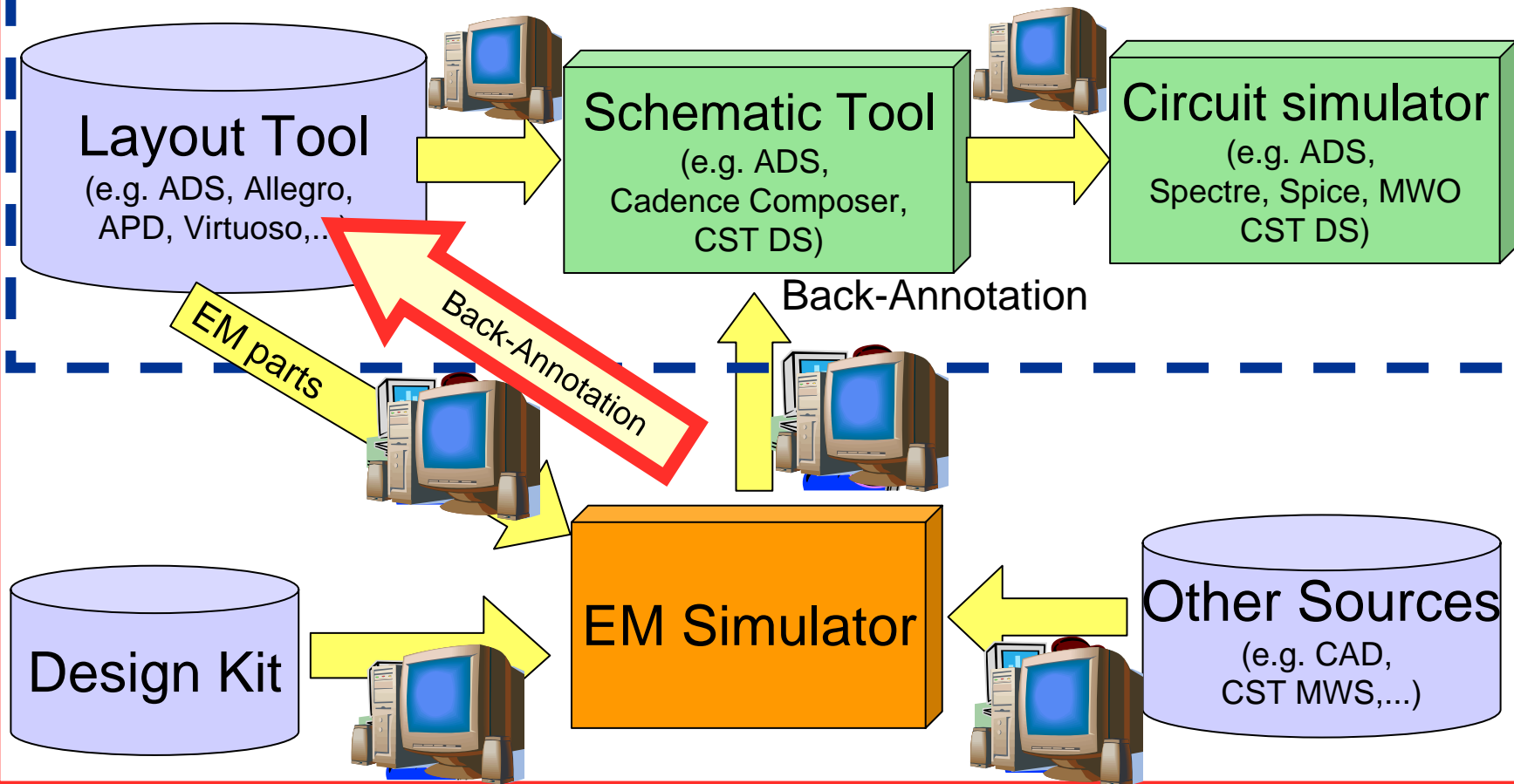


Full integration from one hand is already available
 How about 3D integration into standard flows?





Present



Future

